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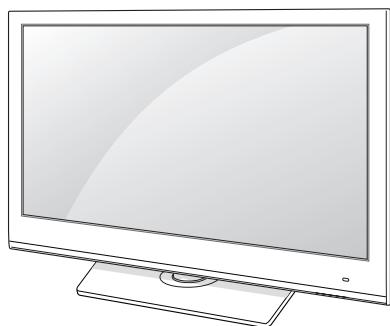
# LCD TV SERVICE MANUAL

CHASSIS : LA01U

MODEL : 47LK520      47LK520-UA

## CAUTION

BEFORE SERVICING THE CHASSIS,  
READ THE SAFETY PRECAUTIONS IN THIS MANUAL.



P/NO : MFL67021017 (1101-REV00)

Printed in Korea

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# SAFETY PRECAUTIONS

## IMPORTANT SAFETY NOTICE

Many electrical and mechanical parts in this chassis have special safety-related characteristics. These parts are identified by  in the Schematic Diagram and Exploded View.

It is essential that these special safety parts should be replaced with the same components as recommended in this manual to prevent Shock, Fire, or other Hazards.

Do not modify the original design without permission of manufacturer.

### General Guidance

An **isolation Transformer** should always be used during the servicing of a receiver whose chassis is not isolated from the AC power line. Use a transformer of adequate power rating as this protects the technician from accidents resulting in personal injury from electrical shocks.

It will also protect the receiver and its components from being damaged by accidental shorts of the circuitry that may be inadvertently introduced during the service operation.

If any fuse (or Fusible Resistor) in this TV receiver is blown, replace it with the specified.

When replacing a high wattage resistor (Oxide Metal Film Resistor, over 1W), keep the resistor 10mm away from PCB.

Keep wires away from high voltage or high temperature parts.

### Before returning the receiver to the customer,

always perform an **AC leakage current check** on the exposed metallic parts of the cabinet, such as antennas, terminals, etc., to be sure the set is safe to operate without damage of electrical shock.

### Leakage Current Cold Check(Antenna Cold Check)

With the instrument AC plug removed from AC source, connect an electrical jumper across the two AC plug prongs. Place the AC switch in the on position, connect one lead of ohm-meter to the AC plug prongs tied together and touch other ohm-meter lead in turn to each exposed metallic parts such as antenna terminals, phone jacks, etc.

If the exposed metallic part has a return path to the chassis, the measured resistance should be between  $1M\Omega$  and  $5.2M\Omega$ .

When the exposed metal has no return path to the chassis the reading must be infinite.

An other abnormality exists that must be corrected before the receiver is returned to the customer.

### Leakage Current Hot Check (See below Figure)

Plug the AC cord directly into the AC outlet.

#### **Do not use a line Isolation Transformer during this check.**

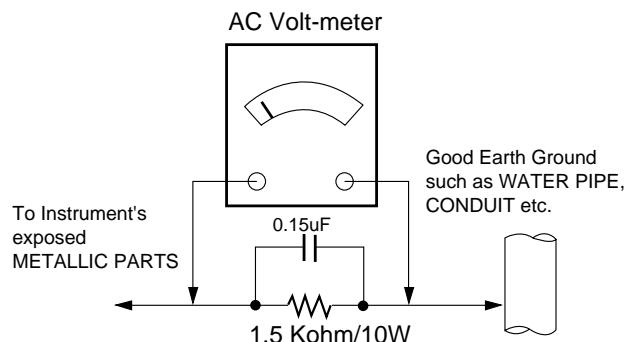
Connect 1.5K/10watt resistor in parallel with a 0.15uF capacitor between a known good earth ground (Water Pipe, Conduit, etc.) and the exposed metallic parts.

Measure the AC voltage across the resistor using AC voltmeter with 1000 ohms/volt or more sensitivity.

Reverse plug the AC cord into the AC outlet and repeat AC voltage measurements for each exposed metallic part. Any voltage measured must not exceed 0.75 volt RMS which corresponds to 0.5mA.

In case any measurement is out of the limits specified, there is possibility of shock hazard and the set must be checked and repaired before it is returned to the customer.

### Leakage Current Hot Check circuit



# SERVICING PRECAUTIONS

**CAUTION:** Before servicing receivers covered by this service manual and its supplements and addenda, read and follow the *SAFETY PRECAUTIONS* on page 3 of this publication.

**NOTE:** If unforeseen circumstances create conflict between the following servicing precautions and any of the safety precautions on page 3 of this publication, always follow the safety precautions. Remember: Safety First.

## General Servicing Precautions

1. Always unplug the receiver AC power cord from the AC power source before;
  - a. Removing or reinstalling any component, circuit board module or any other receiver assembly.
  - b. Disconnecting or reconnecting any receiver electrical plug or other electrical connection.
  - c. Connecting a test substitute in parallel with an electrolytic capacitor in the receiver.
- CAUTION:** A wrong part substitution or incorrect polarity installation of electrolytic capacitors may result in an explosion hazard.
2. Test high voltage only by measuring it with an appropriate high voltage meter or other voltage measuring device (DVM, FETVOM, etc) equipped with a suitable high voltage probe.  
Do not test high voltage by "drawing an arc".
3. Do not spray chemicals on or near this receiver or any of its assemblies.
4. Unless specified otherwise in this service manual, clean electrical contacts only by applying the following mixture to the contacts with a pipe cleaner, cotton-tipped stick or comparable non-abrasive applicator; 10% (by volume) Acetone and 90% (by volume) isopropyl alcohol (90%-99% strength)  
**CAUTION:** This is a flammable mixture.  
Unless specified otherwise in this service manual, lubrication of contacts is not required.
5. Do not defeat any plug/socket B+ voltage interlocks with which receivers covered by this service manual might be equipped.
6. Do not apply AC power to this instrument and/or any of its electrical assemblies unless all solid-state device heat sinks are correctly installed.
7. Always connect the test receiver ground lead to the receiver chassis ground before connecting the test receiver positive lead.  
Always remove the test receiver ground lead last.
8. *Use with this receiver only the test fixtures specified in this service manual.*  
**CAUTION:** Do not connect the test fixture ground strap to any heat sink in this receiver.

## Electrostatically Sensitive (ES) Devices

Some semiconductor (solid-state) devices can be damaged easily by static electricity. Such components commonly are called *Electrostatically Sensitive (ES) Devices*. Examples of typical ES devices are integrated circuits and some field-effect transistors and semiconductor "chip" components. The following techniques should be used to help reduce the incidence of component damage caused by static by static electricity.

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed to prevent potential shock reasons prior to applying power to the

unit under test.

2. After removing an electrical assembly equipped with ES devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ES devices.
4. Use only an anti-static type solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ES devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ES devices.
6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive material).
7. Immediately before removing the protective material from the leads of a replacement ES device, touch the protective material to the chassis or circuit assembly into which the device will be installed.  
**CAUTION:** Be sure no power is applied to the chassis or circuit, and observe all other safety precautions.
8. Minimize bodily motions when handling unpackaged replacement ES devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ES device.)

## General Soldering Guidelines

1. Use a grounded-tip, low-wattage soldering iron and appropriate tip size and shape that will maintain tip temperature within the range of 500°F to 600°F.
2. Use an appropriate gauge of RMA resin-core solder composed of 60 parts tin/40 parts lead.
3. Keep the soldering iron tip clean and well tinned.
4. Thoroughly clean the surfaces to be soldered. Use a small wire-bristle (0.5 inch, or 1.25cm) brush with a metal handle.  
Do not use freon-propelled spray-on cleaners.
5. Use the following unsoldering technique
  - a. Allow the soldering iron tip to reach normal temperature. (500°F to 600°F)
  - b. Heat the component lead until the solder melts.
  - c. Quickly draw the melted solder with an anti-static, suction-type solder removal device or with solder braid.  
**CAUTION:** Work quickly to avoid overheating the circuit board printed foil.
6. Use the following soldering technique.
  - a. Allow the soldering iron tip to reach a normal temperature (500°F to 600°F)
  - b. First, hold the soldering iron tip and solder the strand against the component lead until the solder melts.
  - c. Quickly move the soldering iron tip to the junction of the component lead and the printed circuit foil, and hold it there only until the solder flows onto and around both the component lead and the foil.  
**CAUTION:** Work quickly to avoid overheating the circuit board printed foil.
  - d. Closely inspect the solder area and remove any excess or splashed solder with a small wire-bristle brush.

## **IC Remove/Replacement**

Some chassis circuit boards have slotted holes (oblong) through which the IC leads are inserted and then bent flat against the circuit foil. When holes are the slotted type, the following technique should be used to remove and replace the IC. When working with boards using the familiar round hole, use the standard technique as outlined in paragraphs 5 and 6 above.

### *Removal*

1. Desolder and straighten each IC lead in one operation by gently prying up on the lead with the soldering iron tip as the solder melts.
2. Draw away the melted solder with an anti-static suction-type solder removal device (or with solder braid) before removing the IC.

### *Replacement*

1. Carefully insert the replacement IC in the circuit board.
2. Carefully bend each IC lead against the circuit foil pad and solder it.
3. Clean the soldered areas with a small wire-bristle brush. (It is not necessary to reapply acrylic coating to the areas).

## **"Small-Signal" Discrete Transistor**

### **Removal/Replacement**

1. Remove the defective transistor by clipping its leads as close as possible to the component body.
2. Bend into a "U" shape the end of each of three leads remaining on the circuit board.
3. Bend into a "U" shape the replacement transistor leads.
4. Connect the replacement transistor leads to the corresponding leads extending from the circuit board and crimp the "U" with long nose pliers to insure metal to metal contact then solder each connection.

## **Power Output, Transistor Device**

### **Removal/Replacement**

1. Heat and remove all solder from around the transistor leads.
2. Remove the heat sink mounting screw (if so equipped).
3. Carefully remove the transistor from the heat sink of the circuit board.
4. Insert new transistor in the circuit board.
5. Solder each transistor lead, and clip off excess lead.
6. Replace heat sink.

### **Diode Removal/Replacement**

1. Remove defective diode by clipping its leads as close as possible to diode body.
2. Bend the two remaining leads perpendicular y to the circuit board.
3. Observing diode polarity, wrap each lead of the new diode around the corresponding lead on the circuit board.
4. Securely crimp each connection and solder it.
5. Inspect (on the circuit board copper side) the solder joints of the two "original" leads. If they are not shiny, reheat them and if necessary, apply additional solder.

### **Fuse and Conventional Resistor**

### **Removal/Replacement**

1. Clip each fuse or resistor lead at top of the circuit board hollow stake.
2. Securely crimp the leads of replacement component around notch at stake top.
3. Solder the connections.

**CAUTION:** Maintain original spacing between the replaced component and adjacent components and the circuit board to prevent excessive component temperatures.

## **Circuit Board Foil Repair**

Excessive heat applied to the copper foil of any printed circuit board will weaken the adhesive that bonds the foil to the circuit board causing the foil to separate from or "lift-off" the board. The following guidelines and procedures should be followed whenever this condition is encountered.

### *At IC Connections*

To repair a defective copper pattern at IC connections use the following procedure to install a jumper wire on the copper pattern side of the circuit board. (Use this technique only on IC connections).

1. Carefully remove the damaged copper pattern with a sharp knife. (Remove only as much copper as absolutely necessary).
2. carefully scratch away the solder resist and acrylic coating (if used) from the end of the remaining copper pattern.
3. Bend a small "U" in one end of a small gauge jumper wire and carefully crimp it around the IC pin. Solder the IC connection.
4. Route the jumper wire along the path of the out-away copper pattern and let it overlap the previously scraped end of the good copper pattern. Solder the overlapped area and clip off any excess jumper wire.

### *At Other Connections*

Use the following technique to repair the defective copper pattern at connections other than IC Pins. This technique involves the installation of a jumper wire on the component side of the circuit board.

1. Remove the defective copper pattern with a sharp knife. Remove at least 1/4 inch of copper, to ensure that a hazardous condition will not exist if the jumper wire opens.
2. Trace along the copper pattern from both sides of the pattern break and locate the nearest component that is directly connected to the affected copper pattern.
3. Connect insulated 20-gauge jumper wire from the lead of the nearest component on one side of the pattern break to the lead of the nearest component on the other side.  
Carefully crimp and solder the connections.

**CAUTION:** Be sure the insulated jumper wire is dressed so the it does not touch components or sharp edges.

# SPECIFICATION

NOTE : Specifications and others are subject to change without notice for improvement.

## 1. Application range

This spec sheet is applied LCD TV with 32", 37", 42", 47", 55" LA01U chassis.

## 2. Requirement for Test

Each part is tested as below without special appointment.

- 1) Temperature: 25 °C ± 5 °C
- 2) Relative Humidity: 65 ± 10 %
- 3) Power Voltage : Standard input voltage(100-240V~, 50/60Hz)  
\* Standard Voltage of each product is marked by models
- 4) Specification and performance of each parts are followed each drawing and specification by part number in accordance with BOM.
- 5) The receiver must be operated for about 5 minutes prior to the adjustment.

## 3. Test method

- 1) Performance: LGE TV test method followed
- 2) Demanded other specification
  - Safety : UL, CSA, IEC specification
  - EMC: FCC, ICES, IEC specification

## 4. General Specification(TV)

No	Item	Specification		Remark
1	Receivable System	1) ATSC / NTSC-M		
2	Available Channel	1) VHF : 02 ~ 13 2) UHF : 14 ~ 69 3) DTV : 02 ~ 69 4) CATV : 01 ~ 135 5) CADTV : 01 ~ 135		
3	Input Voltage	1) AC 100 - 240V~ 50/60Hz		Mark : 110V, 60Hz (N.America)
4	Market	North America		
5	Screen Size	42 inch Wide(1920x1080)	FHD + 120Hz	42LK520-UA
		47 inch Wide(1920x1080)	FHD + 120Hz	47LK520-UA
		55 inch Wide(1920x1080)	FHD + 120Hz	55LK520-UA
6	Aspect Ratio	16:9		
7	Tuning System	FS		
8	LCD Module	LC420WUF-SCA2	LGD	42LK520-UA
		LC470WUF-SCA2	LGD	47LK520-UA
		LC550WUD-SCA2	LGD	55LK520-UA
9	Operating Environment	Temp : 0 ~ 40 deg Humidity : ~ 80 %		
10	Storage Environment	Temp : -20 ~ 60 deg Humidity : -85 %		

## 5. Chrominance & Luminance

No.	Item			Min	Typ	Max	Unit	Remarks
1	Max Luminance (Center 1-point / Full White Pattern)			360	500		cd/m <sup>2</sup>	
2	Luminance uniformity							
3	Color coordinate (Default)	RED	X	Typ. -0.03	0.636	Typ. +0.03	42LK520-UA(LGD)	
			Y		0.335			
		GREEN	X		0.291			
			Y		0.603			
		BLUE	X		0.146			
			Y		0.061			
		WHITE	X		0.279			
			Y		0.292			
		RED	X	Typ. -0.03	0.639	Typ. +0.03	47LK520-UA(LGD)	
			Y		0.334			
		GREEN	X		0.290			
			Y		0.606			
		BLUE	X		0.146			
			Y		0.058			
		WHITE	X		0.279			
			Y		0.292			
		RED	X	Typ. -0.03	0.637	Typ. +0.03	55LK520-UA(LGD)	
			Y		0.333			
		GREEN	X		0.287			
			Y		0.605			
		BLUE	X		0.145			
			Y		0.064			
		WHITE	X		0.279			
			Y		0.292			
4	Contrast ratio	Module		1100	1450			47/55LK520-UA(LGD)
				1100	1500			42LK520-UA(LGD)
		DCR		130,000:1	150,000:1			42/47/55LK520-UA(LGD)
6	Color Temperature	Cool		0.254	0.269	0.284	13000K	The W/B Tolerance is ±0.015 for picture quality by DQA
				0.258	0.273	0.288		
		Medium		0.270	0.285	0.300	9300K	
				0.278	0.293	0.308		
		Warm		0.298	0.313	0.324	6500K	
				0.314	0.329	0.344		

## 6. Component Video Input (Y, C<sub>B</sub>/P<sub>B</sub>, C<sub>R</sub>/P<sub>R</sub>)

No	Resolution	H-freq(kHz)	V-freq.(kHz)	Pixel clock	Proposed
1.	720*480	15.73	60	13.5135	SDTV ,DVD 480I
2.	720*480	15.73	59.94	13.5	SDTV ,DVD 480I
3.	720*480	31.50	60	27.027	SDTV 480P
4.	720*480	31.47	59.94	27.0	SDTV 480P
5.	1280*720	45.00	60.00	74.25	HDTV 720P
6.	1280*720	44.96	59.94	74.176	HDTV 720P
7.	1920*1080	33.75	60.00	74.25	HDTV 1080I
8.	1920*1080	33.72	59.94	74.176	HDTV 1080I
9.	1920*1080	67.500	60	148.50	HDTV 1080P
10.	1920*1080	67.432	59.94	148.352	HDTV 1080P
11.	1920*1080	27.000	24.000	74.25	HDTV 1080P
12.	1920*1080	26.97	23.976	74.176	HDTV 1080P
13.	1920*1080	33.75	30.000	74.25	HDTV 1080P
14.	1920*1080	33.71	29.97	740176	HDTV 1080P

## 7. RGB Input (PC)

No	Resolution	H-freq(kHz)	V-freq.(kHz)	Pixel clock	Proposed	
	PC				DDC	
1.	640*350	31.468	70.09	25.17	EGA	X
2.	720*400	31.469	70.08	28.32	DOS	O
3.	640*480	31.469	59.94	25.17	VESA(VGA)	O
4.	800*600	37.879	60.31	40.00	VESA(SVGA)	O
5.	1024*768	48.363	60.00	65.00	VESA(XGA)	O
6.	1280*768	47.776	59.870	79.5	CVT(WXGA)	X
7.	1360*768	47.712	60.015	85.50	VESA(WXGA)	X
8.	1280*1024	63.981	60.020	108.00	VESA(SXGA)	O
9.	1920*1080	66.587	59.934	138.50	WUXGA	O

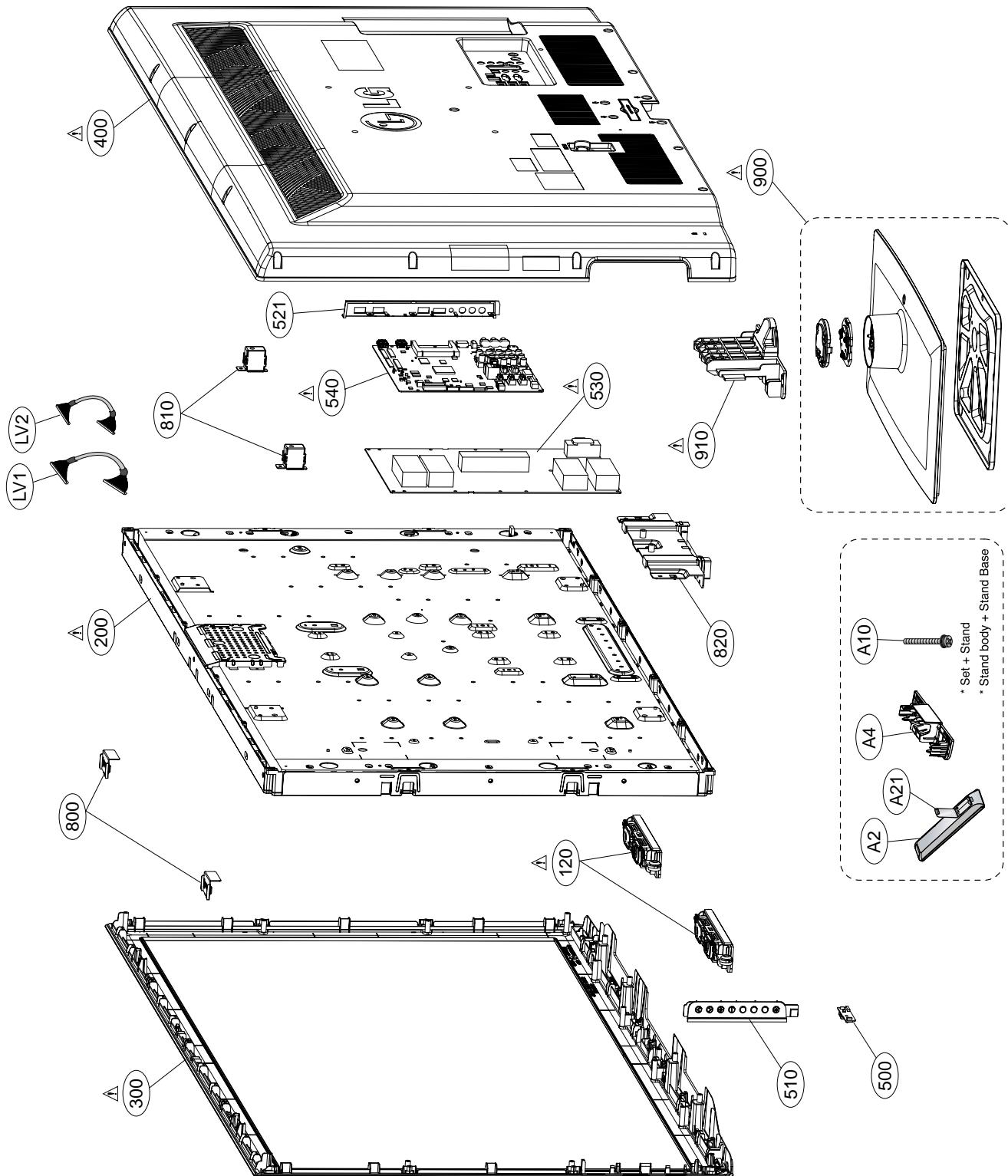
## 8. HDMI input (PC/DTV)

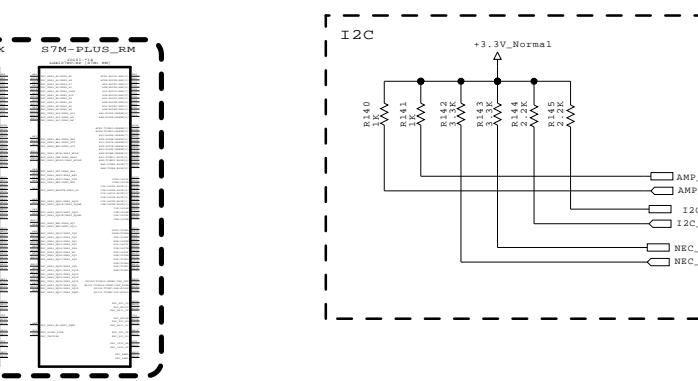
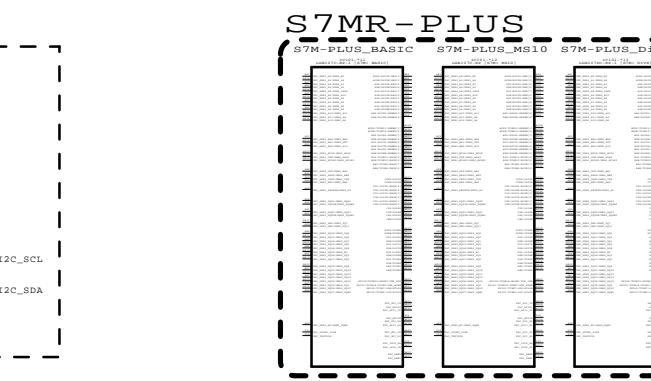
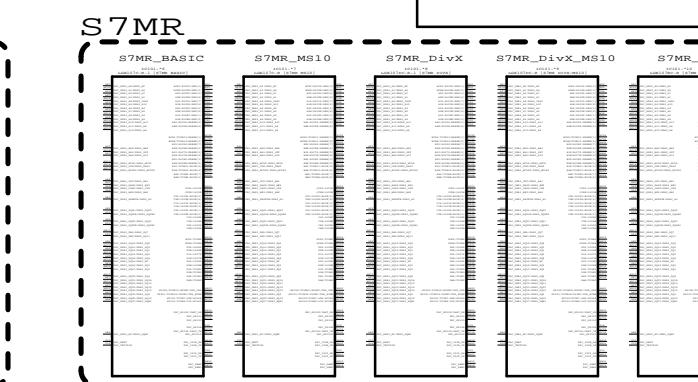
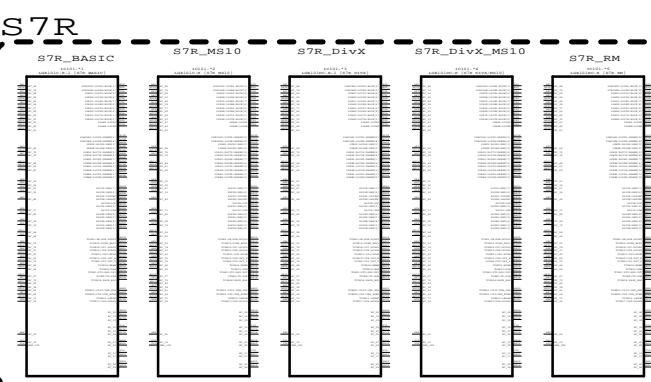
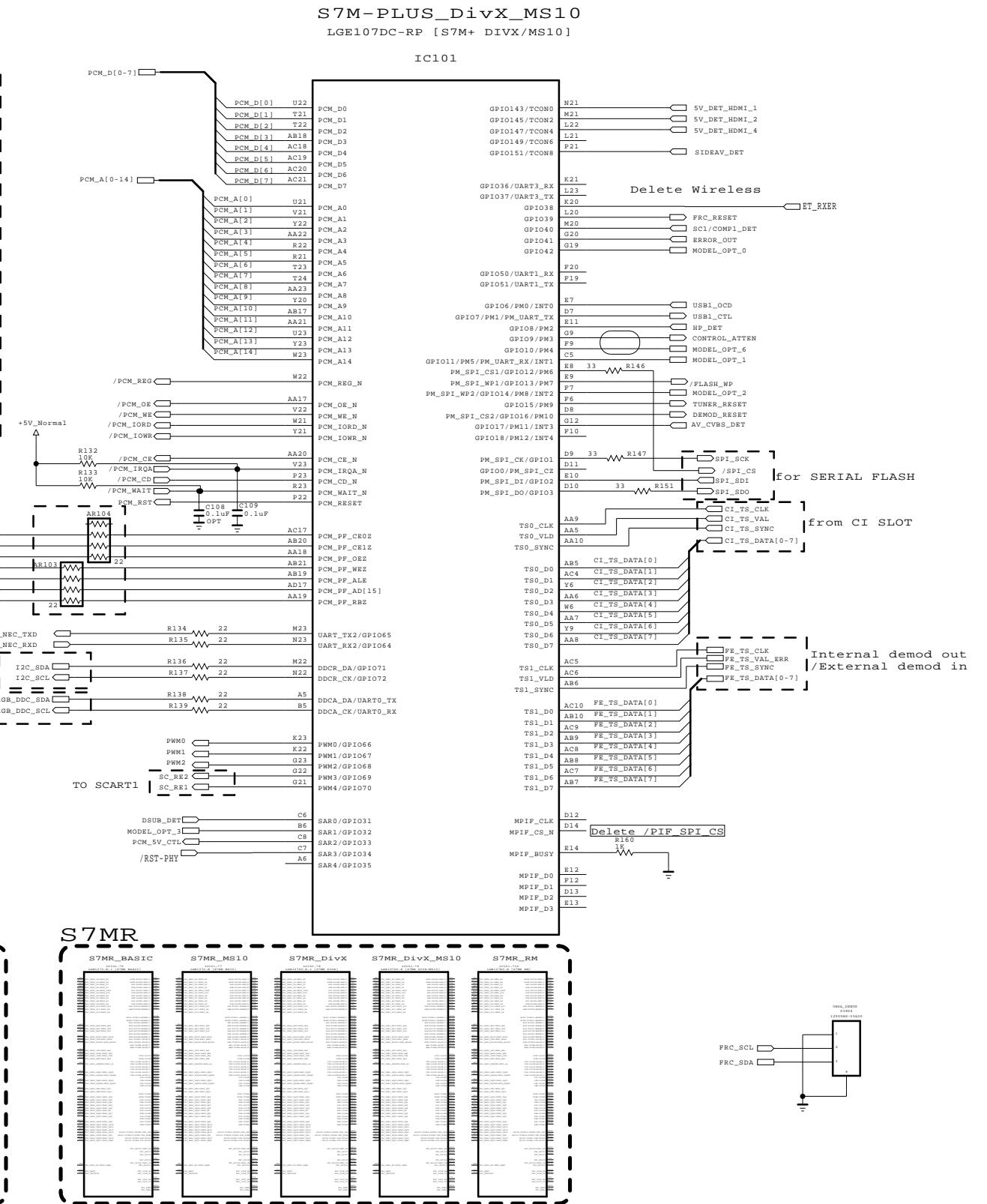
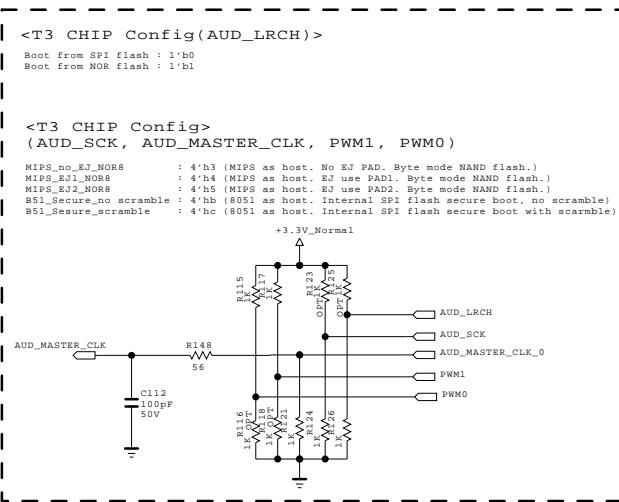
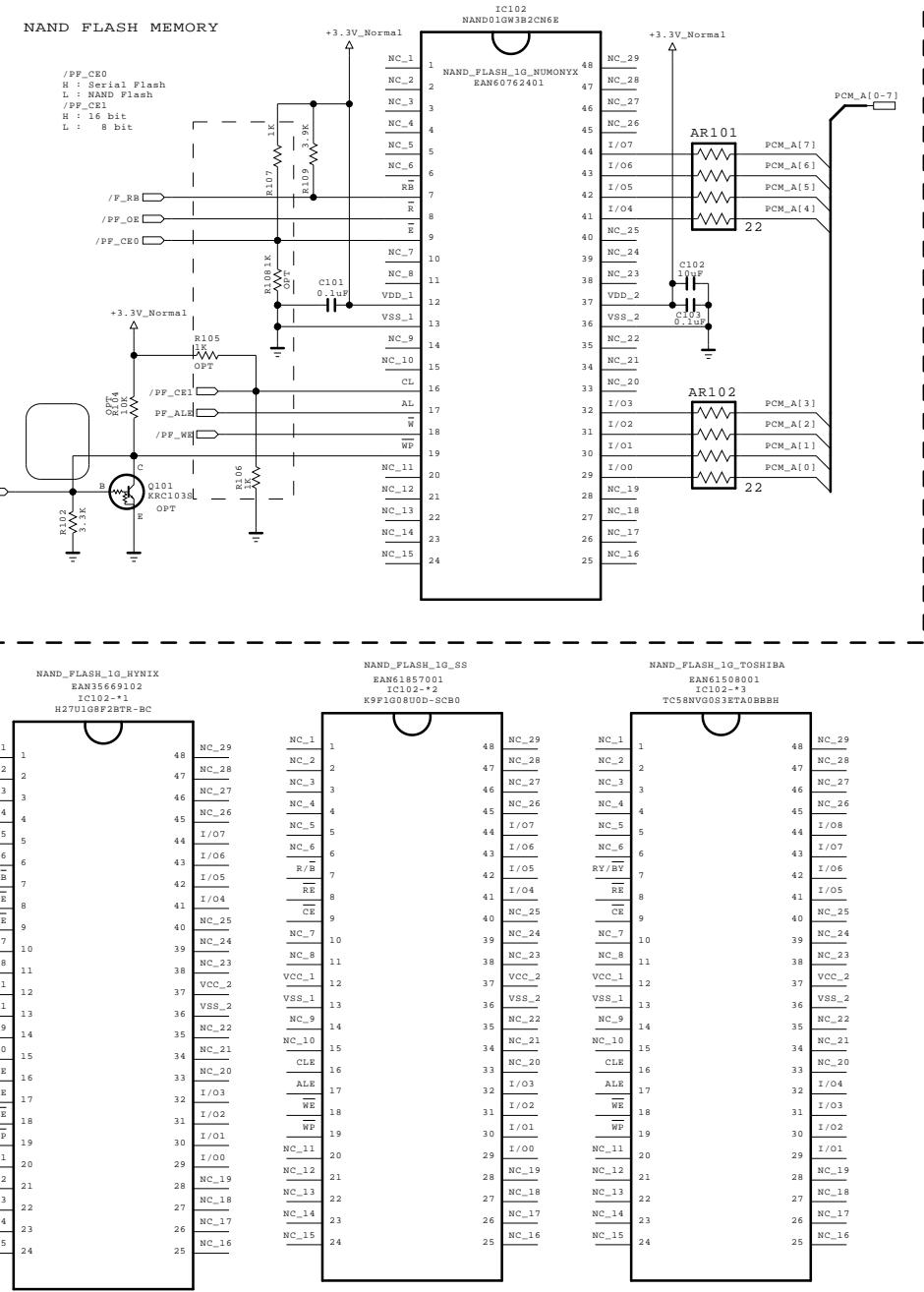
No	Resolution	H-freq(kHz)	V-freq.(kHz)	Pixel clock	Proposed	
	PC					DDC
1.	640*350	31.468	70.09	25.17	EGA	X
2.	720*400	31.469	70.08	28.32	DOS	O
3.	640*480	31.469	59.94	25.17	VESA(VGA)	X
4.	800*600	37.879	60.31	40.00	VESA(SVGA)	O
5.	1024*768	48.363	60.00	65.00	VESA(XGA)	O
6.	1360*768	47.712	60.015	85.50	VESA (WXGA)	O
7.	1280*1024	63.981	60.020	108.00	VESA (SXGA)	O
8.	1920*1080	67.500	60.000	148.50	HDTV 1080P	O
	DTV					
1	720*480	31.47	60	27.027	SDTV 480P	O
2	720*480	31.47	59.94	27.00	SDTV 480P	O
3	1280*720	45.00	60.00	74.25	HDTV 720P	O
4	1280*720	44.96	59.94	74.176	HDTV 720P	O
5	1920*1080	33.75	60.00	74.25	HDTV 1080I	O
6	1920*1080	33.72	59.94	74.176	HDTV 1080I	O
7	1920*1080	67.500	60	148.50	HDTV 1080P	O
8	1920*1080	67.432	59.939	148.352	HDTV 1080P	O
9	1920*1080	27.000	24.000	74.25	HDTV 1080P	O
10	1920*1080	26.97	23.976	74.176	HDTV 1080P	O
11	1920*1080	33.75	30.000	74.25	HDTV 1080P	O
12	1920*1080	33.71	29.97	74.176	HDTV 1080P	O

# EXPLODED VIEW

## IMPORTANT SAFETY NOTICE

Many electrical and mechanical parts in this chassis have special safety-related characteristics. These parts are identified by  $\triangle$  in the Schematic Diagram and EXPLODED VIEW.  
It is essential that these special safety parts should be replaced with the same components as recommended in this manual to prevent X-RADIATION, Shock, Fire, or other Hazards.  
Do not modify the original design without permission of manufacturer.



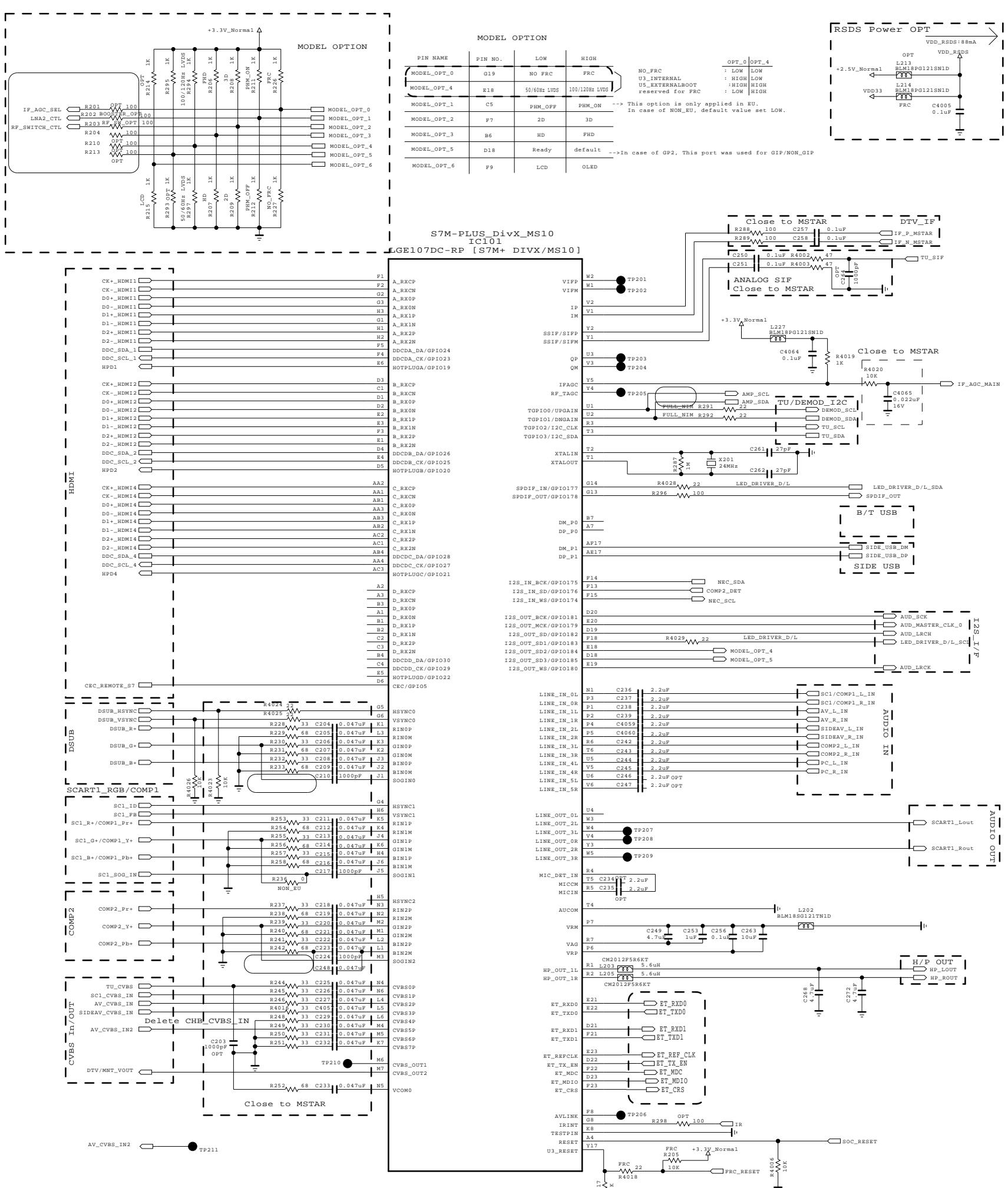


THE  SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION. FIRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IT IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE  SYMBOL MARK OF THE SCHEMATIC.

SECRET

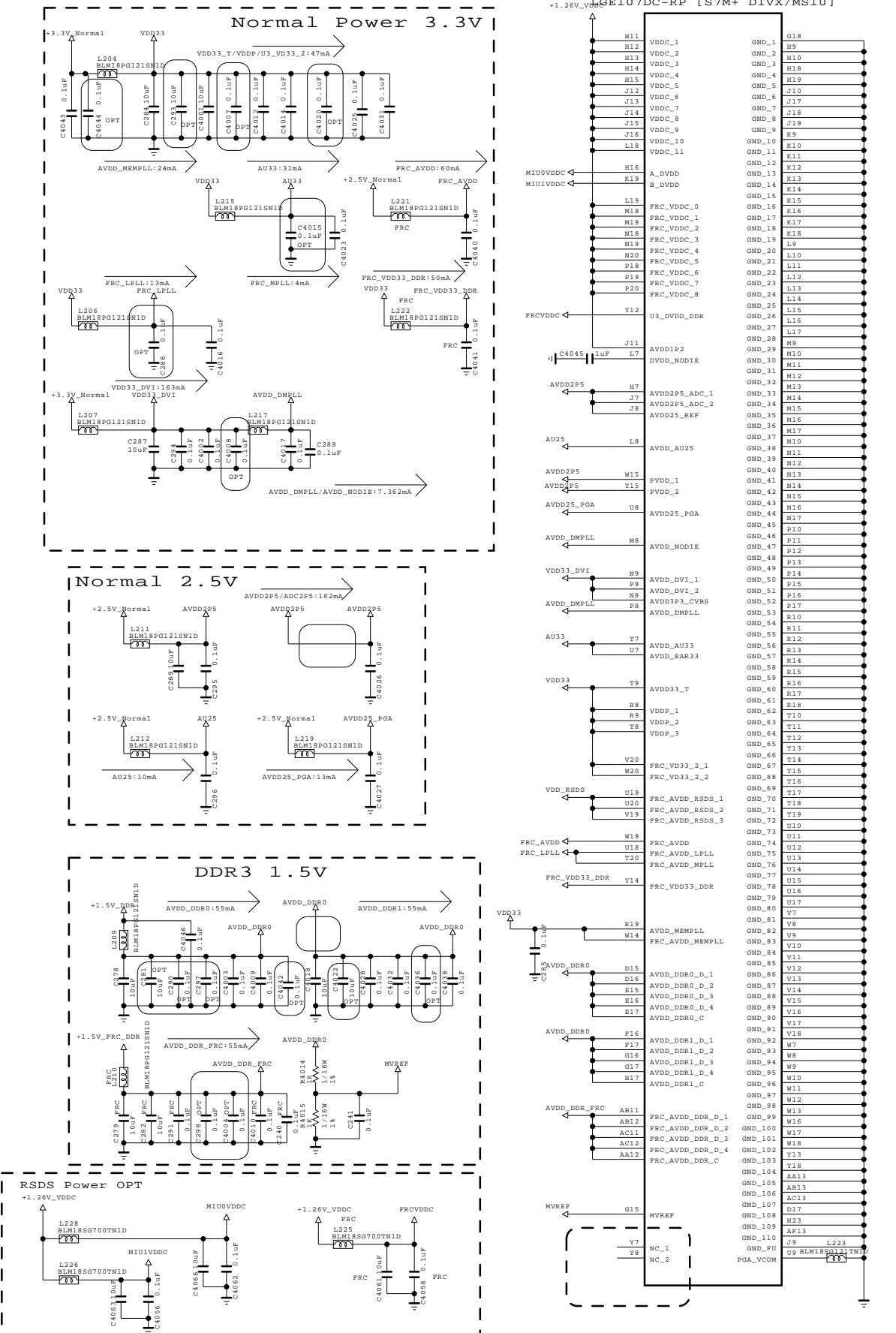
LG ELECTRONICS

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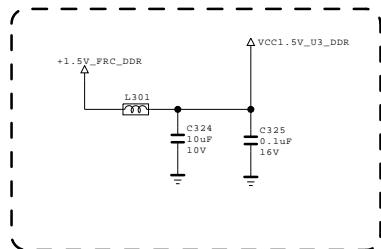
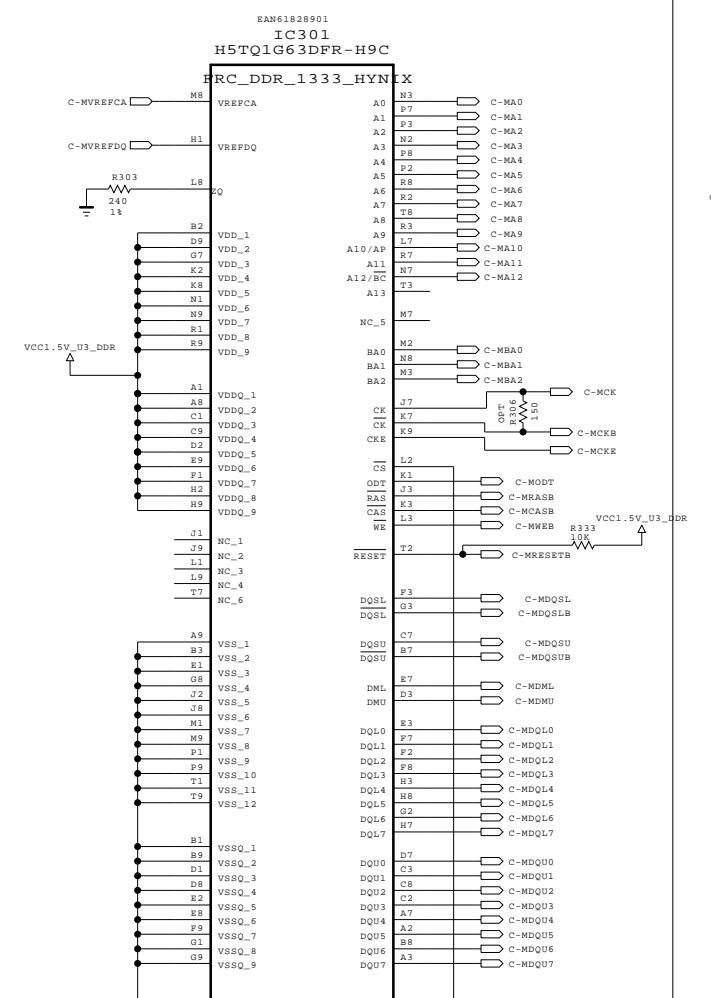
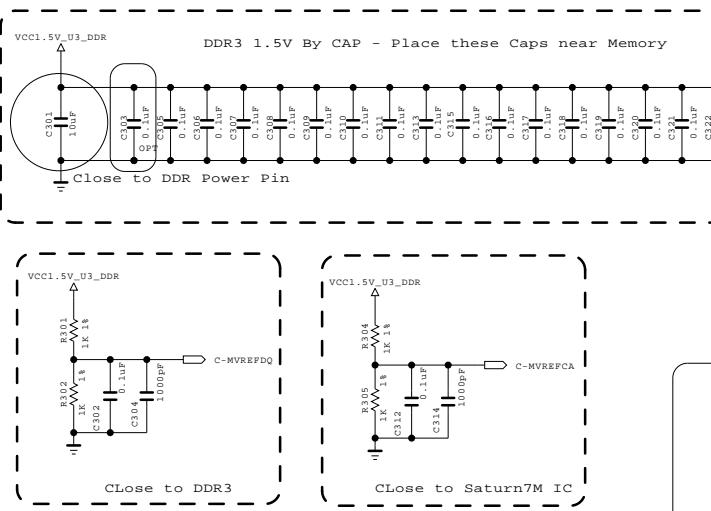


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SECRET

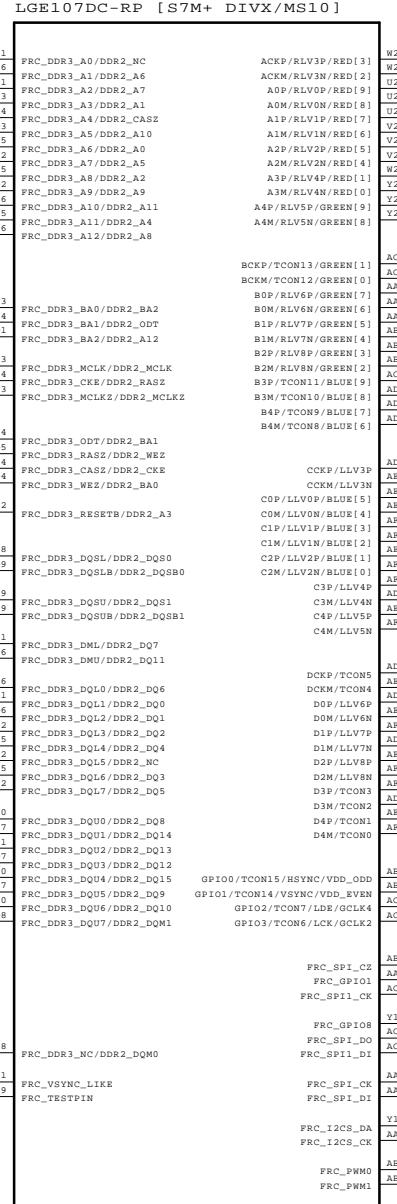


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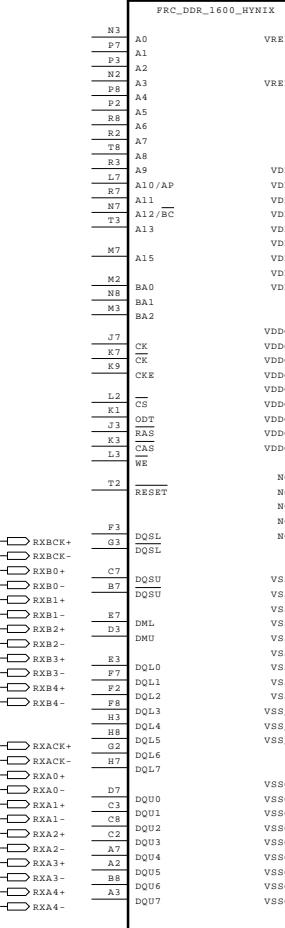


S7M-PLUS\_DivX\_MS10

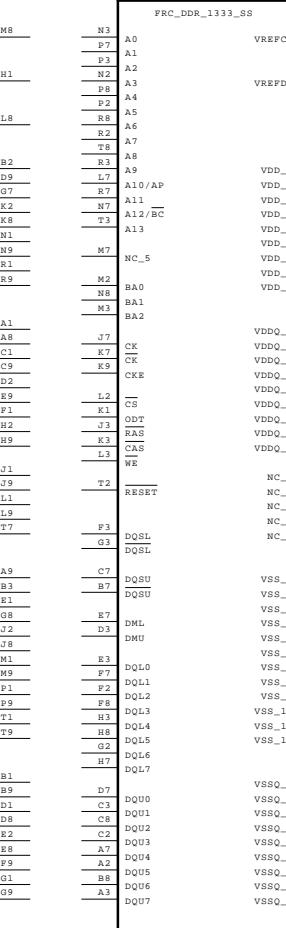
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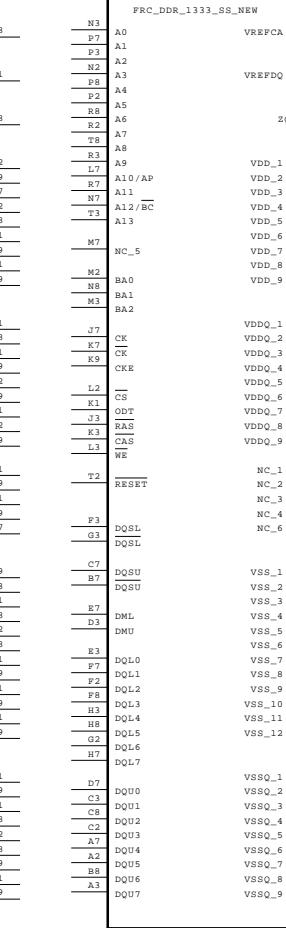
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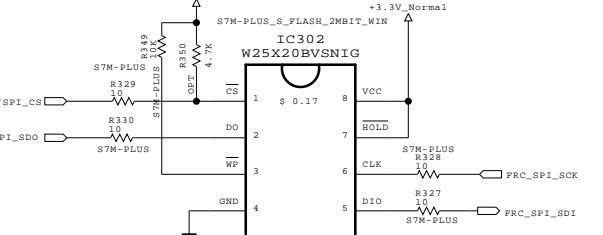
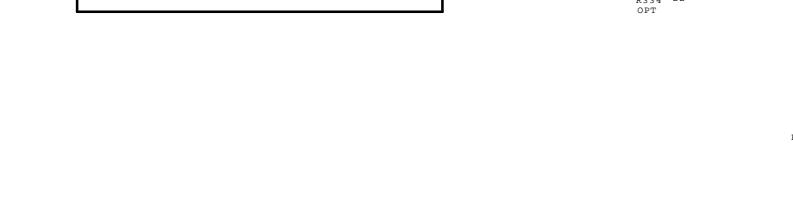
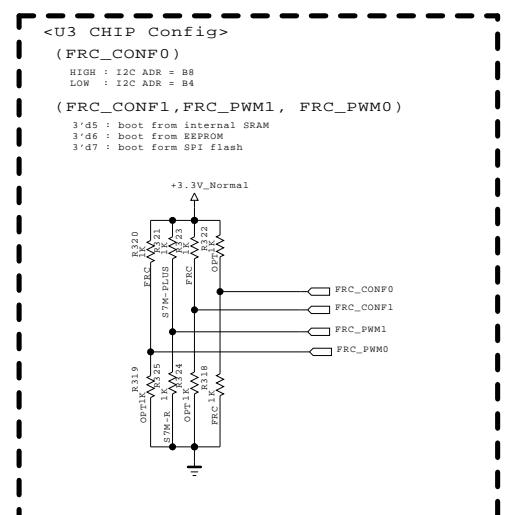
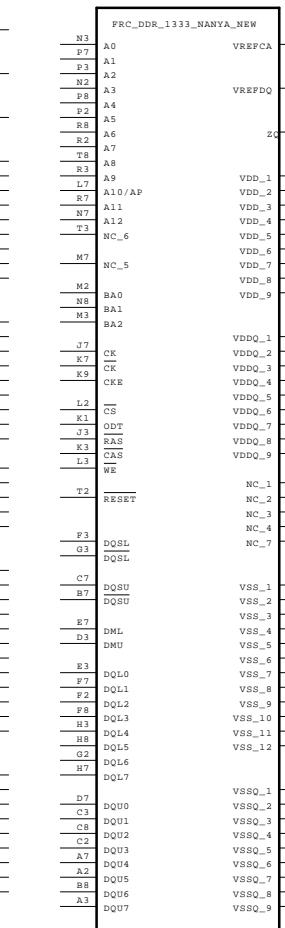
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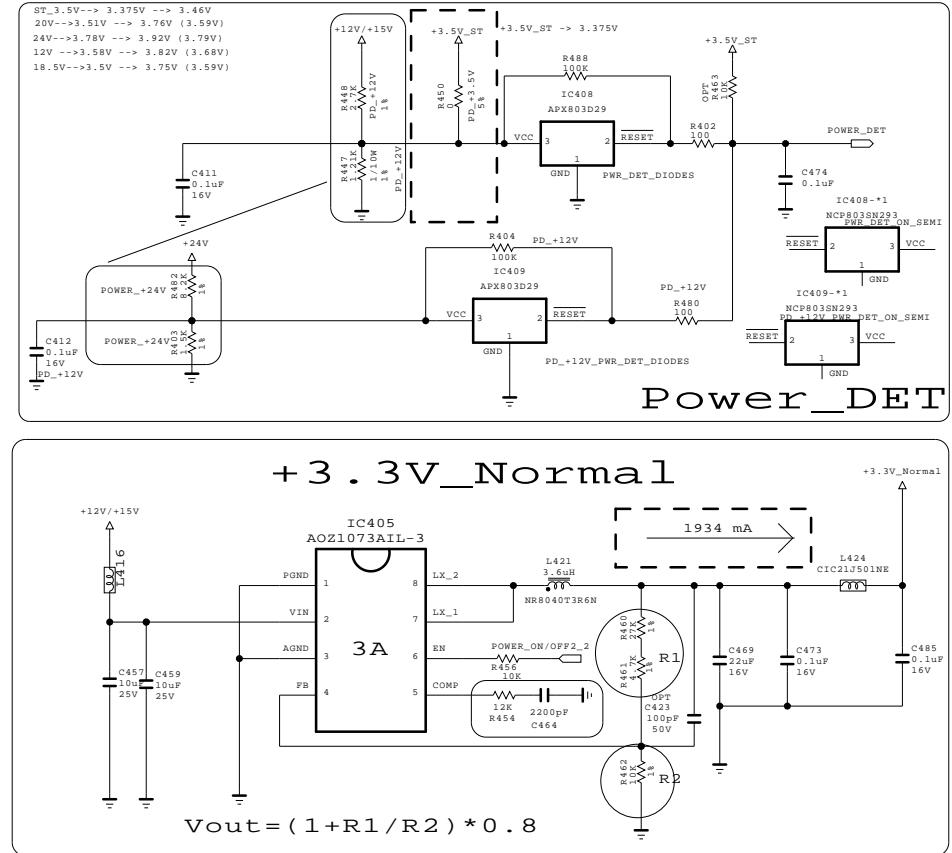
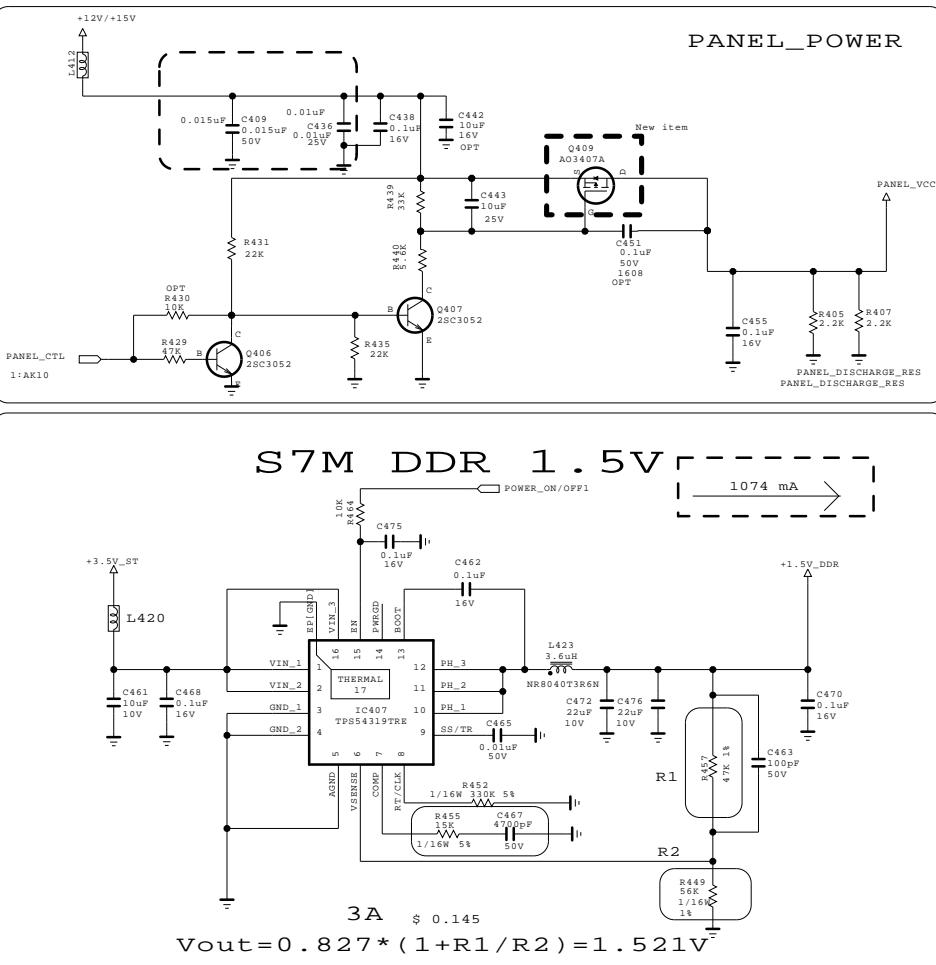
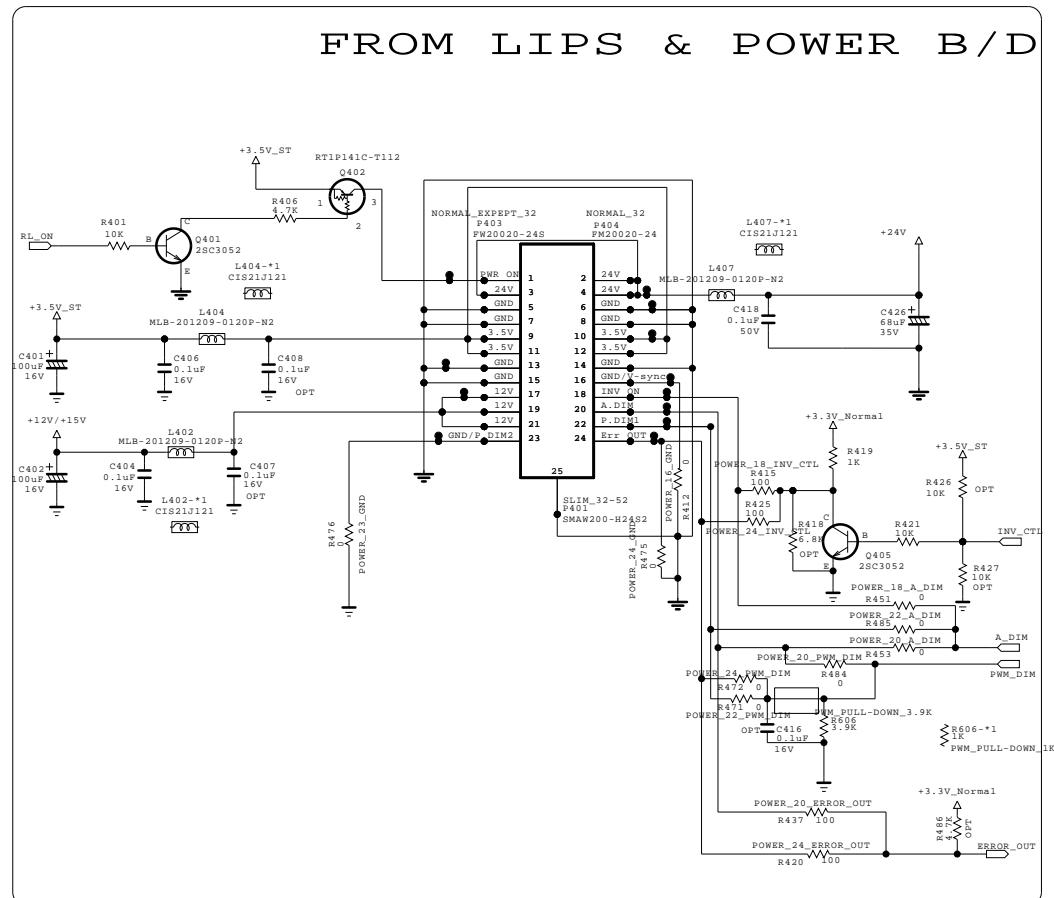


EAN61857201  
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SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION, FIRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE SYMBOL MARK OF THE SCHEMATIC.

FROM LIPS & POWER B/D

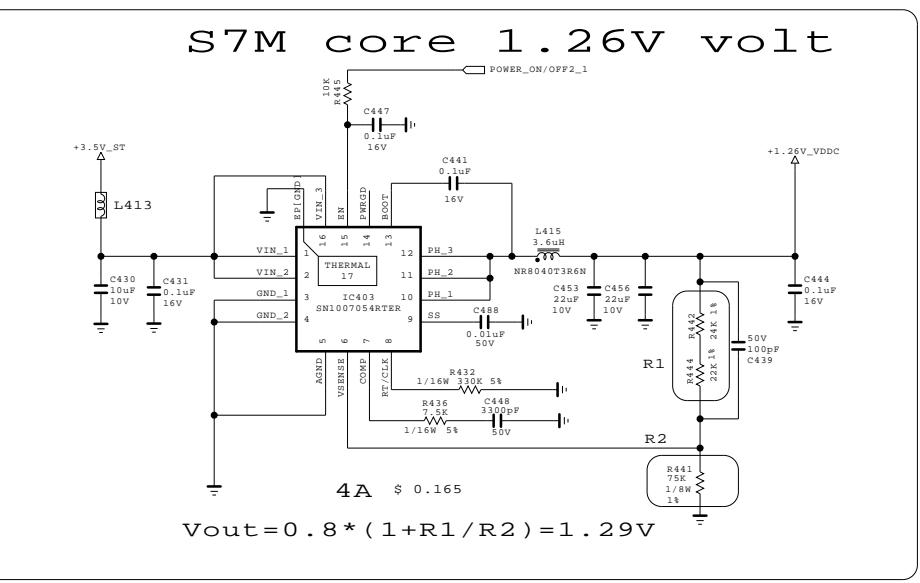
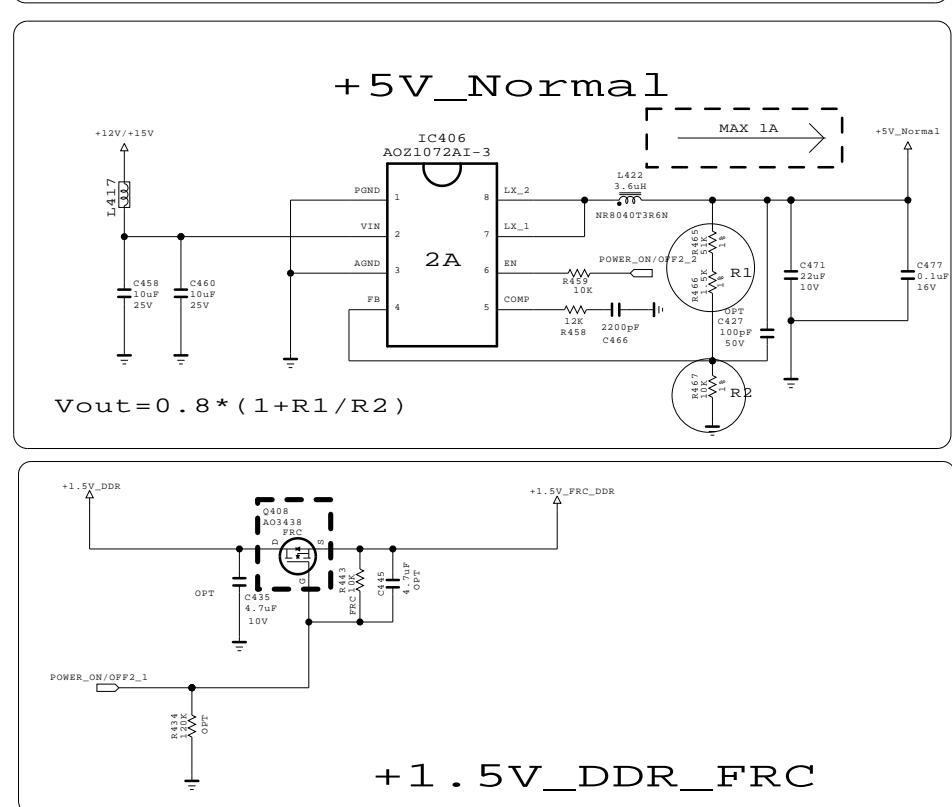
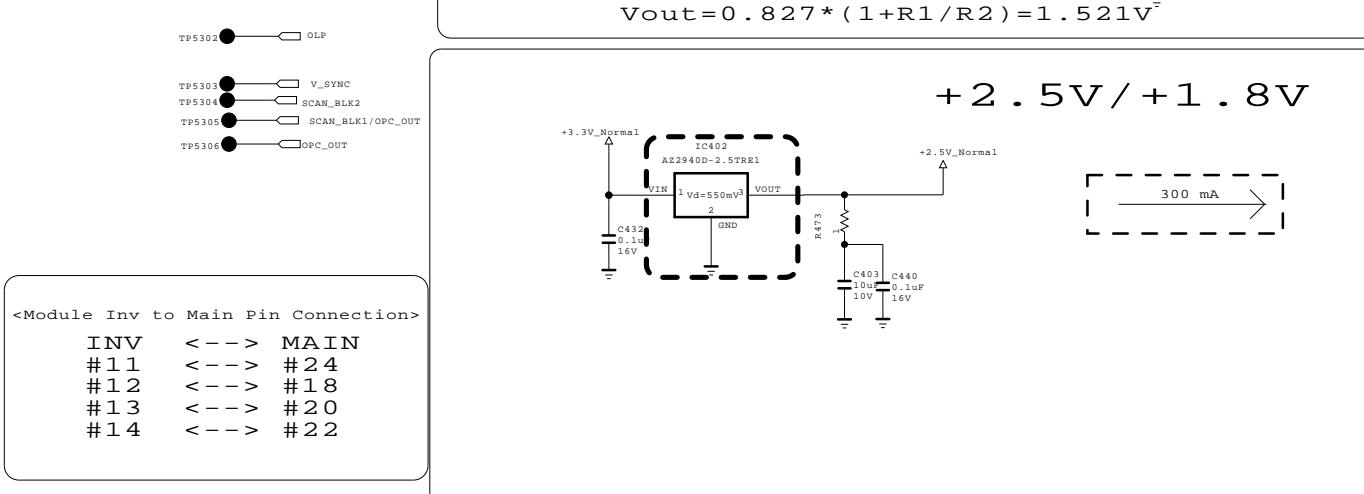


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PIN No	LGD (PSU) or LIPS	CM010* Lamp (PSU)	AUO 10* Lamp (PSU)	SHARP (PSU)	IPS-@ (PSU)
16	GND	GND	GND	GND	GND
18	INV_ON	A-DIM	INV_ON	INV_ON	INV_ON
20	VBR-A	NC	Err_out	5/26:0:ERROR 26/32HD:NC	Err_out
22	PWM_DIM	PWM_DIM	NC	26/32:52:PWM 60:NC	NC
24	Err_out	INV_ON	PWM_DIM	26/32:52:GND 60:PWM	PWM_DIM
23	GND	GND	GND	GND	GND

<LED MODULE BIN MAP -> latest update 20100618

<LED MODULE PIN MAP -> latest update 20100618>				
PIN NO	LGD LPB OS LPB	32LES300-TA CM010-LED (PSU)	32LE4500-TA AUO 10"-LED (PSU)	32LES300-TA LGD 10"-LED (PSU)
16	NC	NC	NC	NC
18	INV_ON	INV_ON	INV_ON	INV_ON
20	NC	err_out ---> NC	err_out ---> NC	NC
22	PWM_DIM	NC	NC	PWM_DIM
24	err_out ---> NC	PWM_DIM	PWM_DIM	err_out ---> NC
23	NC	NC	NC	NC

LGD edge led error-out use or not? checking is necessary

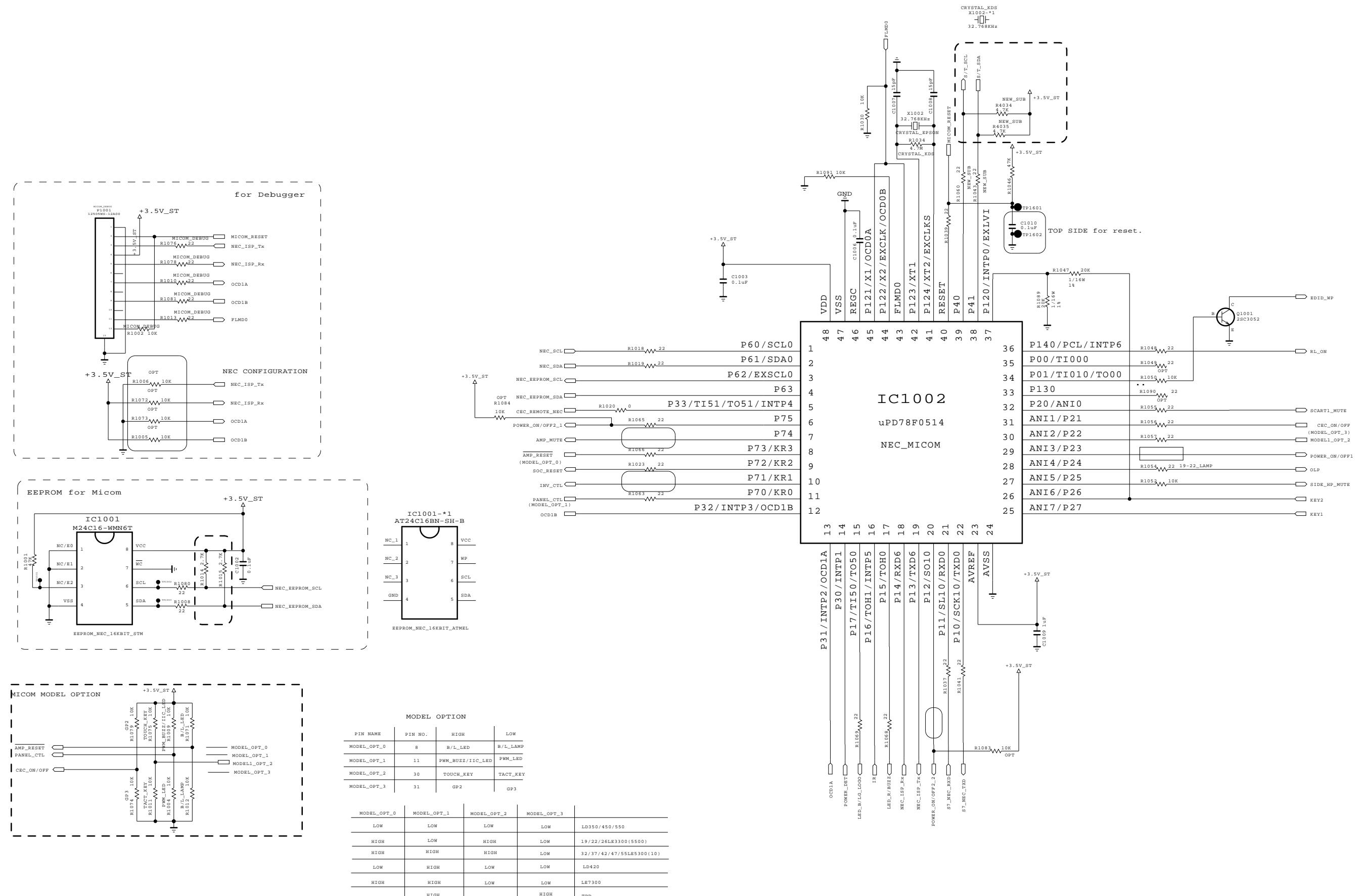


THE  SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION. FIRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE  SYMBOL MARK OF THE SCHEMATIC.

SECRET

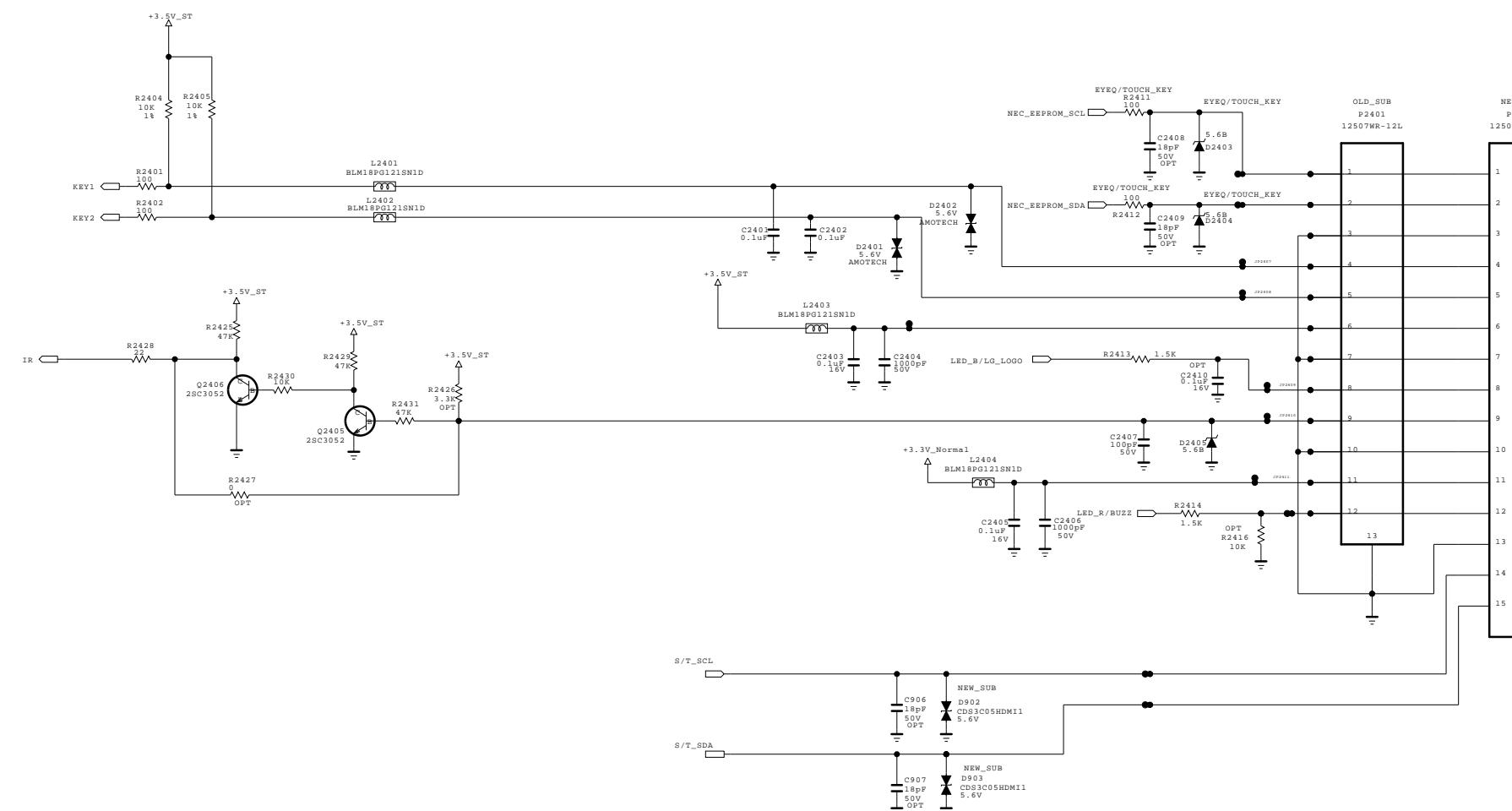
 LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	POWER_LARGE	SHEET	4 /



THE SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION, FIRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE SYMBOL MARK OF THE SCHEMATIC.

## CONTROL IR & LED

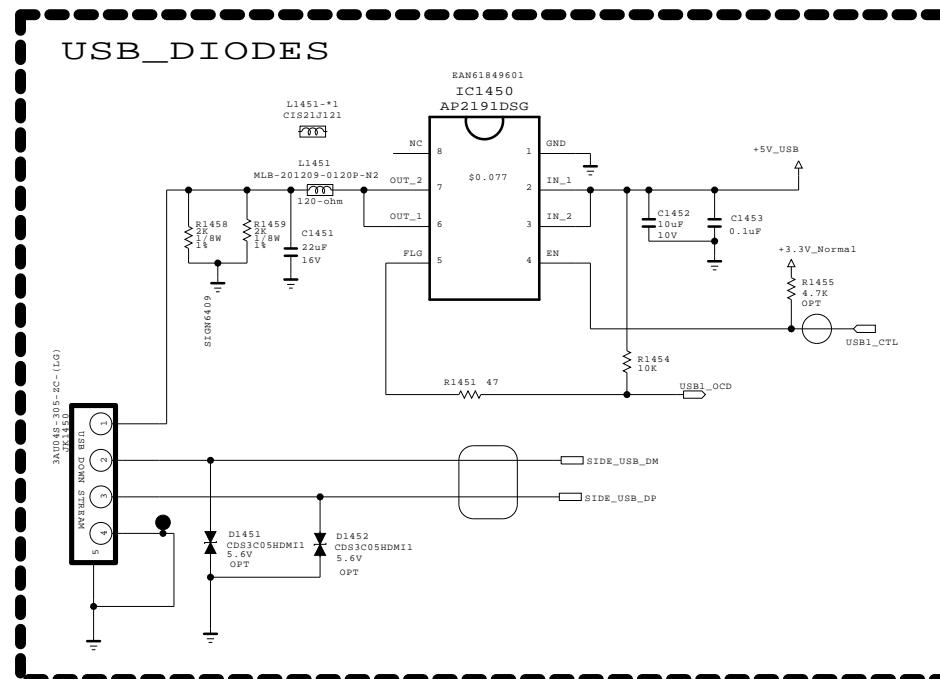


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SECRET



MODEL	GP2R	DATE	20101023
BLOCK	IR / CONTROL - L	SHEET	6 /

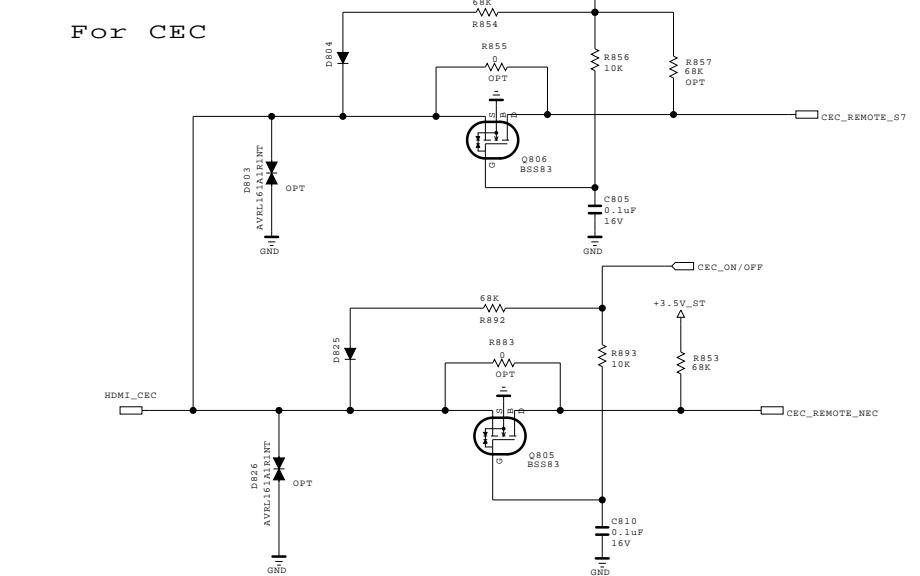
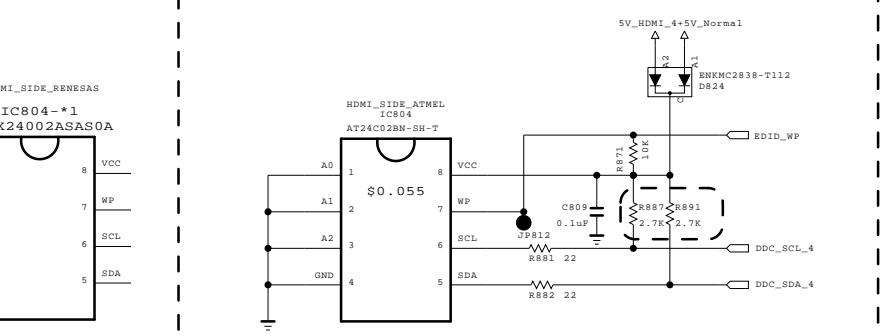
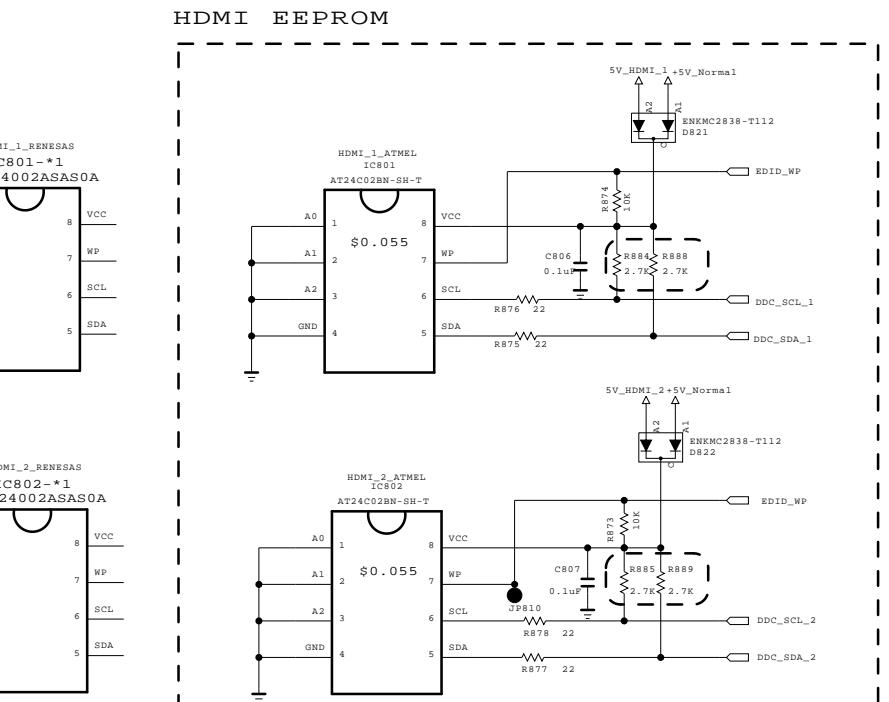
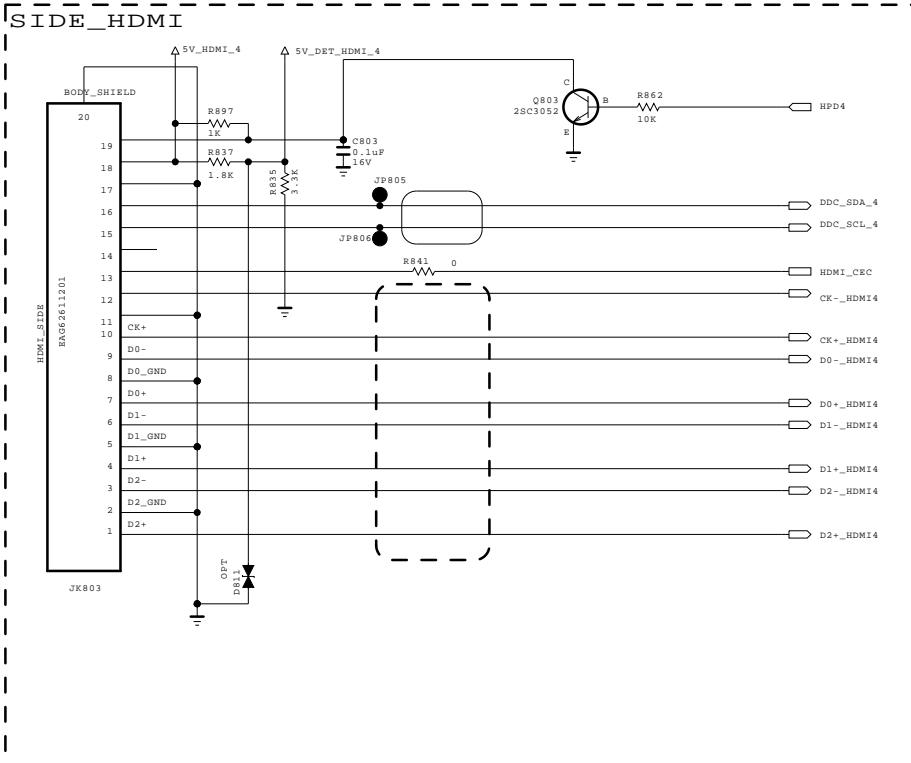
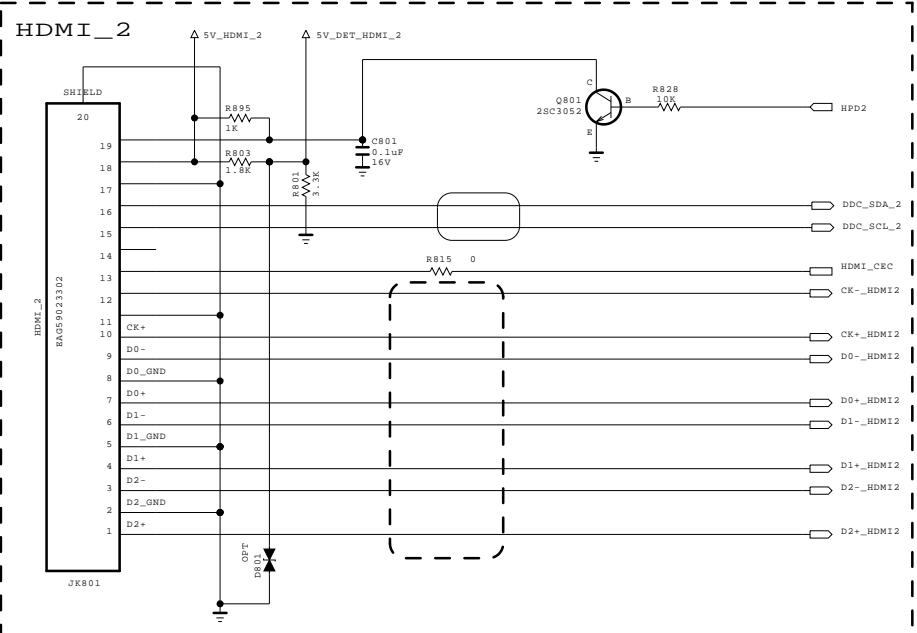
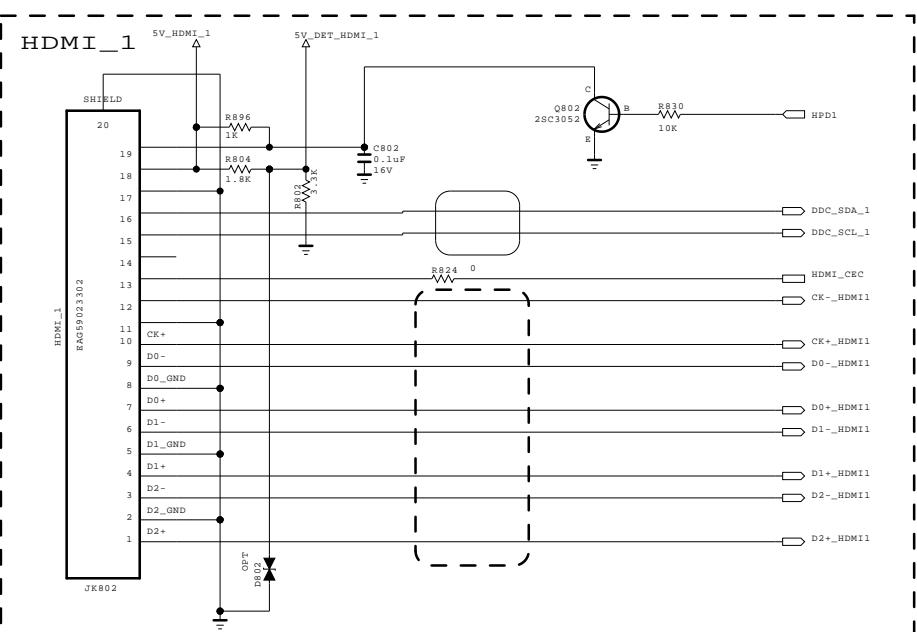


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**SECRET**  
LG Electronics

LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	USB_OCP_DIODE	SHEET	7



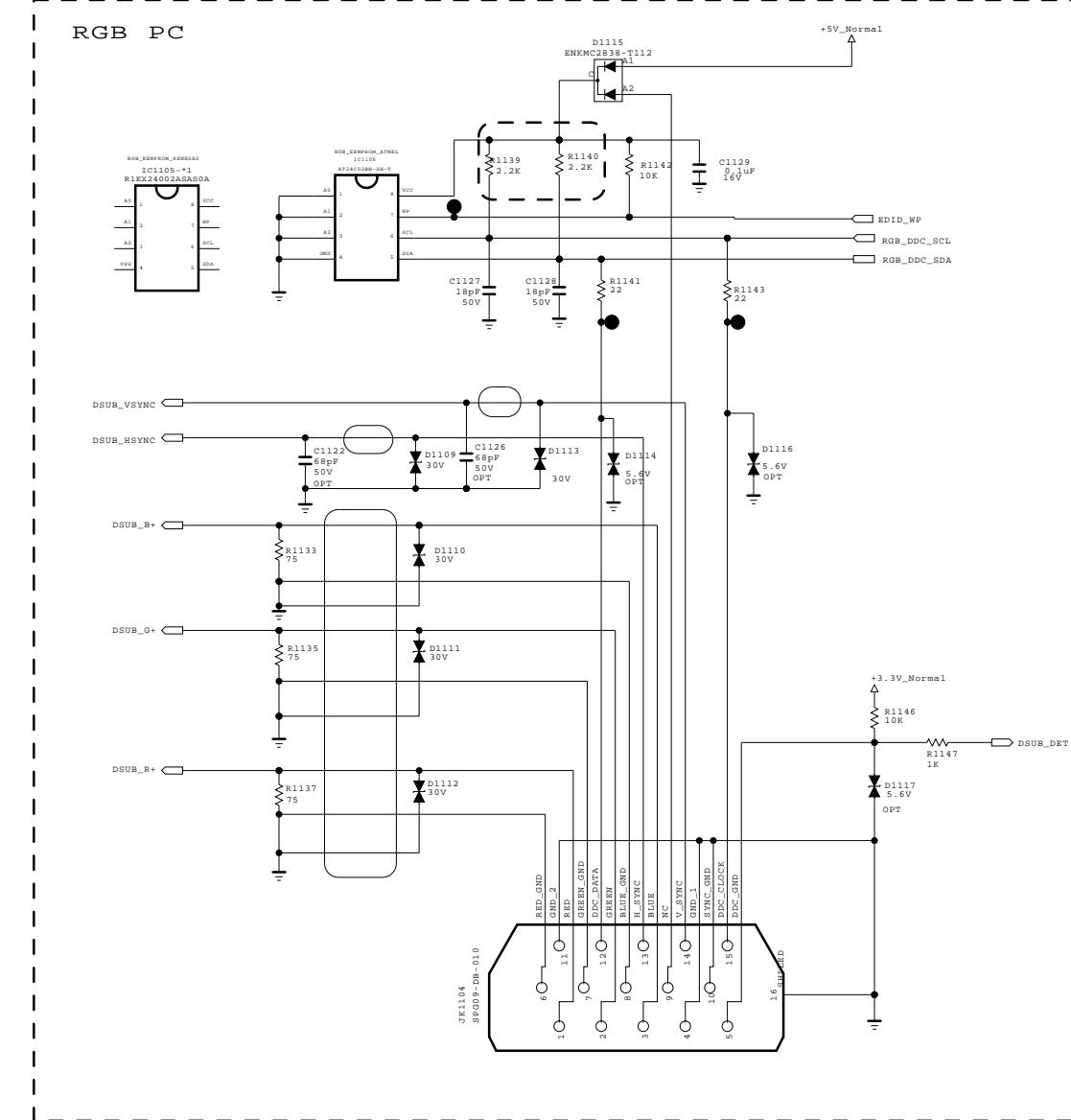
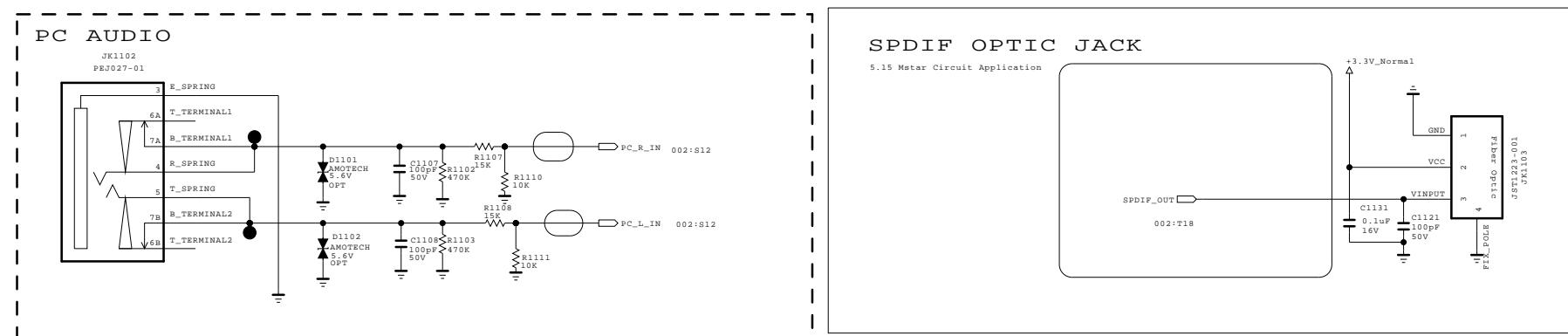
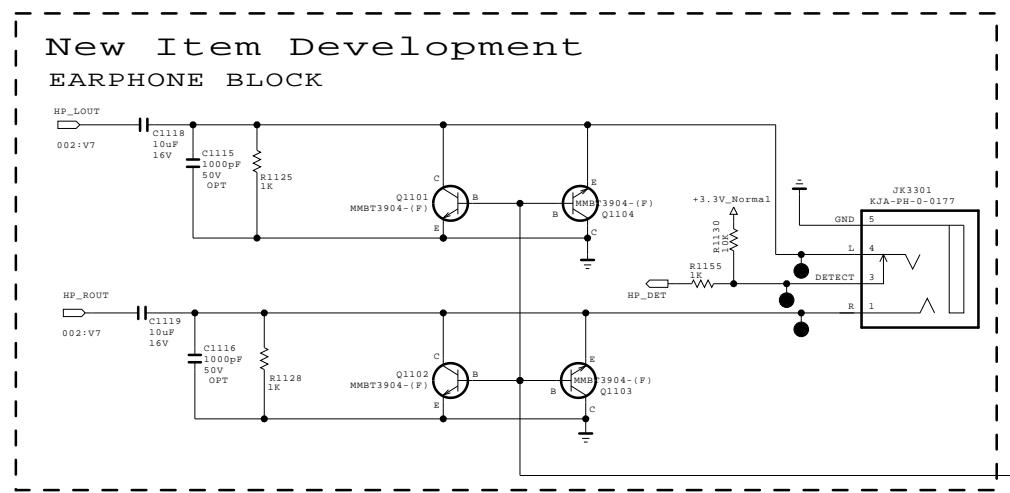
THE  SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION. FILRE AND ELECTRICAL SHOCK HAZARDS. WHEN SERVICING IT IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE  SYMBOL MARK OF THE SCHEMATIC.

SECRET



MODEL	GP2R	DATE	20101023
BLOCK	HDMI	SHEET	8 /

# RGB / SPDIF / PC / HP

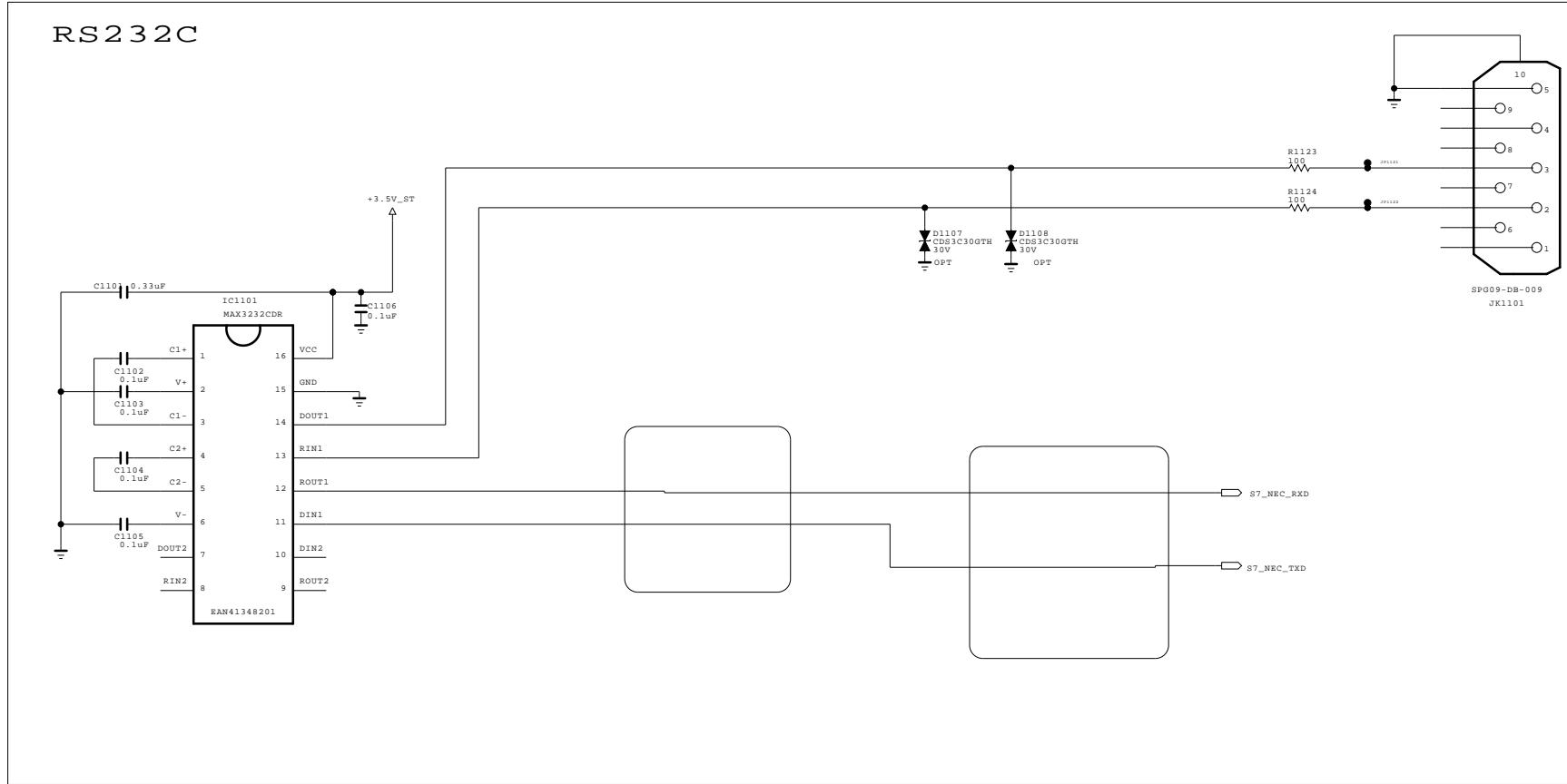


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SECRET



MODEL	GP2R	DATE	20101023
BLOCK	RGB / SPDIF / HP	SHEET	9 /

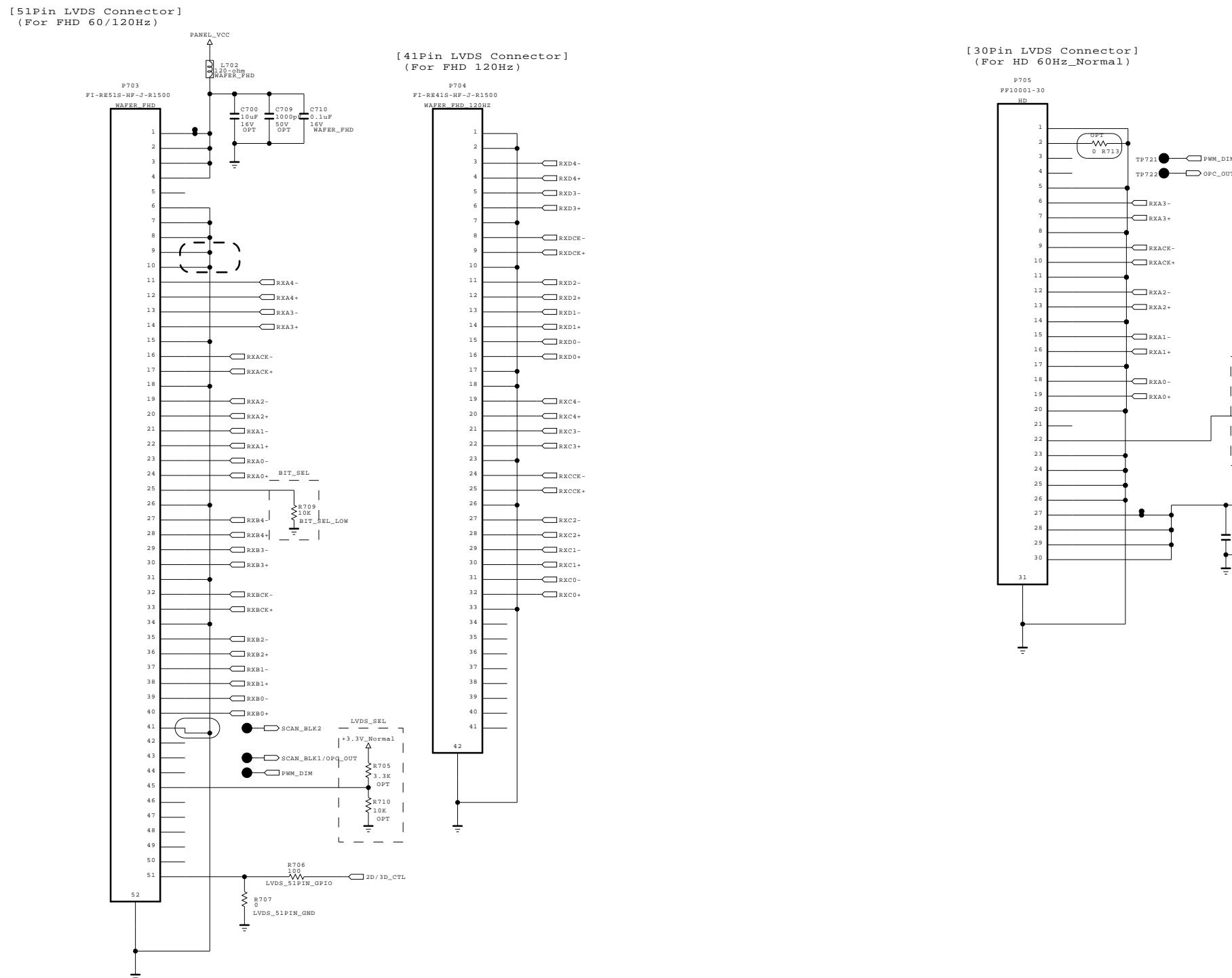


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**SECRET**  
LG Electronics

 LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	RS232C_9PIN	SHEET	10

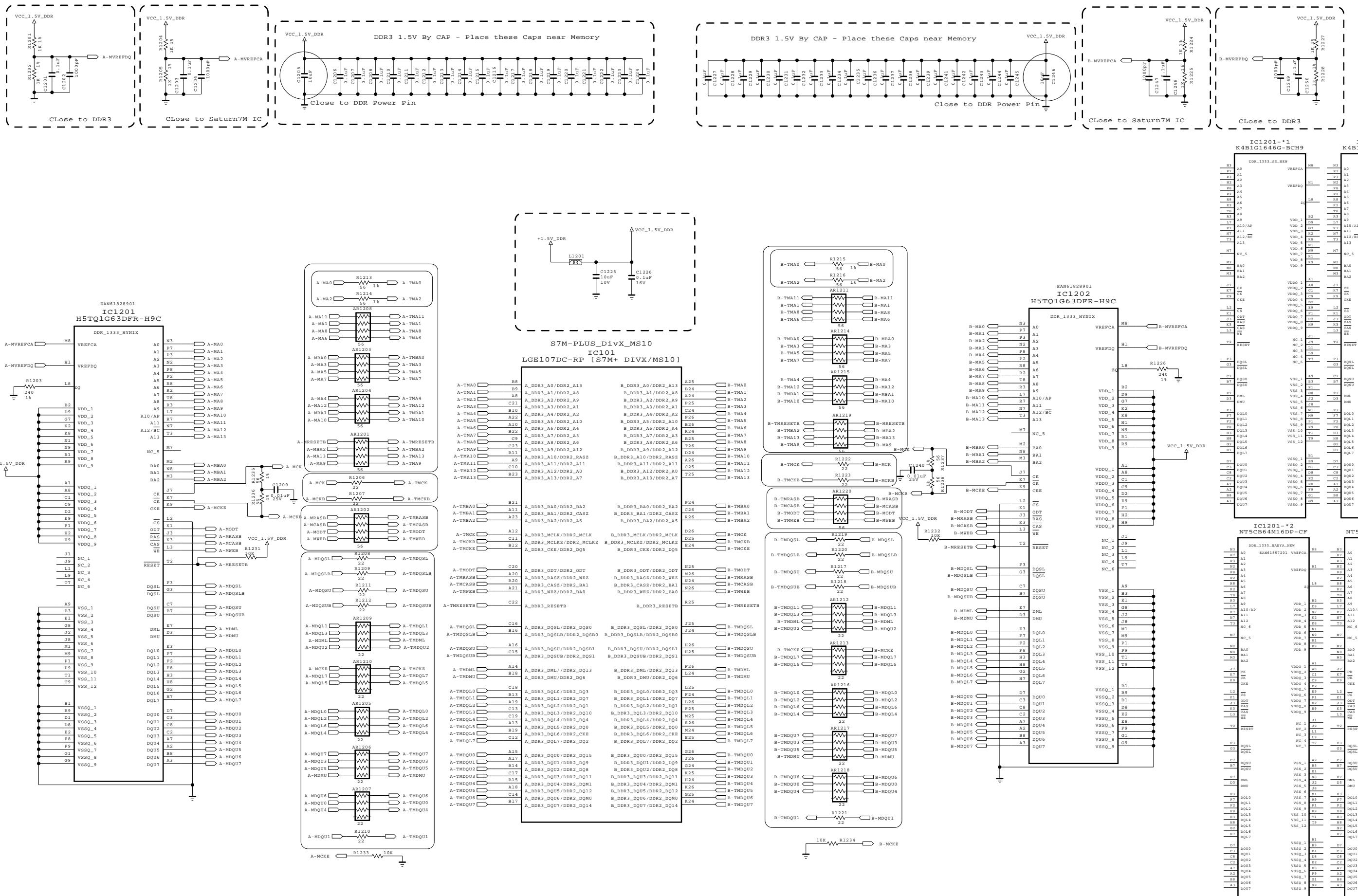


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SECRET



<u>MODEL</u>	GP2R	<u>DATE</u>	20101023
<u>BLOCK</u>	LVDS_LARGE	<u>SHEET</u>	11 /

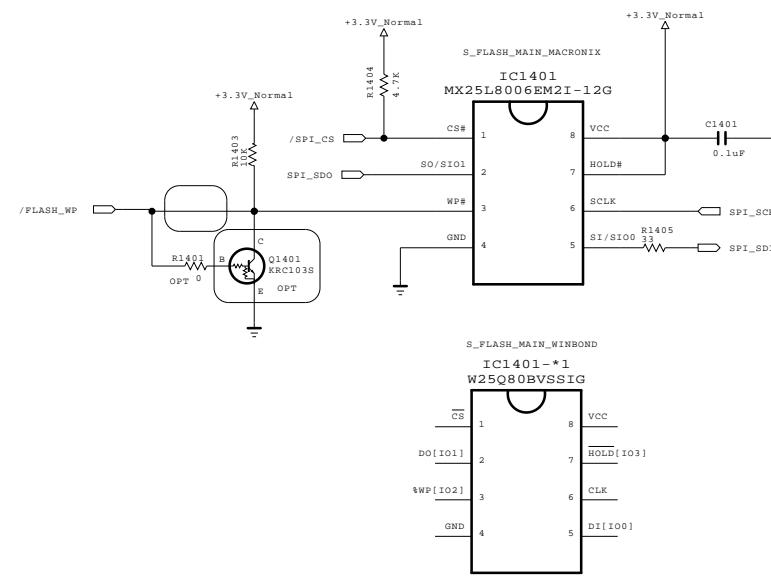


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SECRET  
LG Electronics



MODEL	GP2R	DATE	20101023
BLOCK	DDR_256	SHEET	12 /



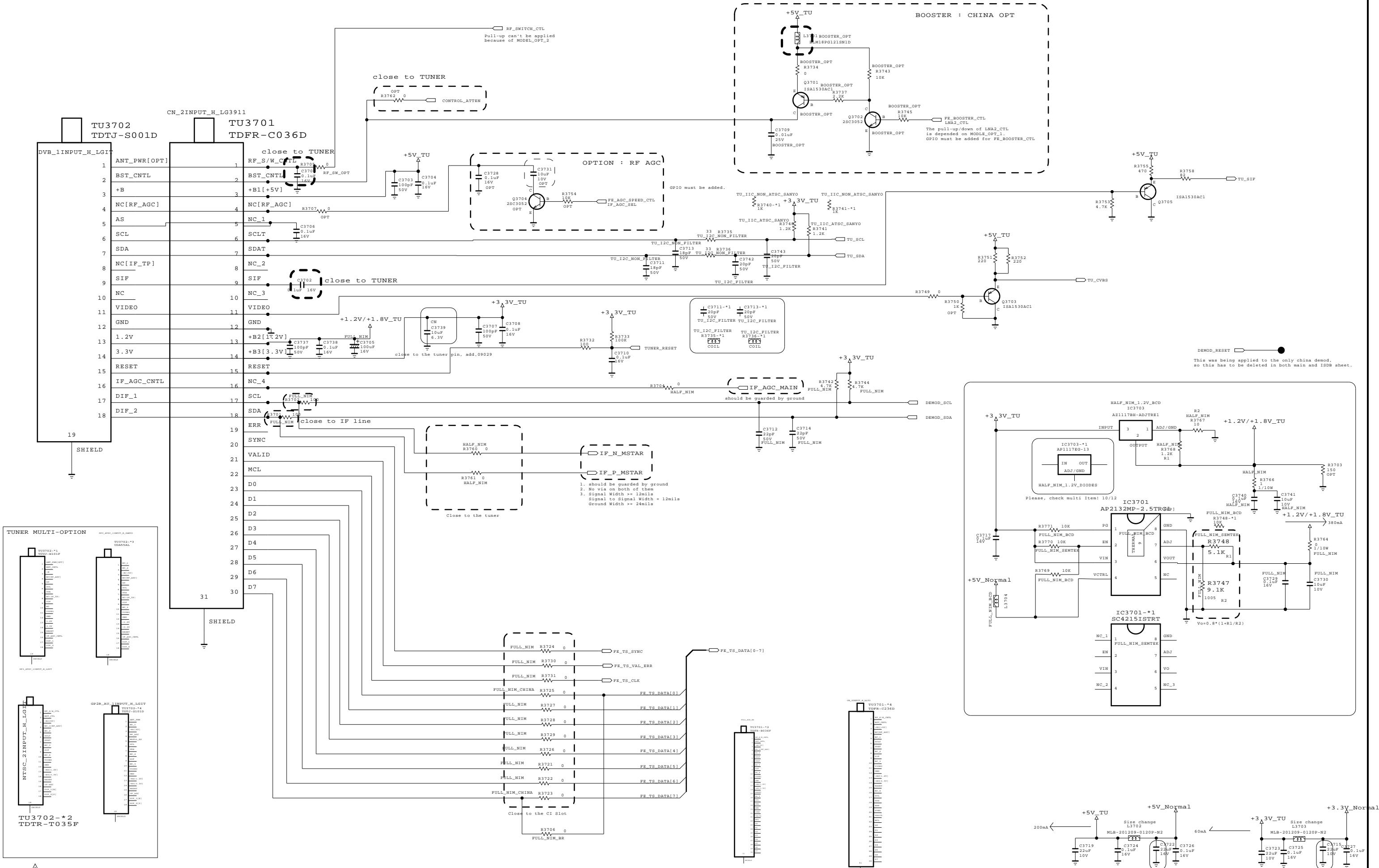
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**SECRET**  
LG Electronics

LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	SFLASH 1MB	SHEET	13

# GP2R\_LARGE\_TUNER



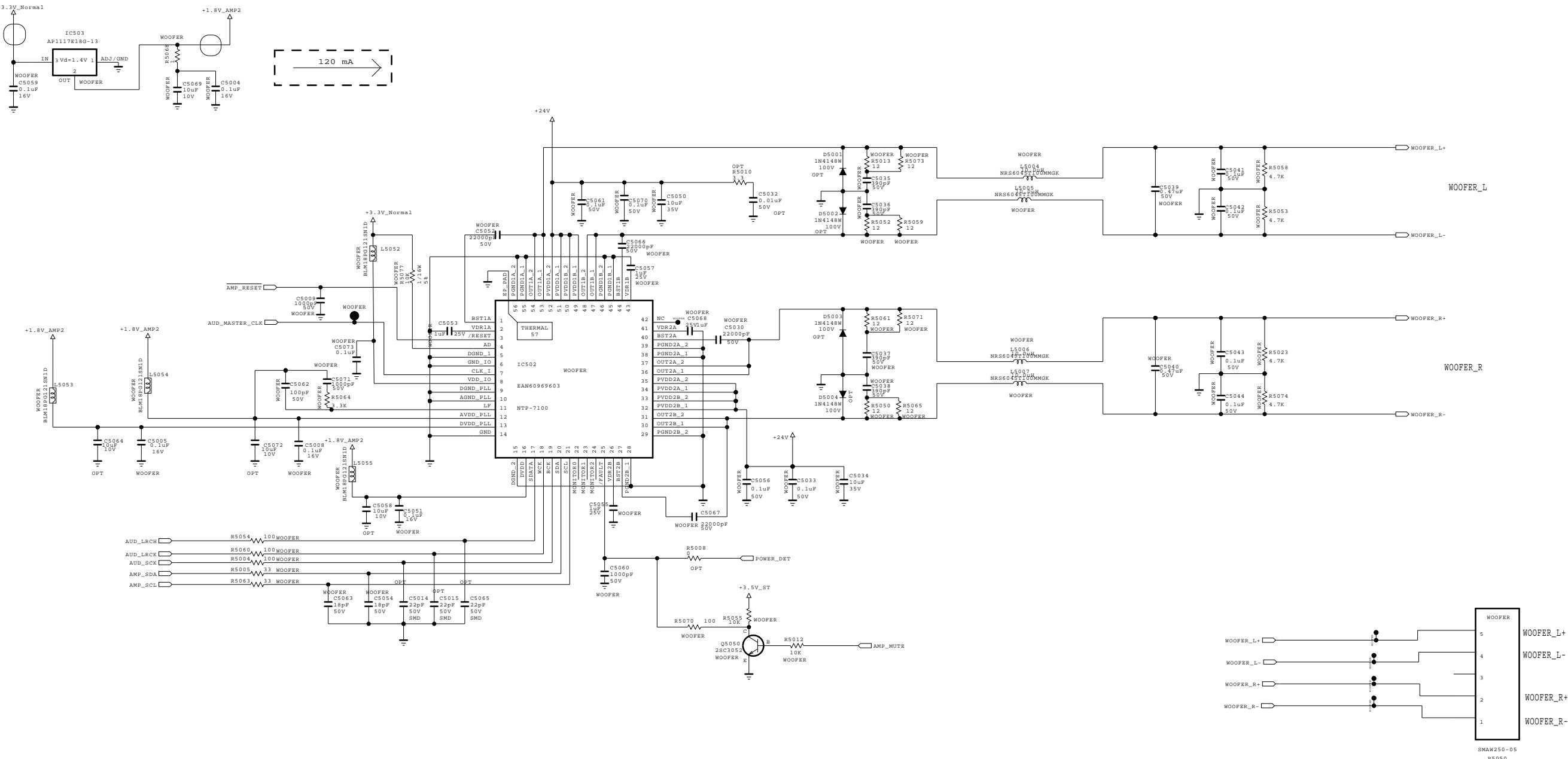
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SECRET



MODEL	GP2R	DATE	20101023
BLOCK	TUNER_L	SHEET	14

# WOOFER AMP

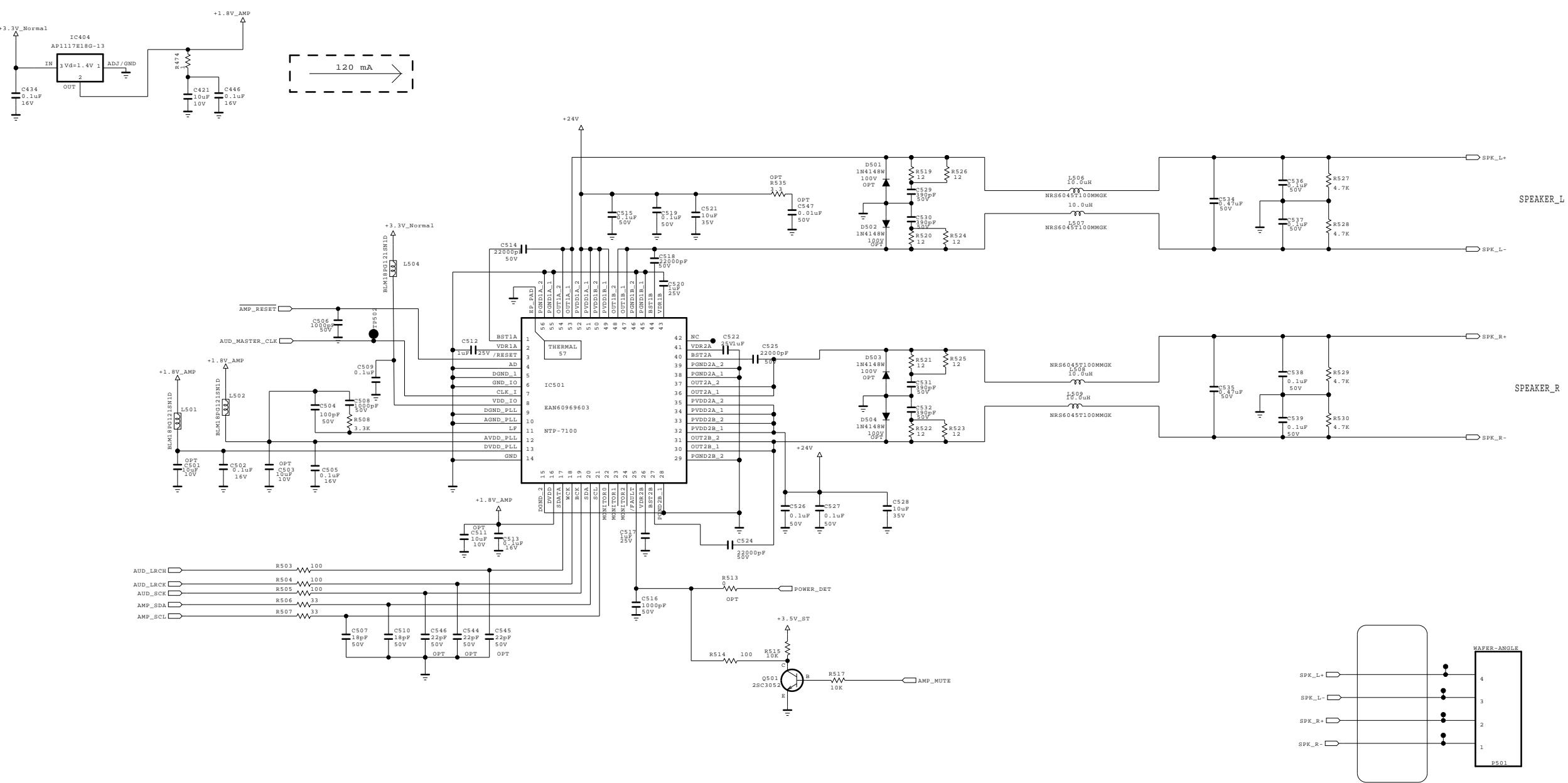


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SECRET



MODEL	GP2R	DATE	20101023
BLOCK	WOOFER_NTP	SHEET	15 /

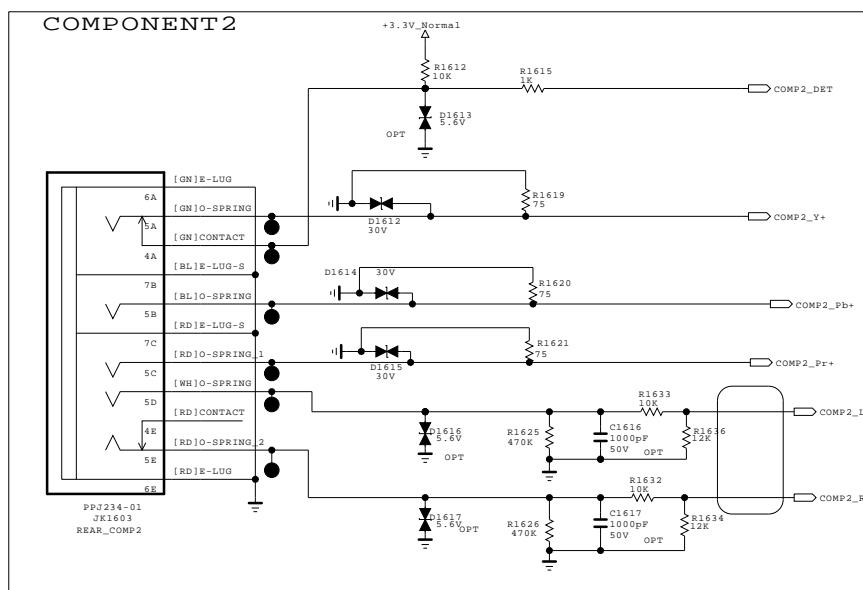
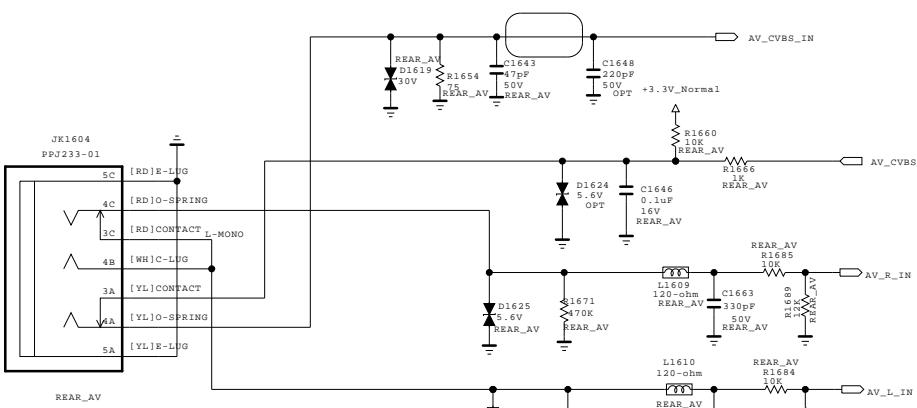


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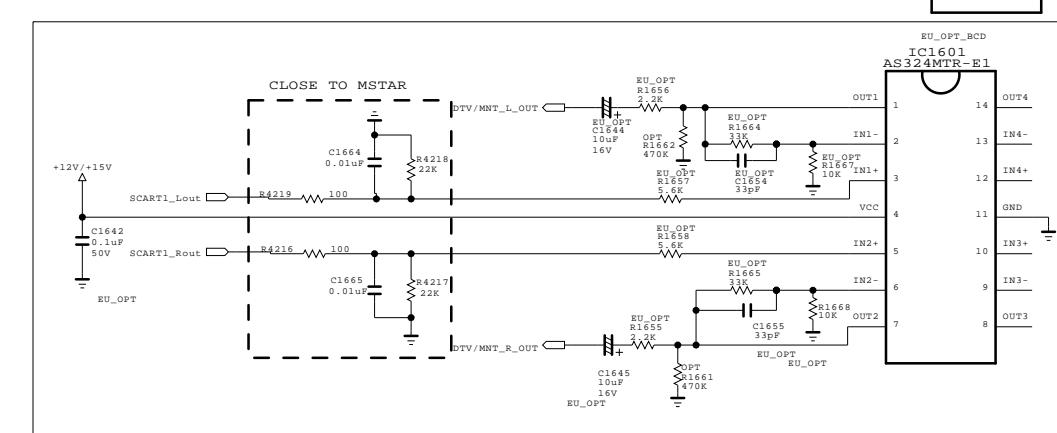
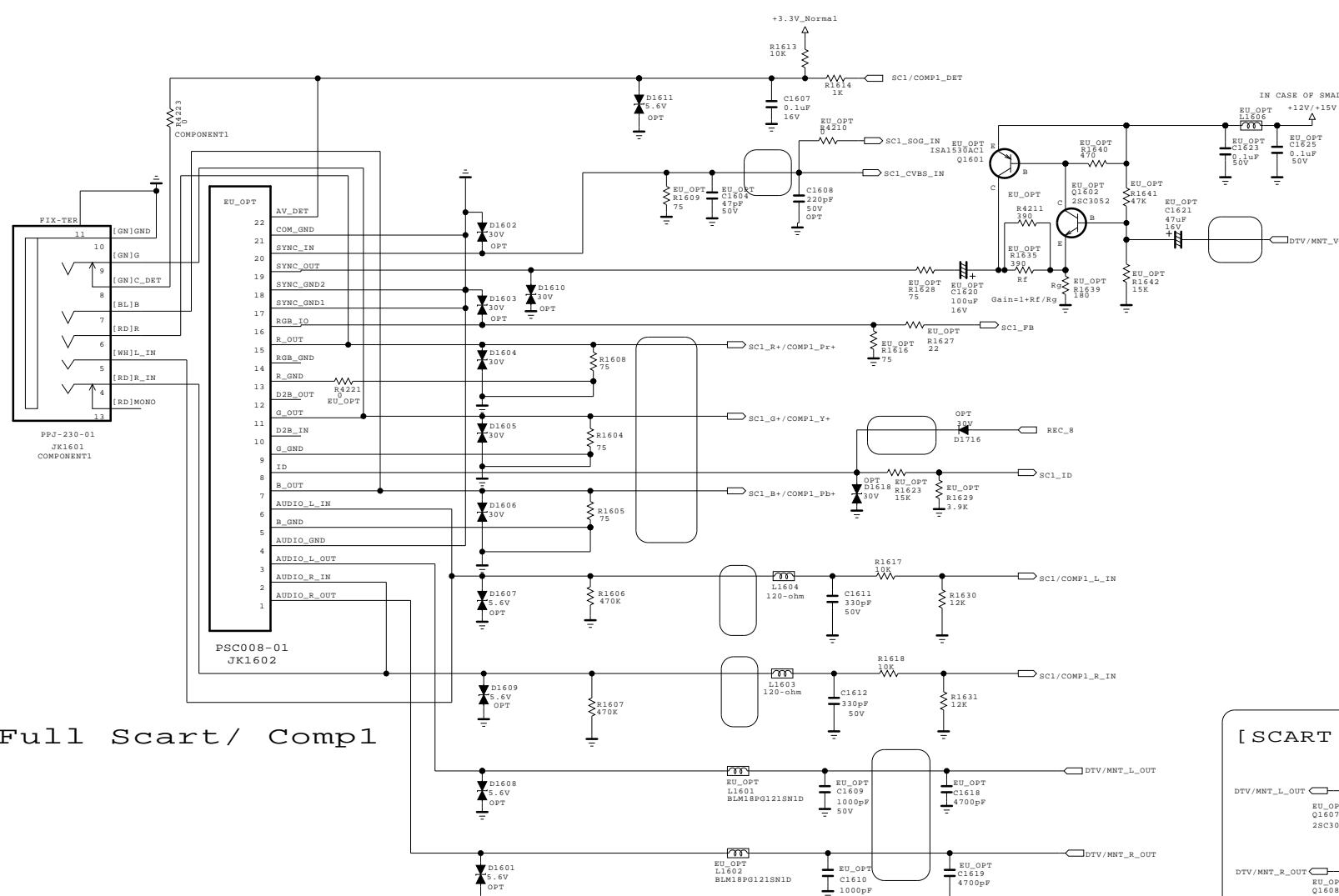
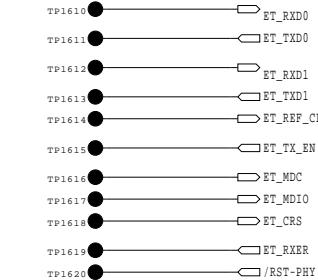
SECRET  
LG Electronics

LG ELECTRONICS

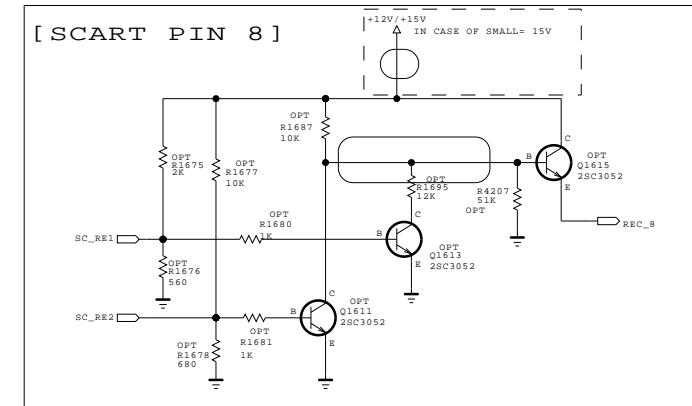
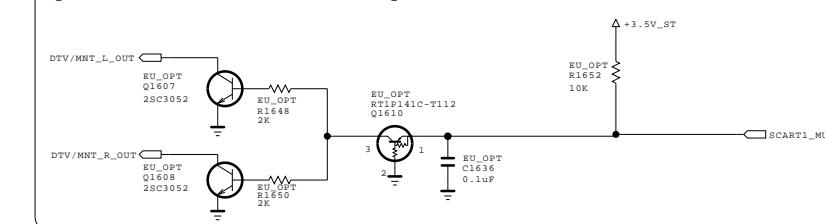
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BLOCK	AMP_NTP	SHEET	16



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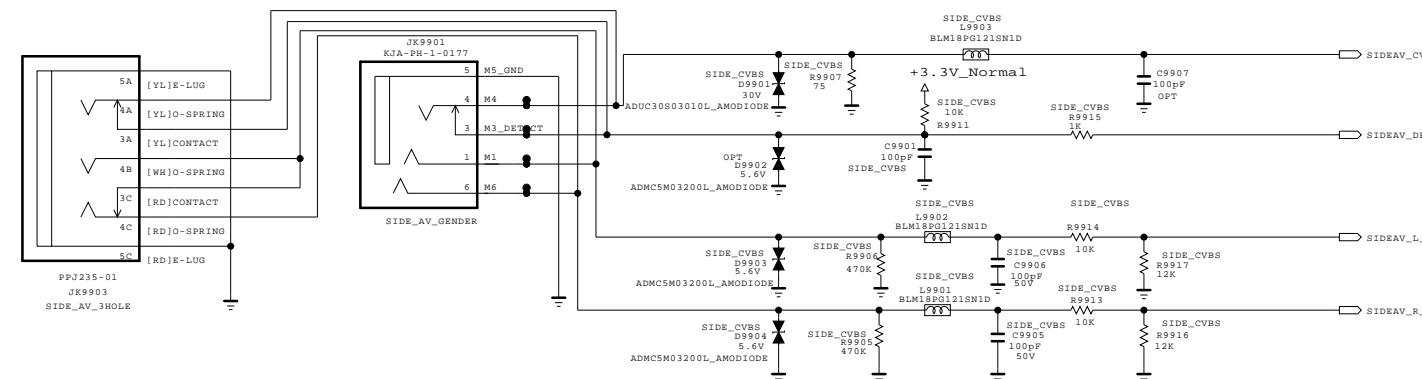


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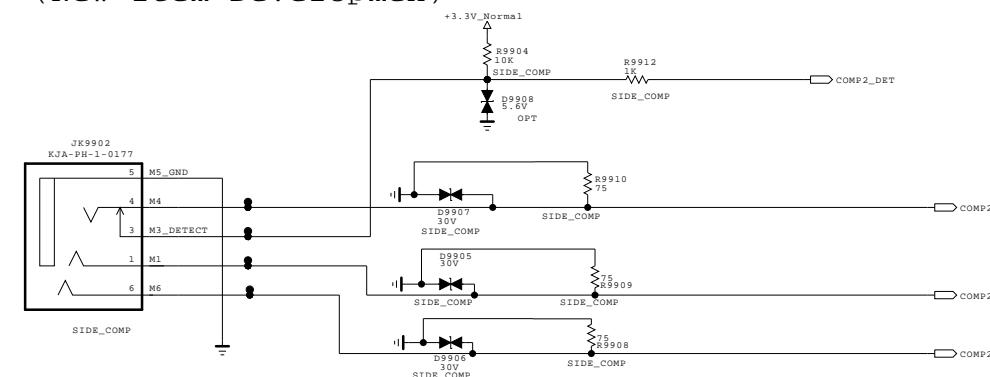


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SIDE CVBS PHONE JACK  
(New Item Development)



SIDE COMPONENT PHONE JACK  
(New Item Development)



THE  SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION. FILRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE  SYMBOL MARK OF THE SCHEMATIC

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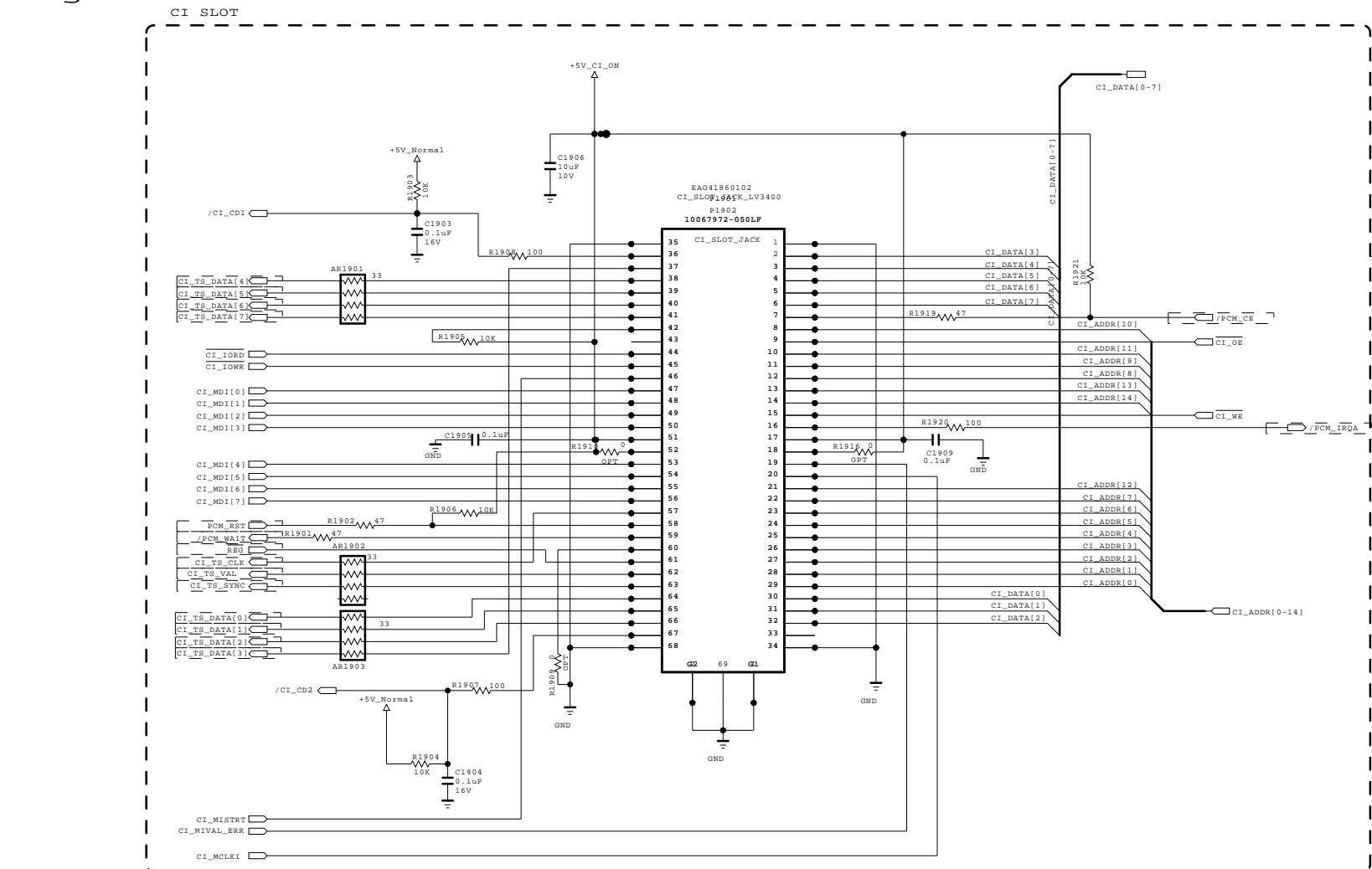


LG ELECTRONICS

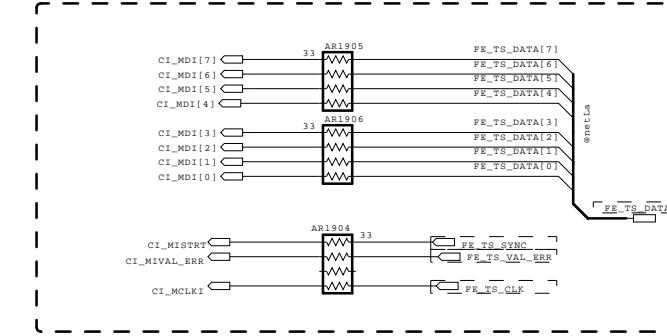
MODEL	GP2R	DATE	20101023
BLOCK	SIDE_JACK	SHEET	18 /

\* Option name of this page : CI\_SLOT  
(because of Hong Kong)

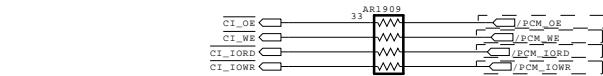
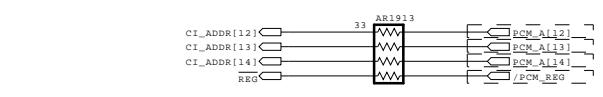
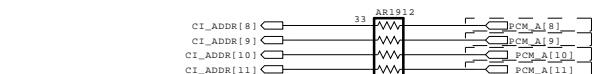
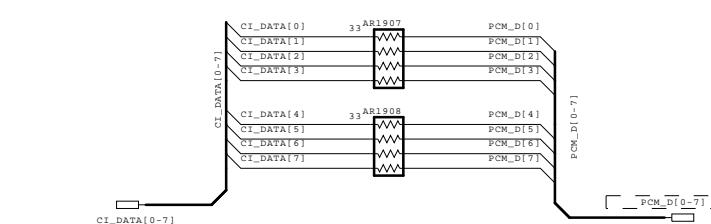
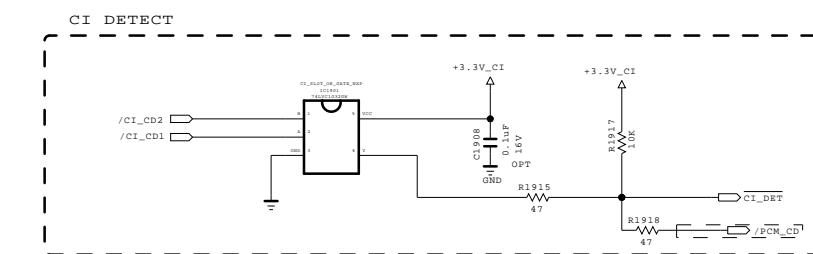
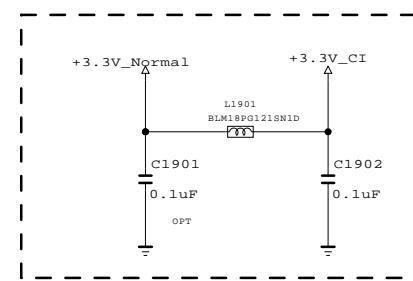
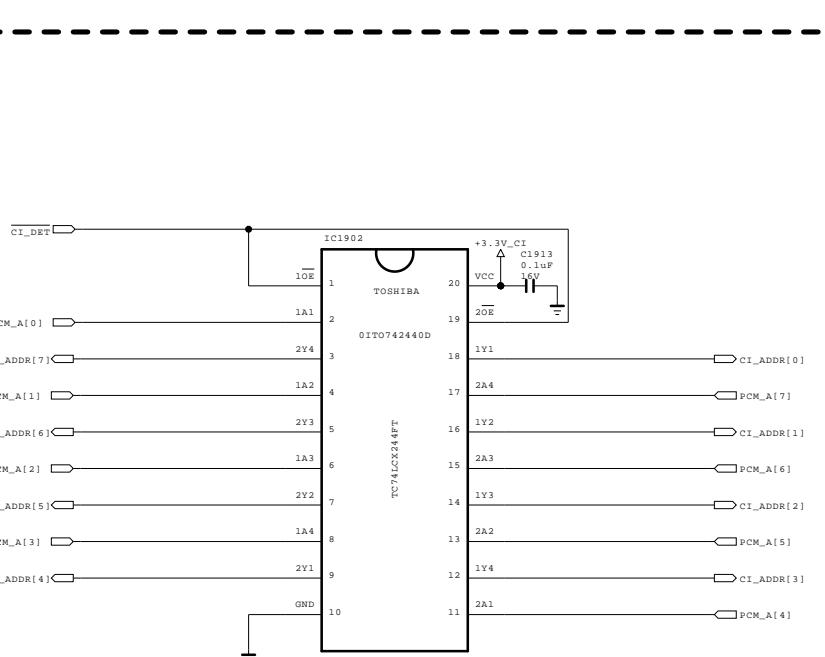
## CI Region



## CI TS INPUT



## CI HOST I/F



THE SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION, FIRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE SYMBOL MARK OF THE SCHEMATIC.

**SECRET**  
LG Electronics

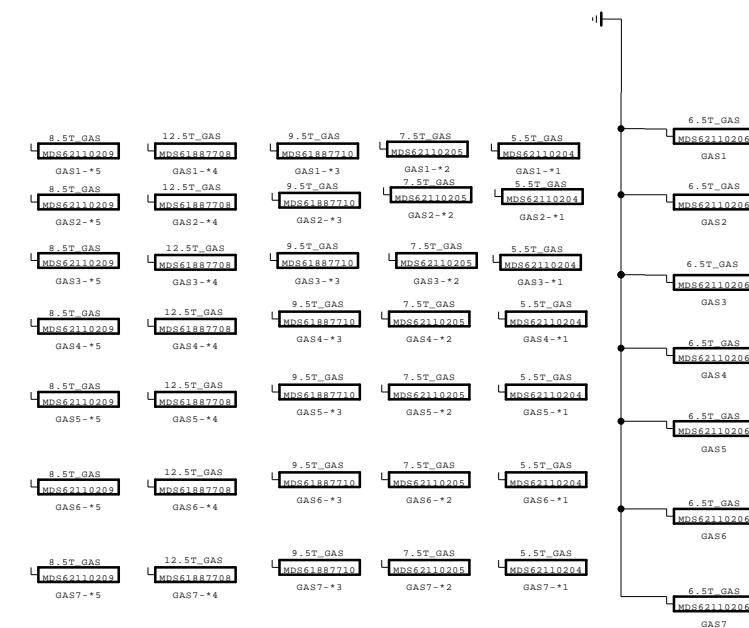
LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	PCMCII	SHEET	20

THE  SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES  
SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION,  
FIRE AND ELECTRICAL SHOCK HAZARDS. WHEN SERVICING IF IS  
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THE CRITICAL COMPONENTS IN THE  SYMBOL MARK OF THE SCHEMATIC.

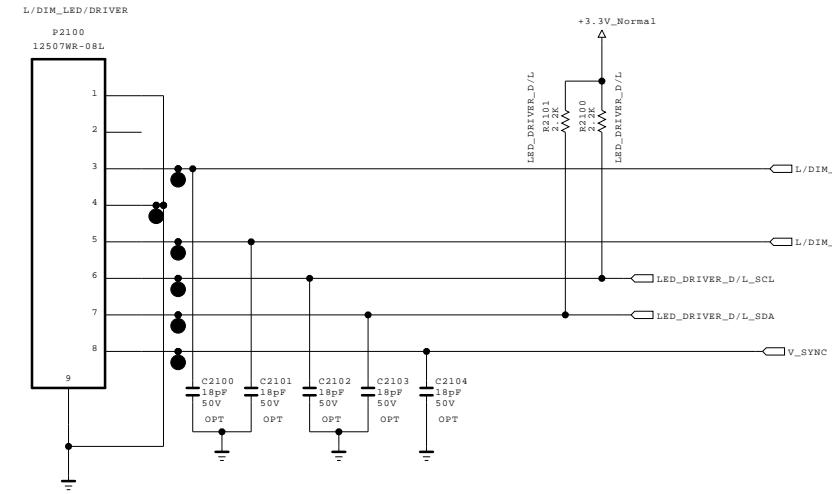
**SECRET**  
LG Electronics

## SMD GASKET



MODEL	GP2R	DATE	20101023
BLOCK	SMD_GAS	SHEET	20

LG ELECTRONICS

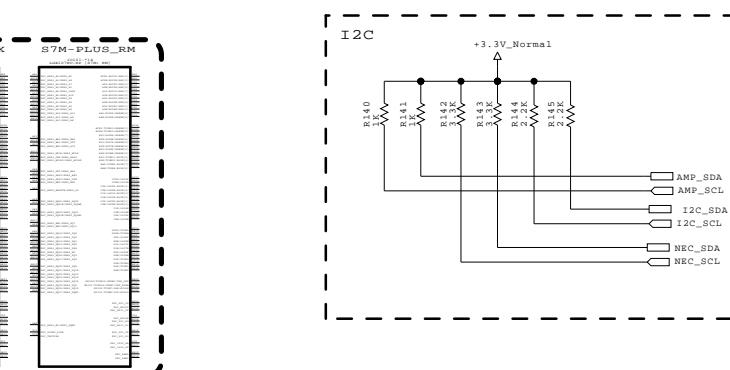
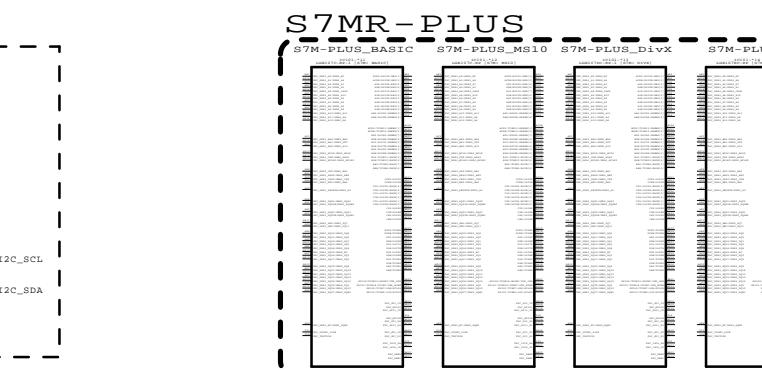
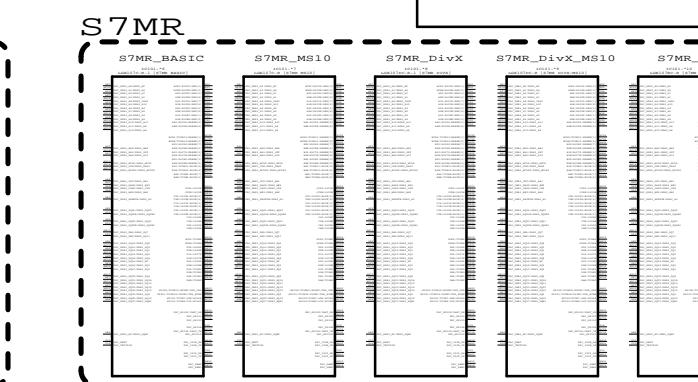
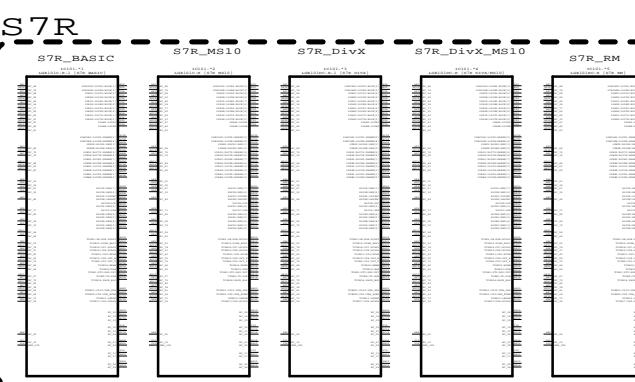
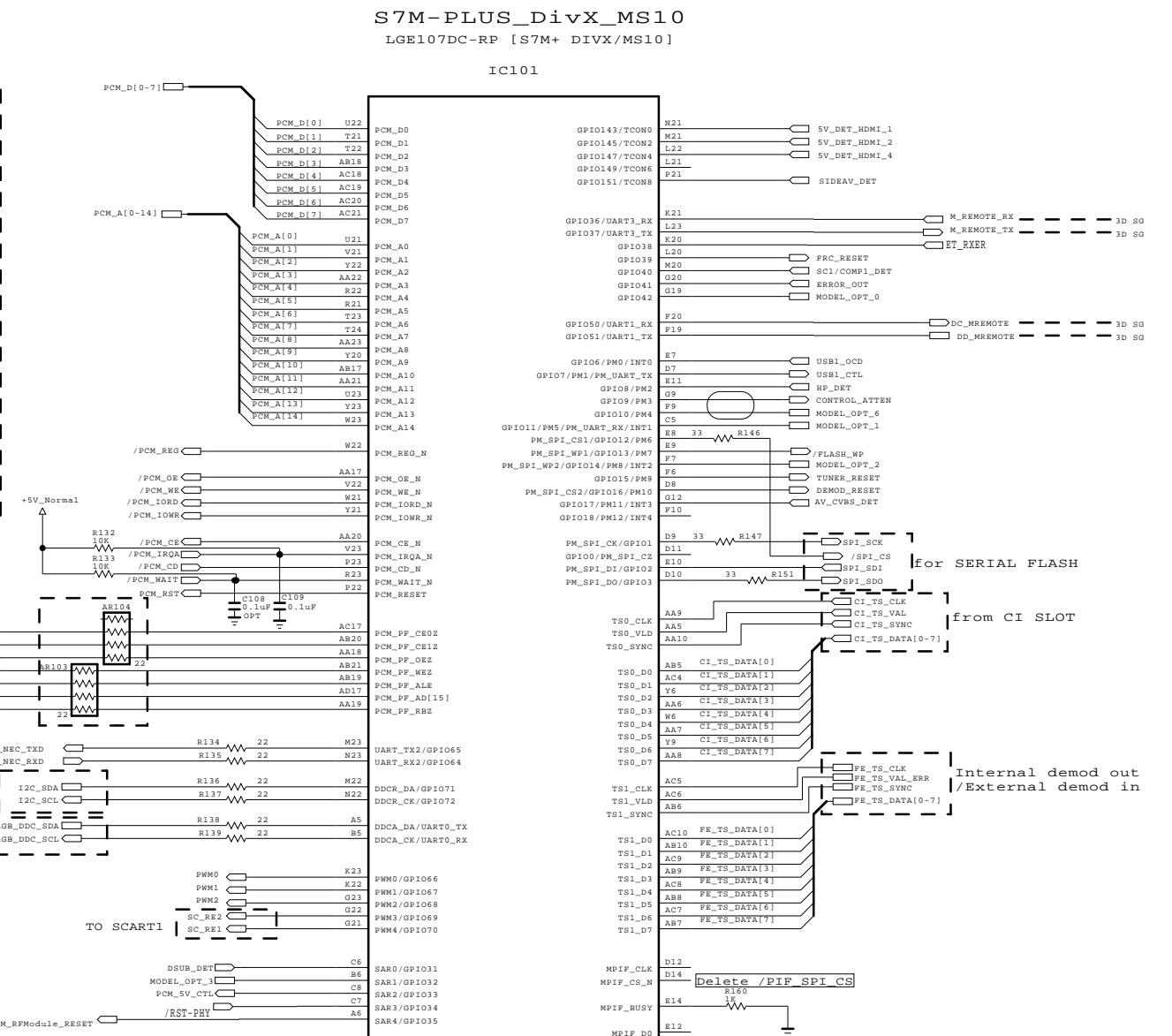
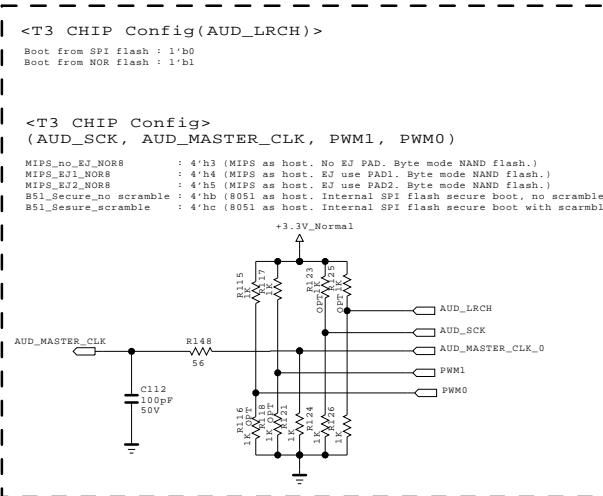
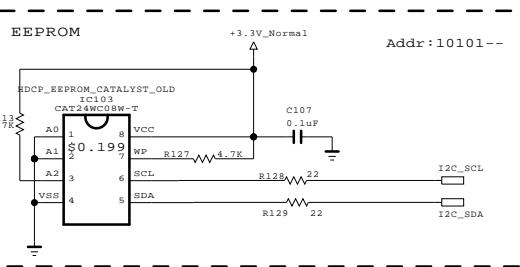
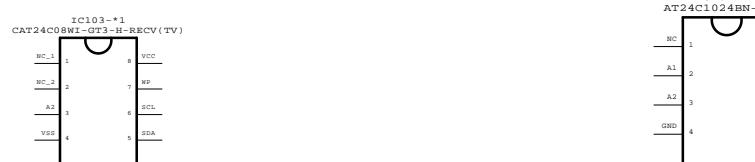
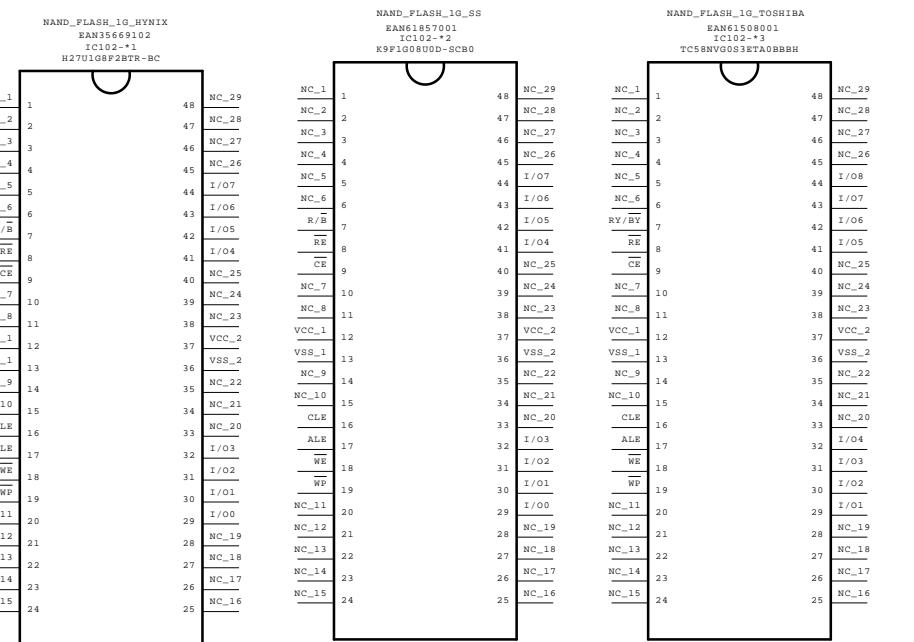
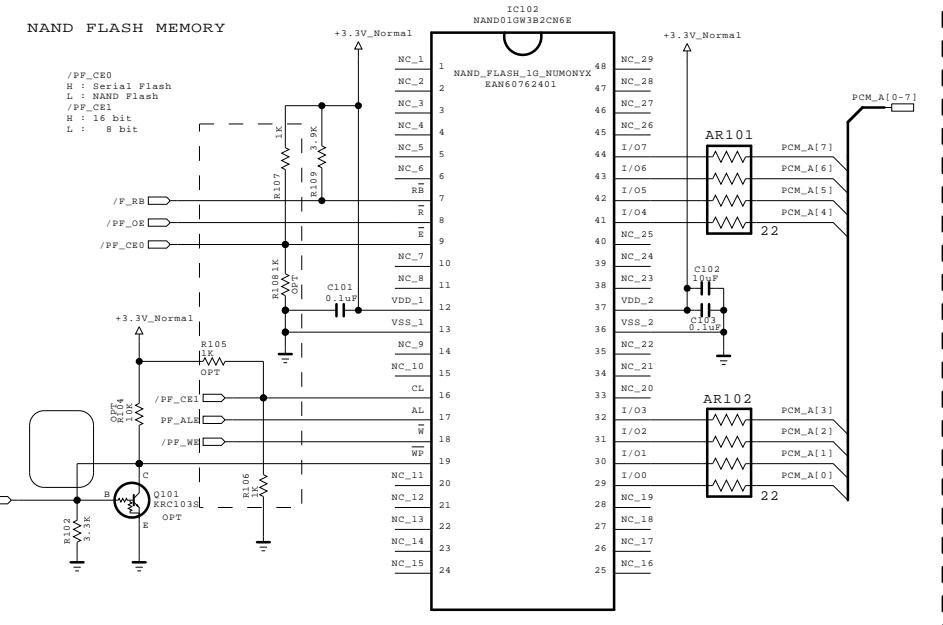


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**SECRET**  
LG Electronics

 LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	L / DIM _ LED	SHEET	21

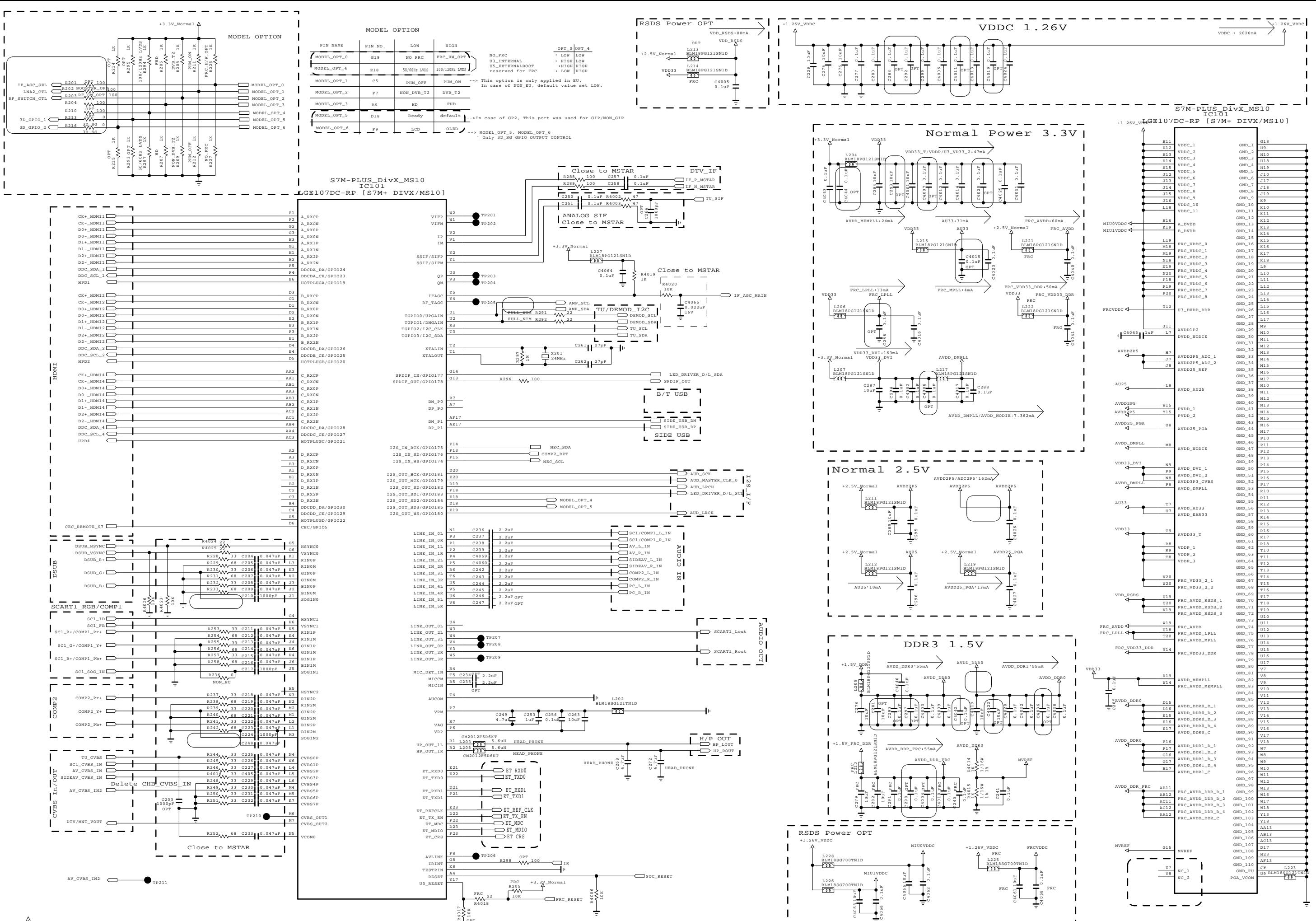


THE  SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION. FIRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IT IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE  SYMBOL MARK OF THE SCHEMATIC.

SECRET

LG ELECTRONICS

MODEL	GP3_Saturn7M	DATE	ver. 0.1
BLOCK	FLASH/EEPROM/GPIO	SHEET	1

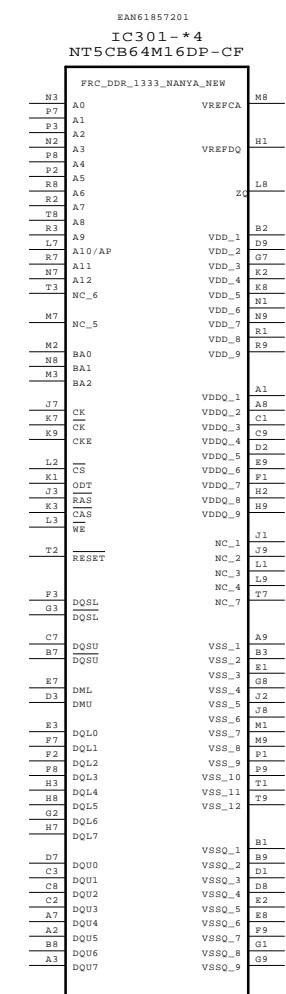
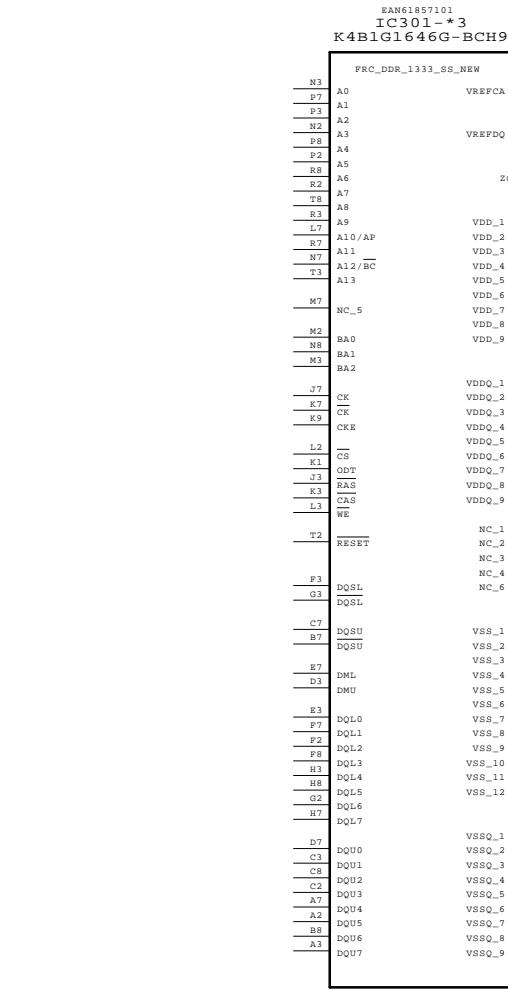
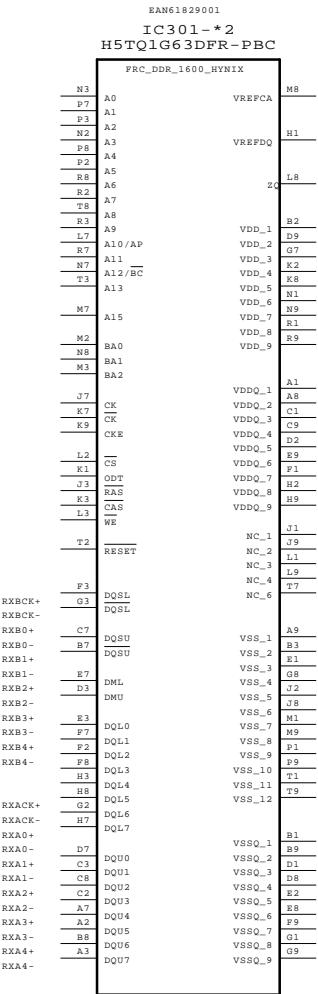
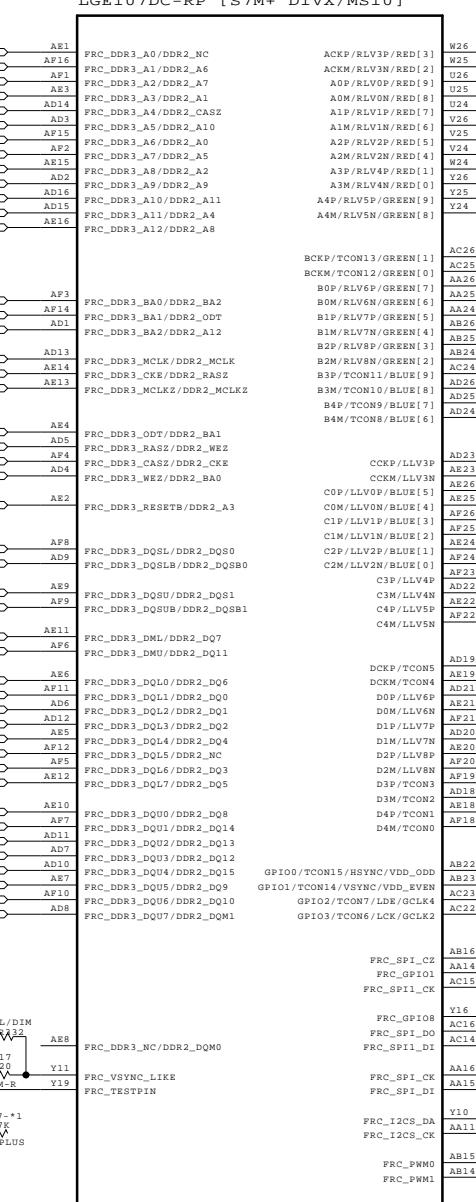
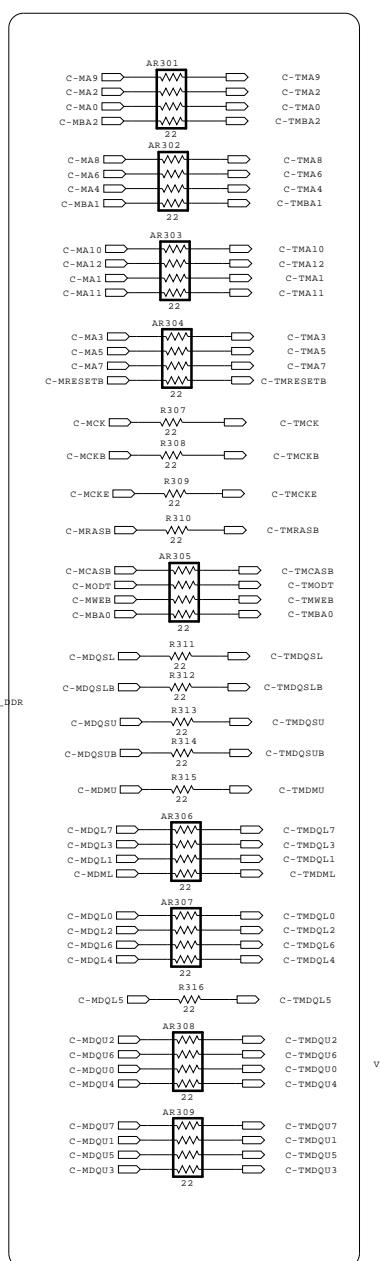
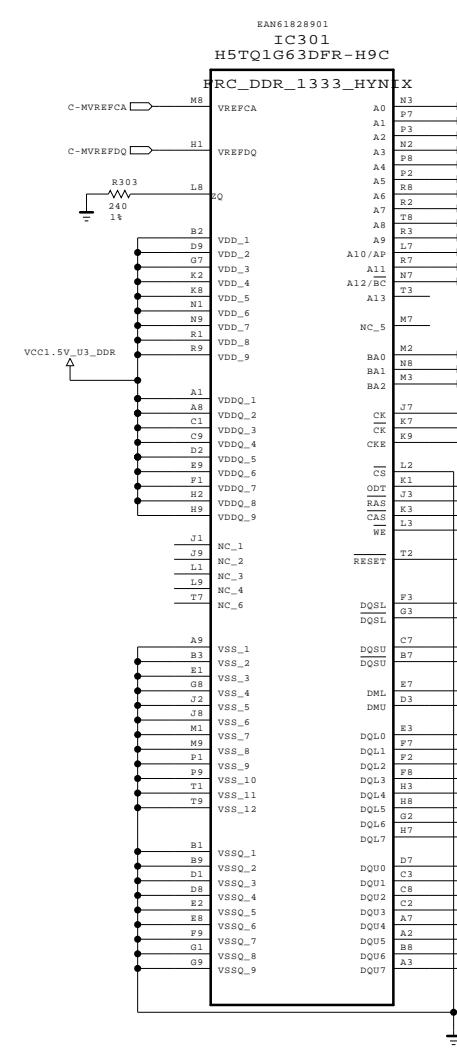
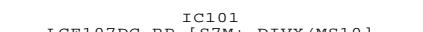
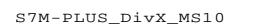
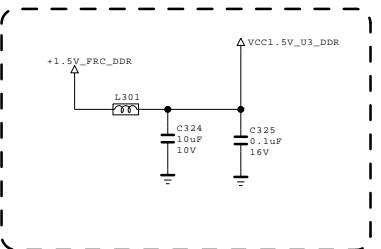
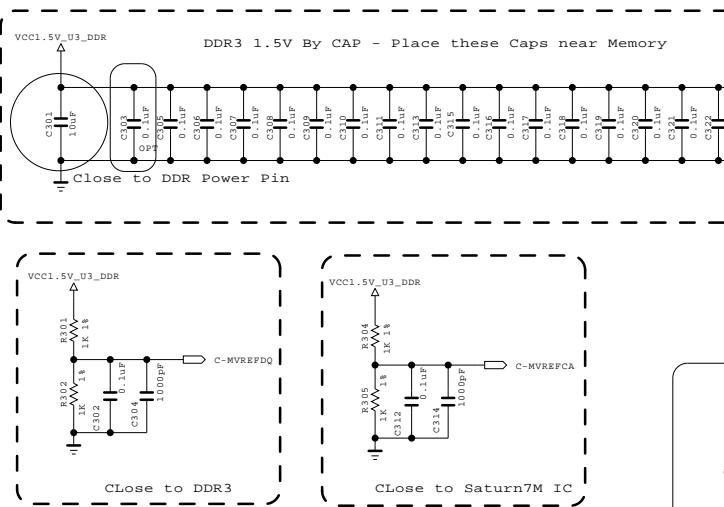


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SECRET

 LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	MAIN2, HW OPT	SHEET	2 /



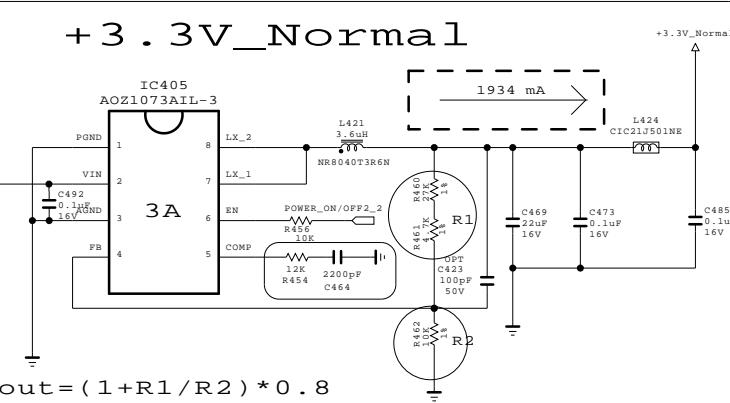
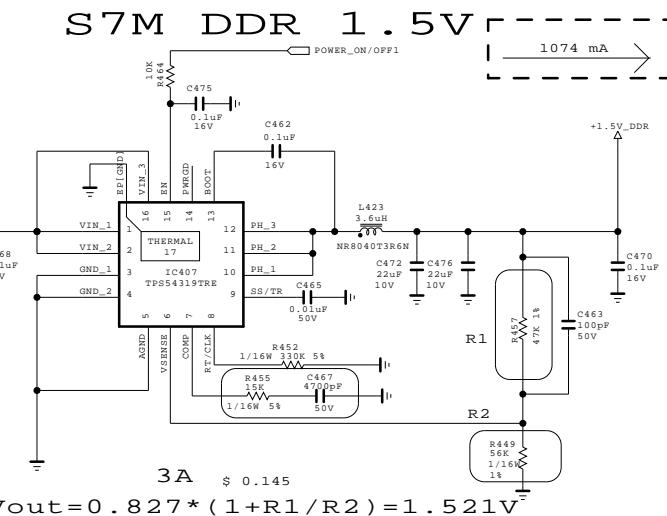
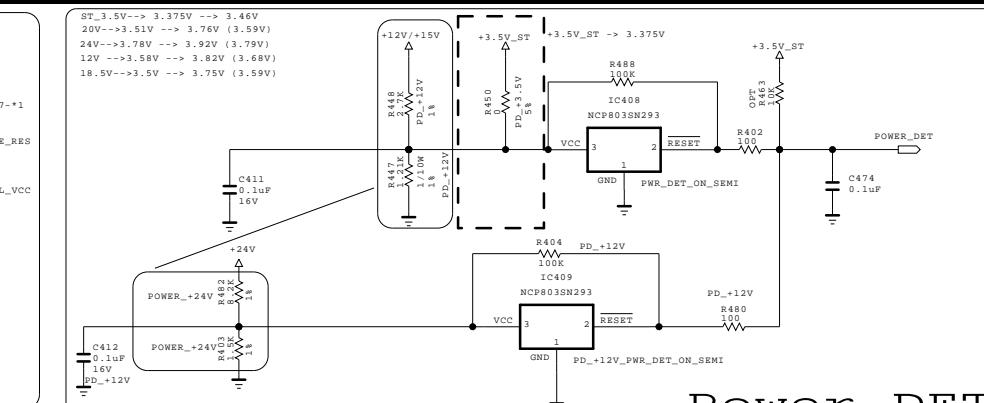
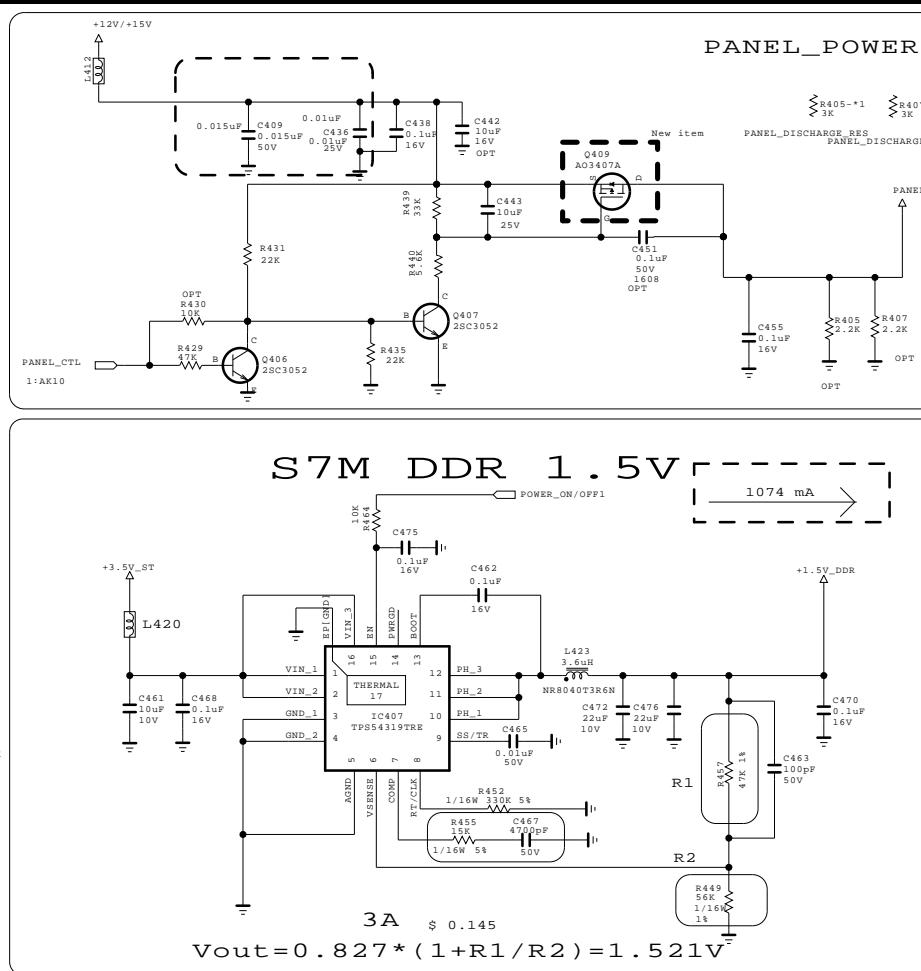
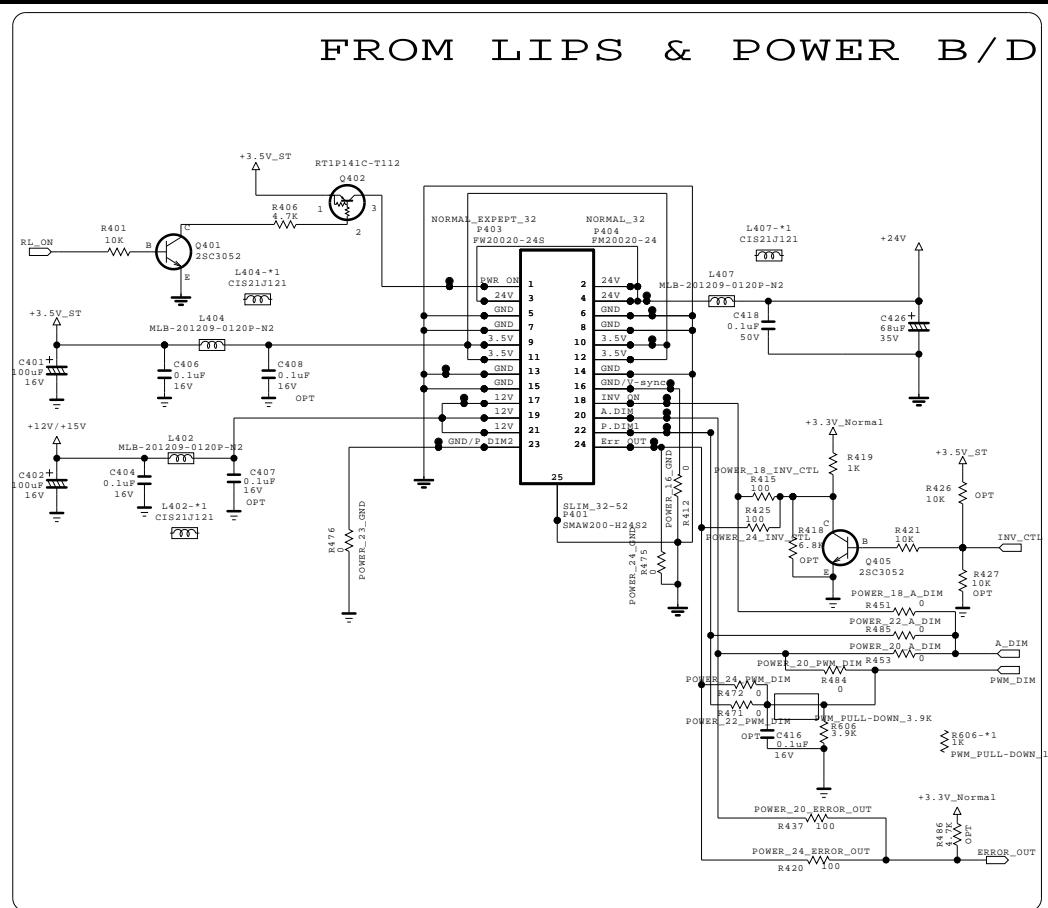
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SECRET

 LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	FRC_DDR	SHEET	3 /

# FROM LIPS & POWER B/D



## MODULE PIN MAP

PIN NO	LGD (PSU) or LIPS	CMO10*Lamp (PSU)	AUO 10*Lamp (PSU)	SHARP (PSU)	IPS-@ (PSU)
16	GND	GND	GND	GND	GND
18	INV_ON	A-DIM	INV_ON	INV_ON	INV_ON
20	VBR-A	NC	Err_out	5/60:ERROR 26/32ND:NC	Err_out
22	PWM_DIM	PWM_DIM	NC	26/32/52:PWM 60:NC	NC
24	Err_out	INV_ON	PWM_DIM	26/32/52:GND 60:PWM	PWM_DIM
23	GND	GND	GND	GND	GND

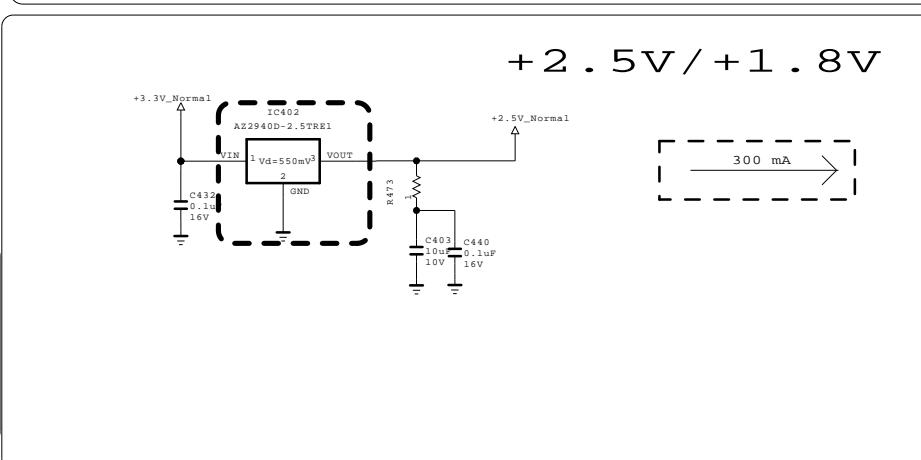
## LED MODULE PIN MAP -> latest update 20100618

PIN NO	LGD LPB OS LPB	32LE5300-TA CM010-LRD (PSU)	32LE5450-TA AUG 10-LRD (PSU)	32LE5300-TA LGD 10-LED (PSU)
16	NC	NC	NC	NC
18	INV_ON	INV_ON	INV_ON	INV_ON
20	NC	err_out	err_out	NC
22	PWM_DIM	NC	NC	PWM_DIM
24	err_out	--> NC	PWM_DIM	err_out --> NC
23	NC	NC	NC	NC

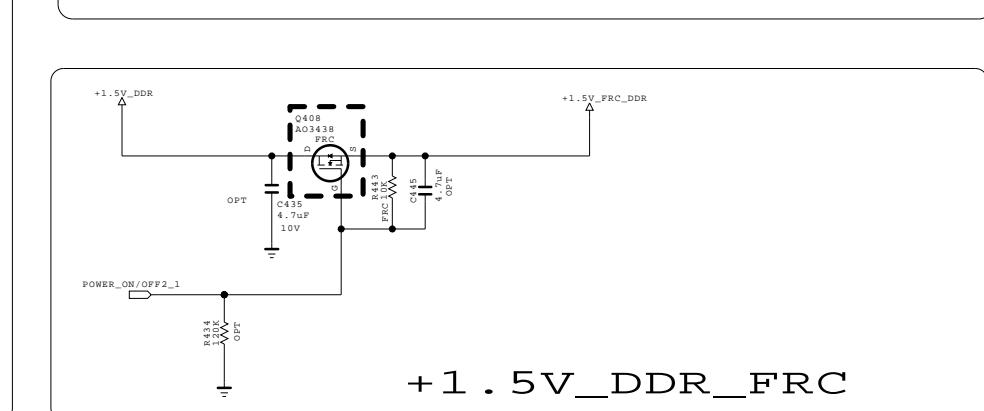
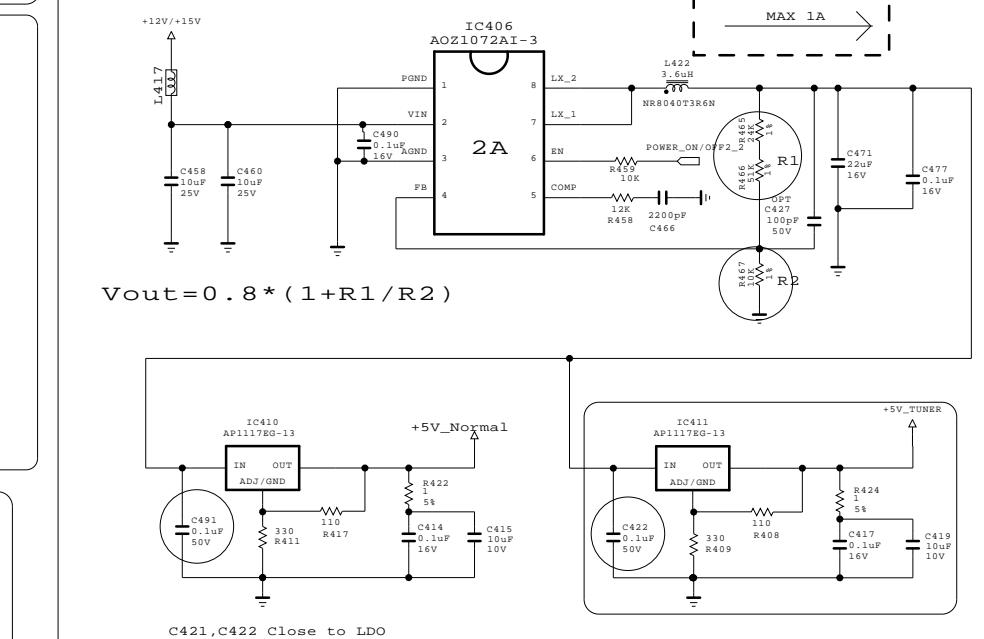
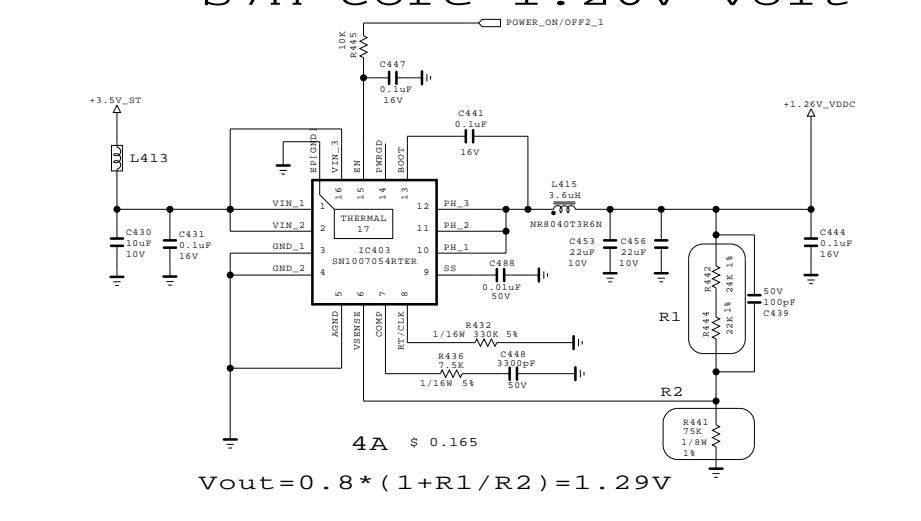
LGD edge led error-out use or not? checking is necessary...

## <Module Inv to Main Pin Connection>

INV <--> MAIN  
#11 <--> #24  
#12 <--> #18  
#13 <--> #20  
#14 <--> #22



## S7M core 1.26V volt

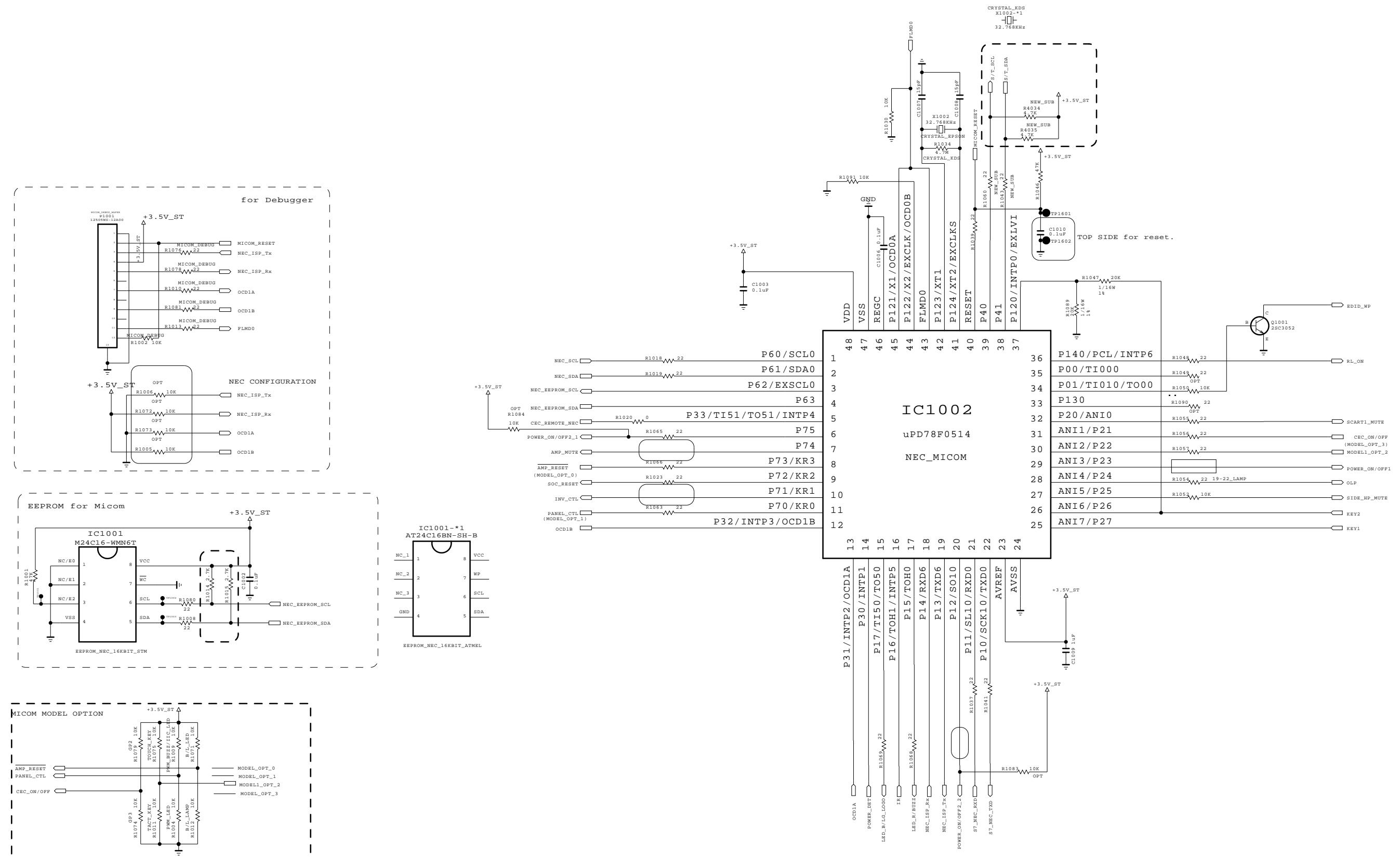


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LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	POWER_LARGE	SHEET	4



2011Y, GP2R, 101125 Update

MODEL OPTION			
PIN NAME	PIN NO.	HIGH	LOW
ODEL_OPT_0	8	B/L_LED	B/L_LED
ODEL_OPT_1	11	PWM_BUZZ_IIC_LED	PWM_BUZZ_IIC_LED
ODEL_OPT_2	30	TOUCH_KEY	TACT
ODEL_OPT_3	31	GP2	GP

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SECRET



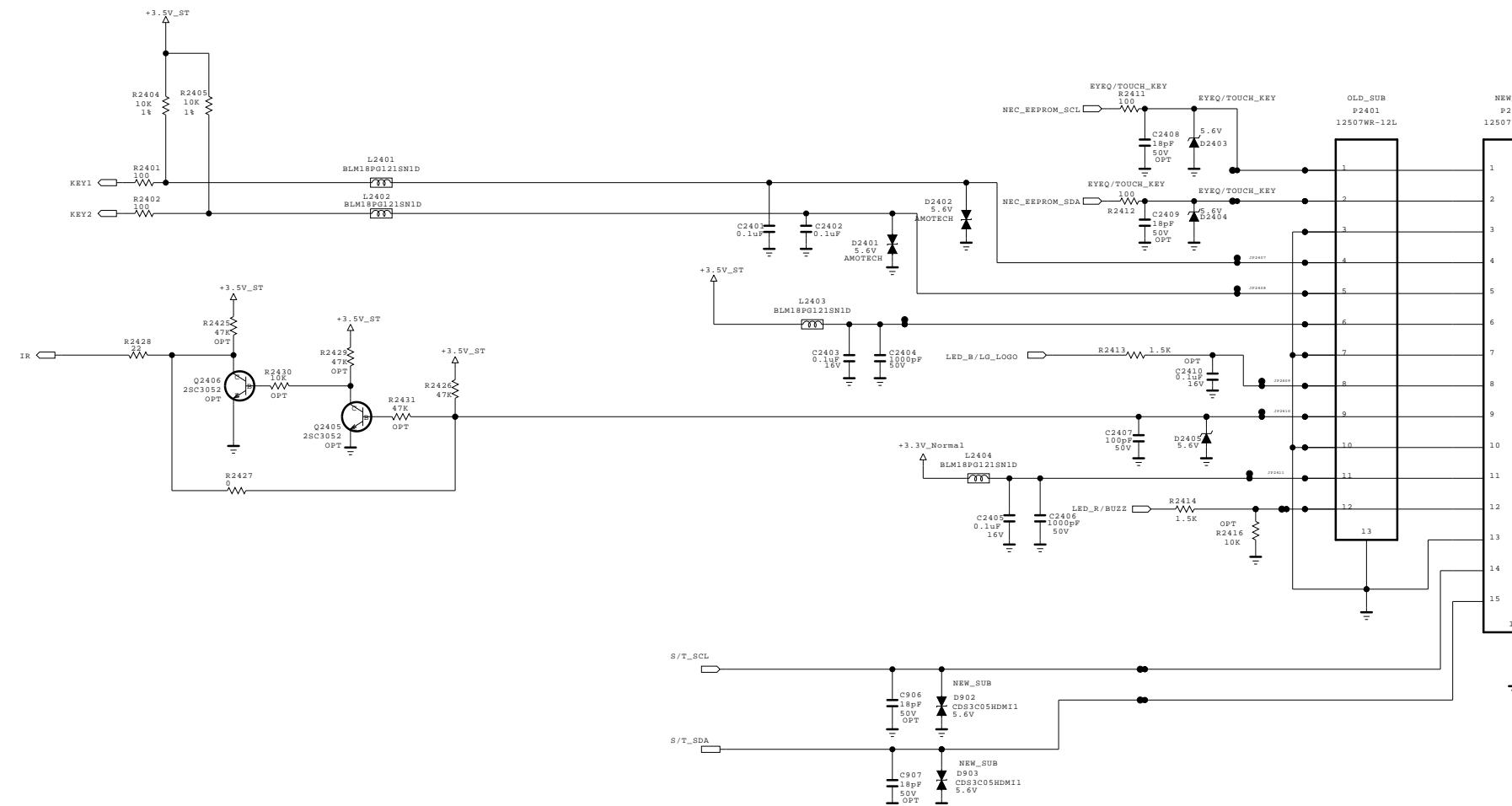
2010Y, GP2

MODEL_OPT_0	MODEL_OPT_1	MODEL_OPT_2	MODEL_OPT_3	Description
LOW	LOW	LOW	LOW	LK330/LK430 for KR/US 10V EVB-Q Sensor KEY & PWM LED & No Buzz & No LED B
LOW	LOW	LOW	HIGH	LK330/LK430/LK530 KEY & PWM LED & No Buzz & No LED B
LOW : LED HIGH : LAMP	HIGH	HIGH	LOW	LV25/LV35/LV45/LW45/LV55/LK45/L S/T & IIC LED & NO BUZZ & LED Bl
		HIGH	LOW	TBD IIC LED (09V IIC Protocol) & No BUZZ
		Low	HIGH	TBD S/T & IIC LED & No Buzz & LED Bl

MODEL_OPT_0	MODEL_OPT_1	MODEL_OPT_2	MODEL_OPT_3	
LOW	LOW	LOW	LOW	LD350/450/550 PWm LED & No Buzz & No LED Blink
HIGH	LOW	HIGH	LOW	19/22/26LE5300/5300 IIC LED & PWm IIC BUZZ
HIGH	HIGH	HIGH	LOW	32/37/42/47/55LE5300 IIC LED & PWm BUZZ
LOW	HIGH	LOW	LOW	IIC LED (09Y IIC Protocol) & NO BUZZ LD420
IC	HIGH	LOW	LOW	LET3700 GPIO LED & NO BUZZ

MODEL	GP2R	DATE	20101125
BLOCK	MICOM Rev. 4	SHEET	5 /

CONTROL  
IR & LED

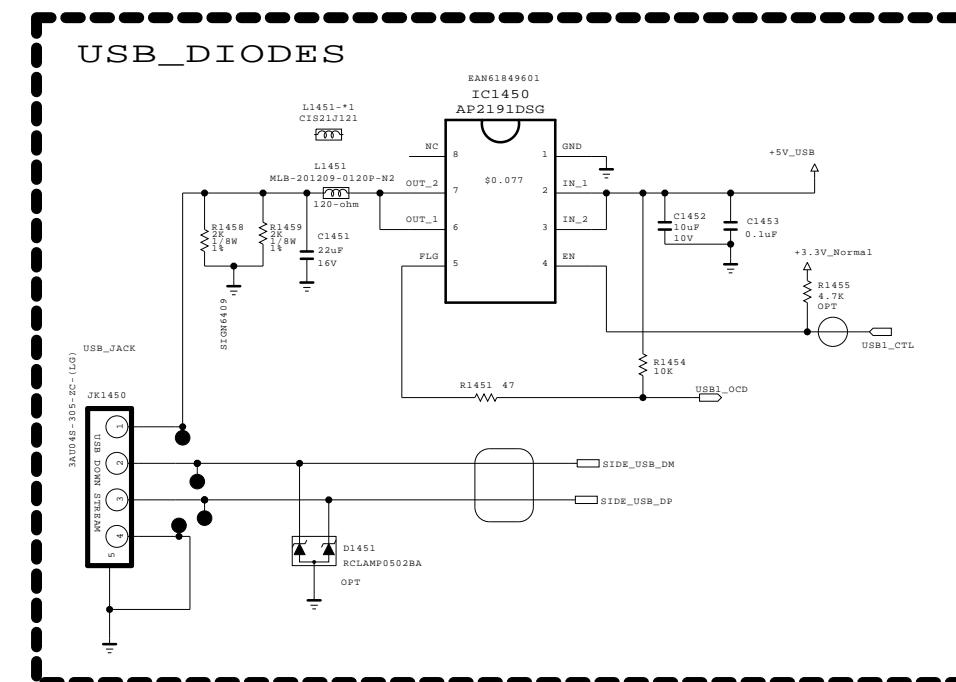


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LG Electronics

LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	IR / CONTROL - L	SHEET	6

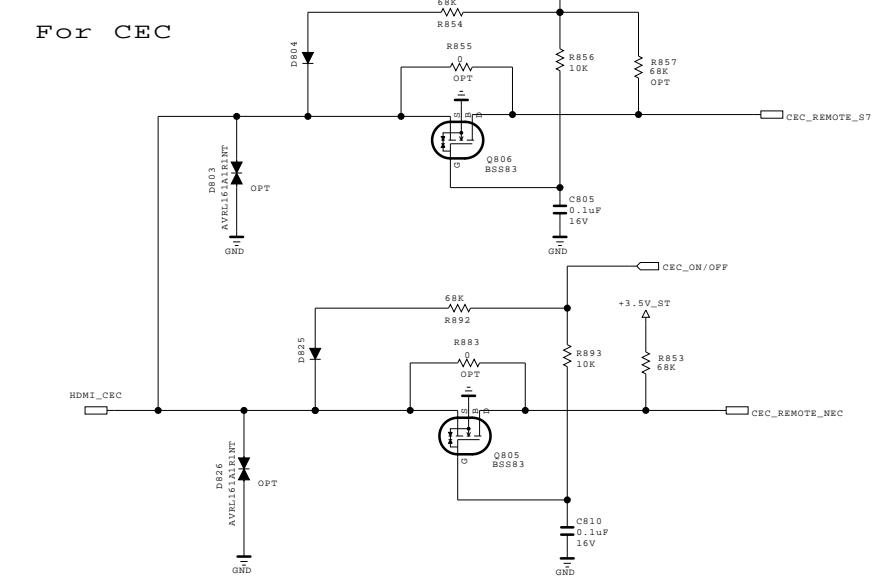
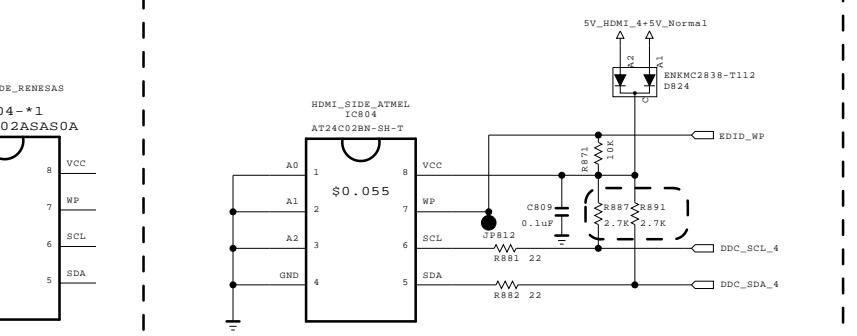
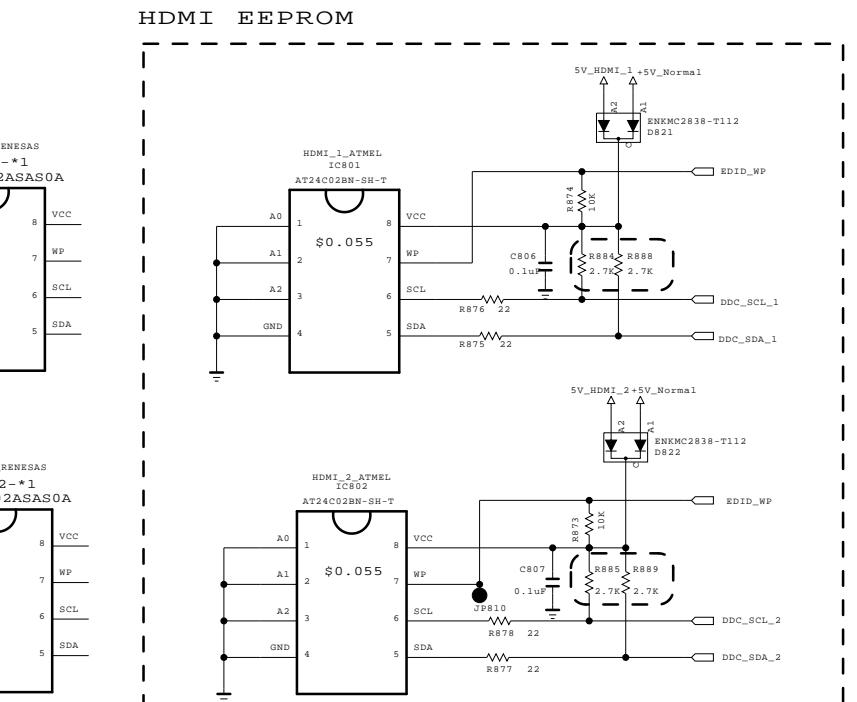
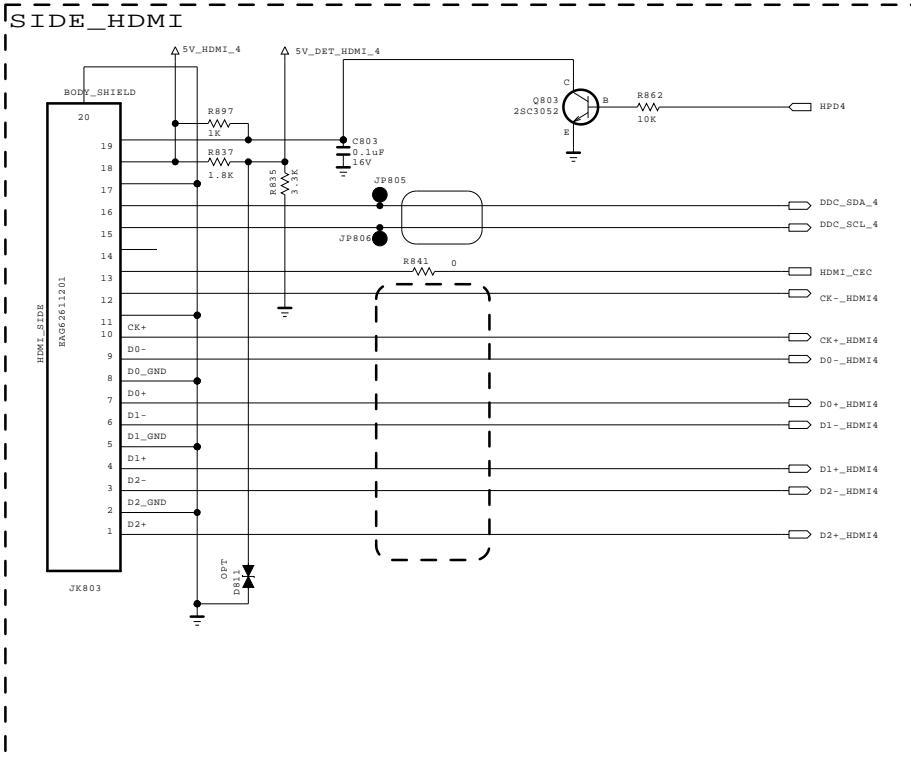
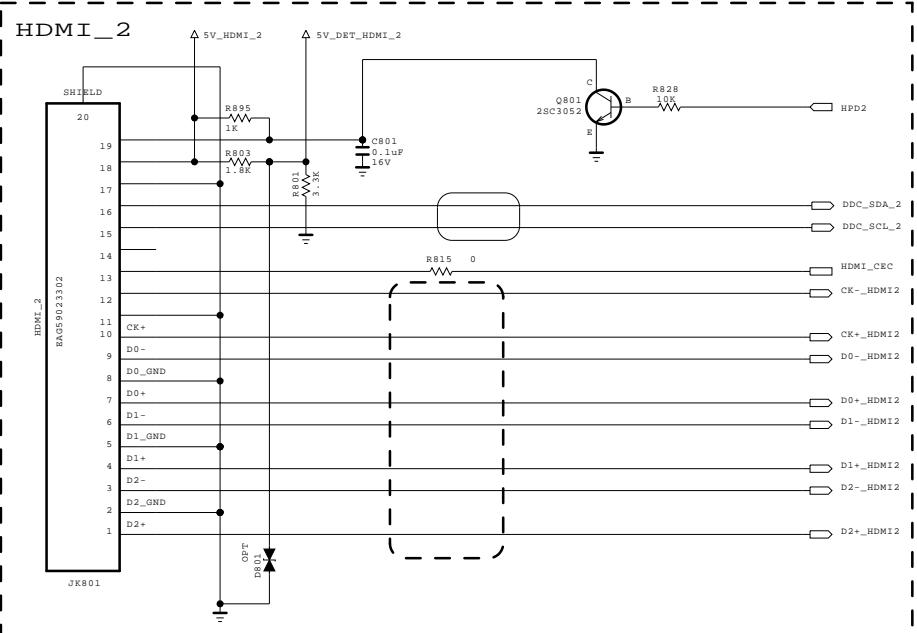
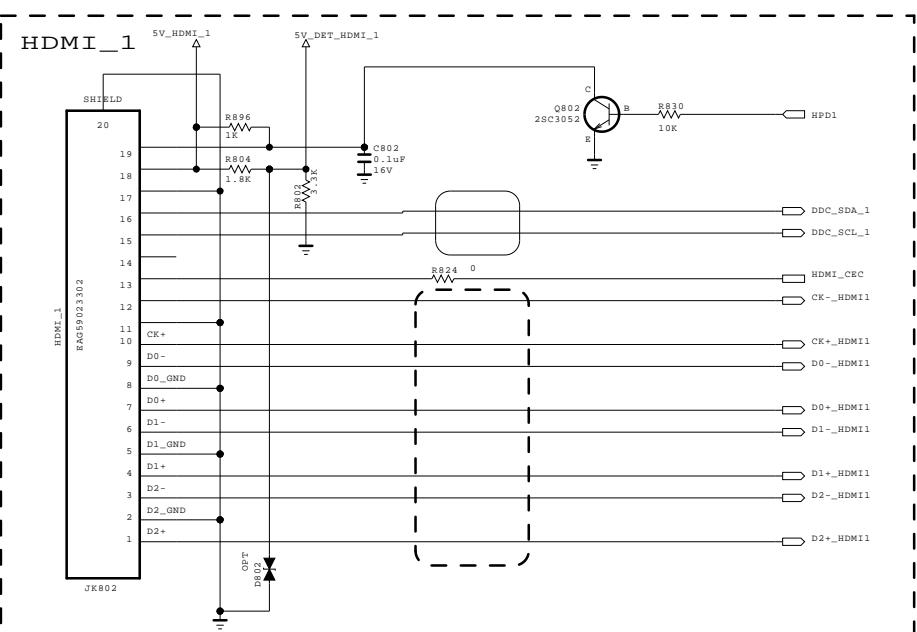


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LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	USB_OCP_DIODE	SHEET	7



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SECRET

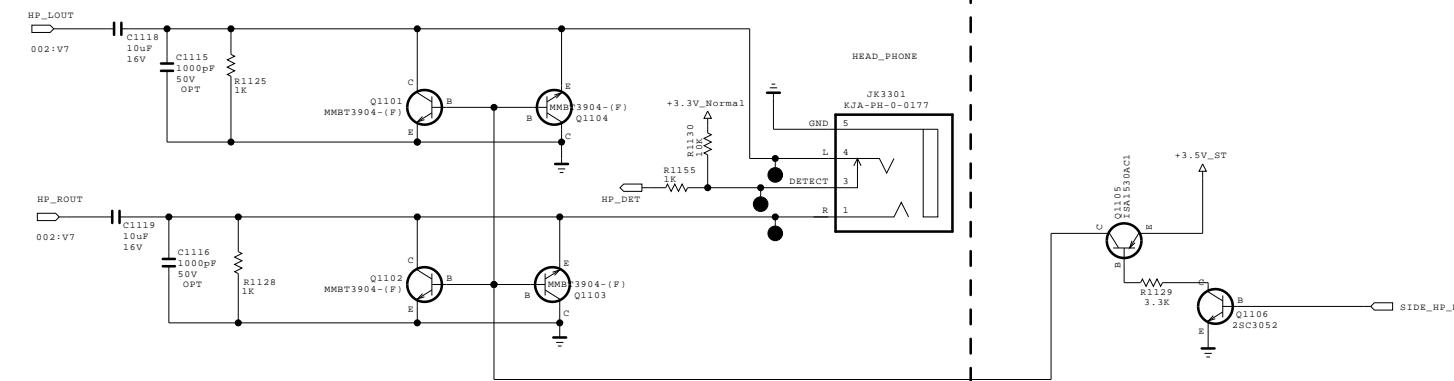


MODEL	GP2R	DATE	20101023
BLOCK	HDMI	SHEET	8 /

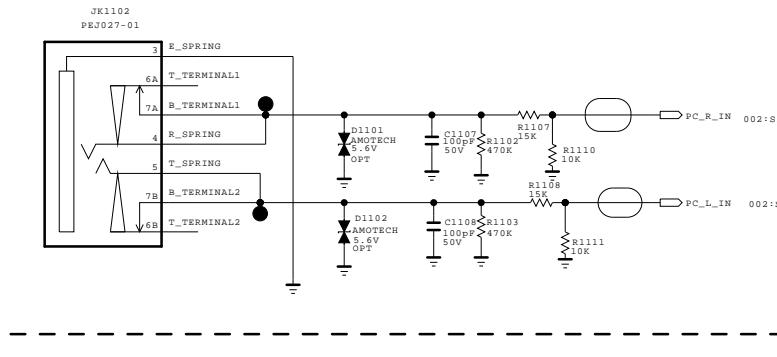
# RGB / SPDIF / PC / HP

## New Item Development

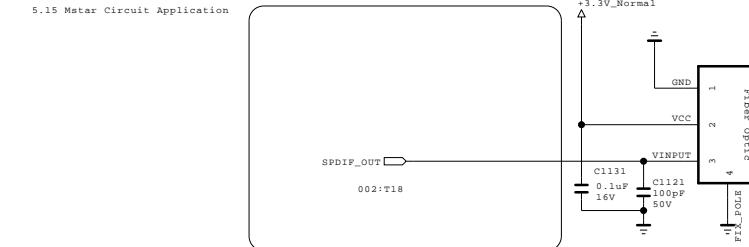
## EARPHONE BLOCK



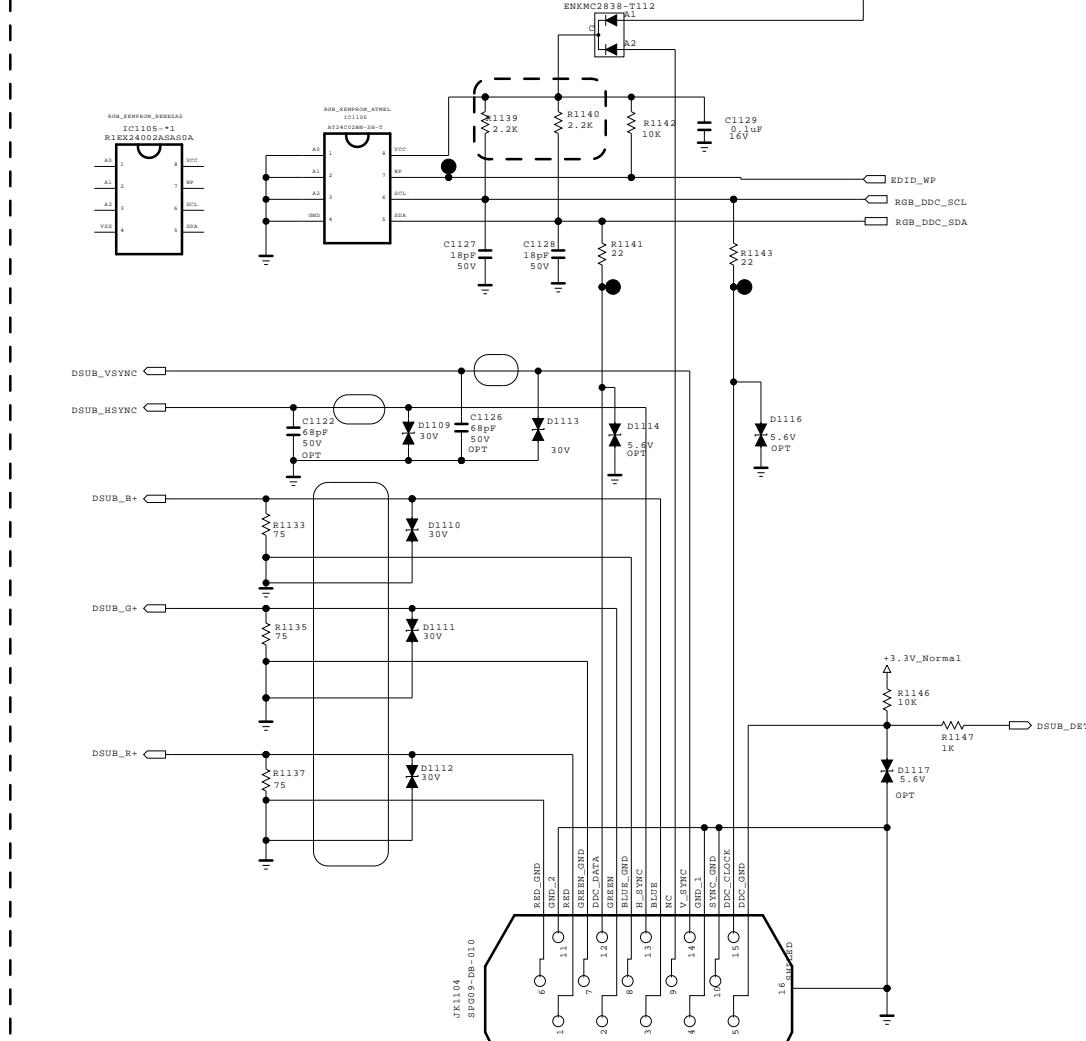
PC AUDIO



SPDIF OPTIC JAC



RGB

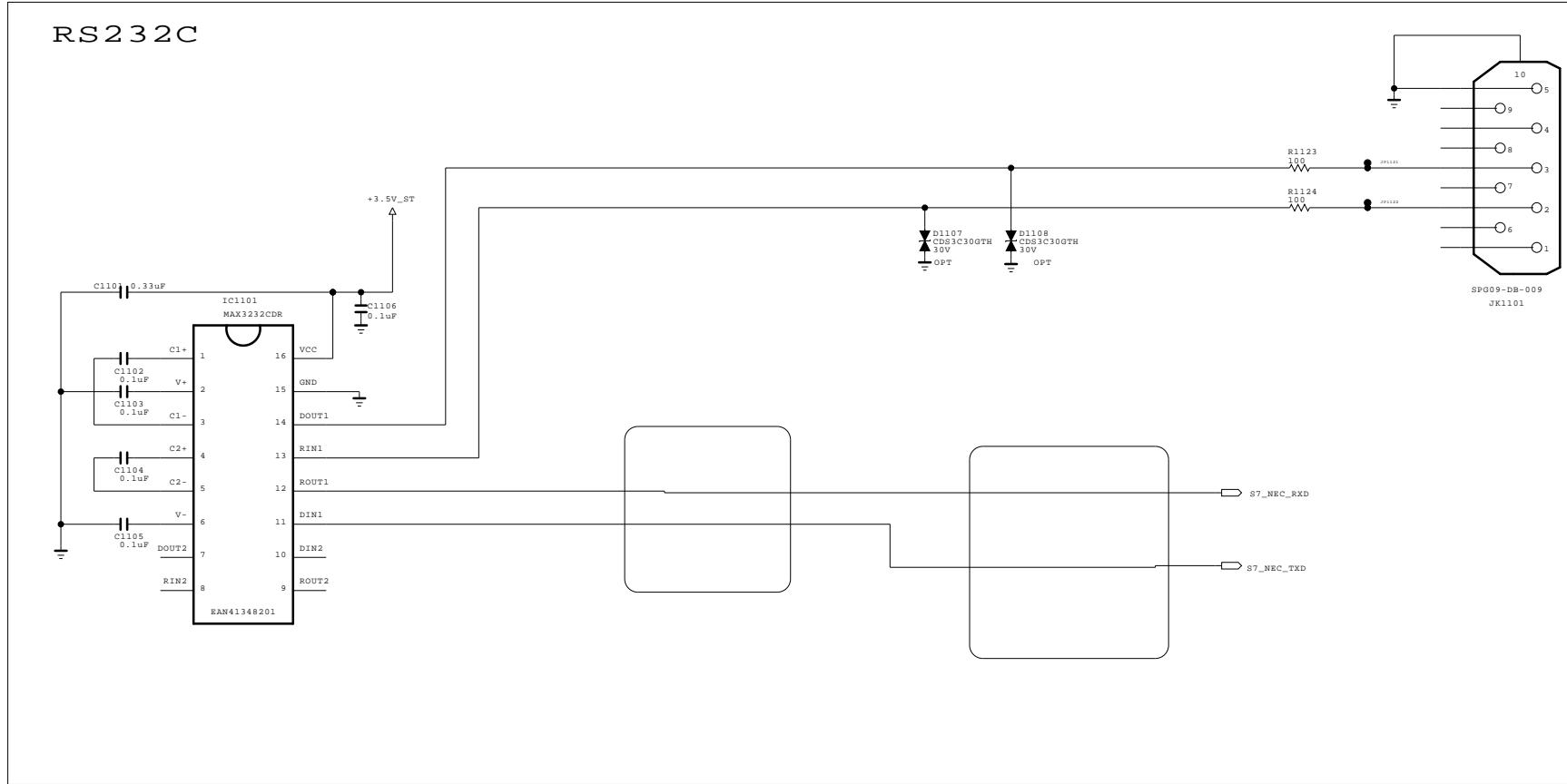


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SECRET



MODEL	GP2R	DATE	20101023
BLOCK	RGB / SPDIF / HP	SHEET	9 /



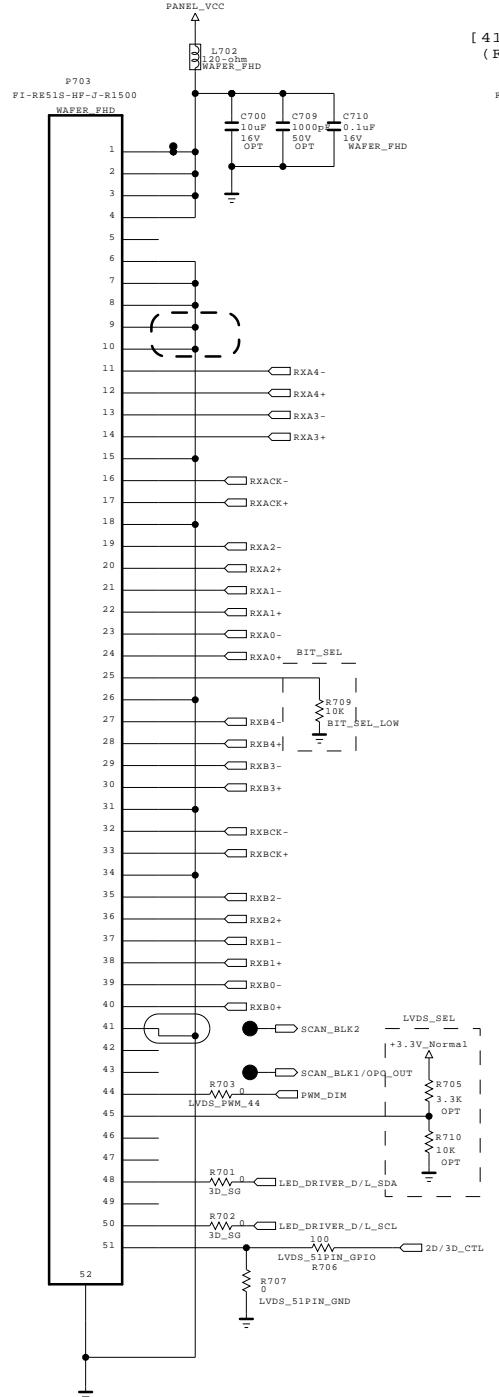
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**SECRET**  
LG Electronics

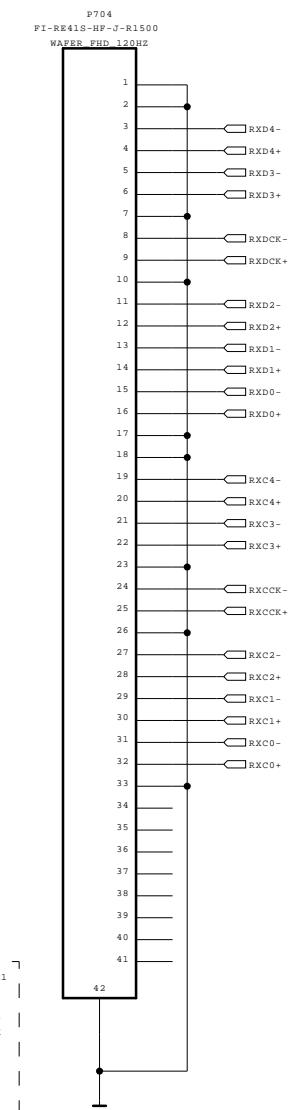
 LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	RS232C_9PIN	SHEET	10

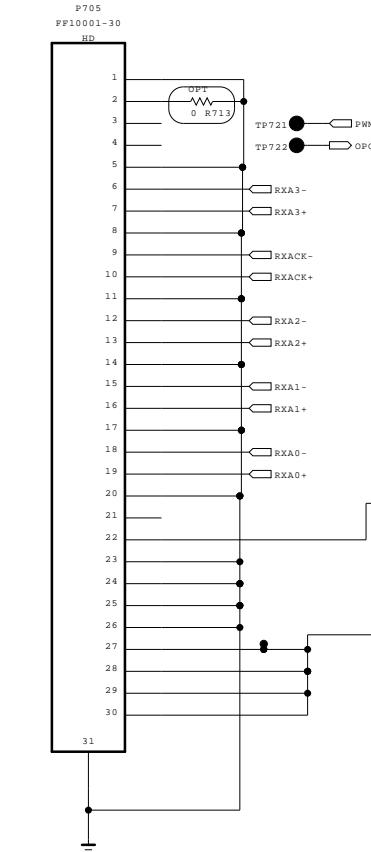
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(For FHD 60/120Hz)



[41Pin LVDS Connector]  
(For FHD 120Hz)



[30Pin LVDS Connector]  
(For HD 60Hz\_Normal)

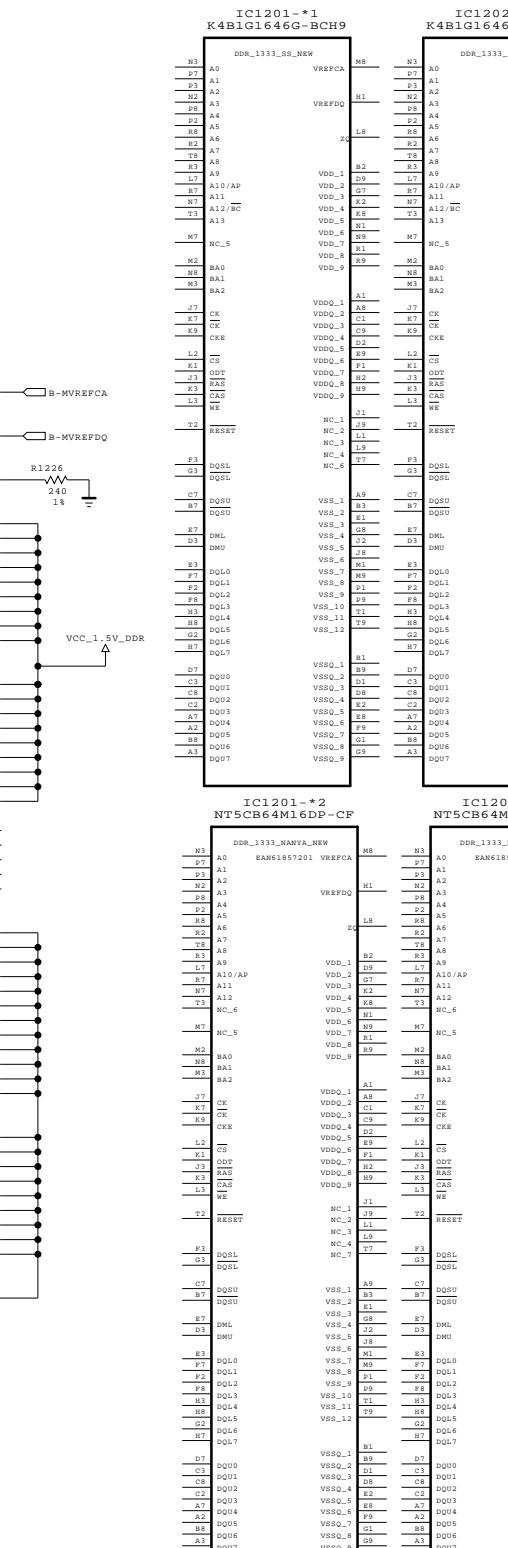
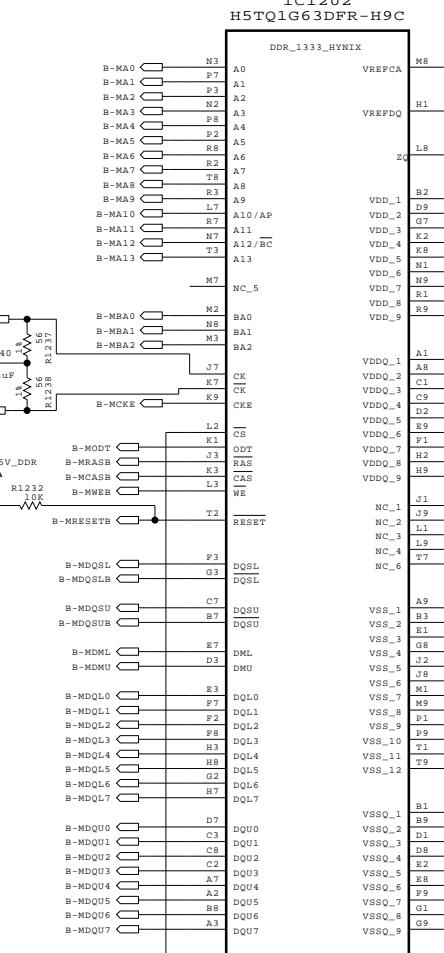
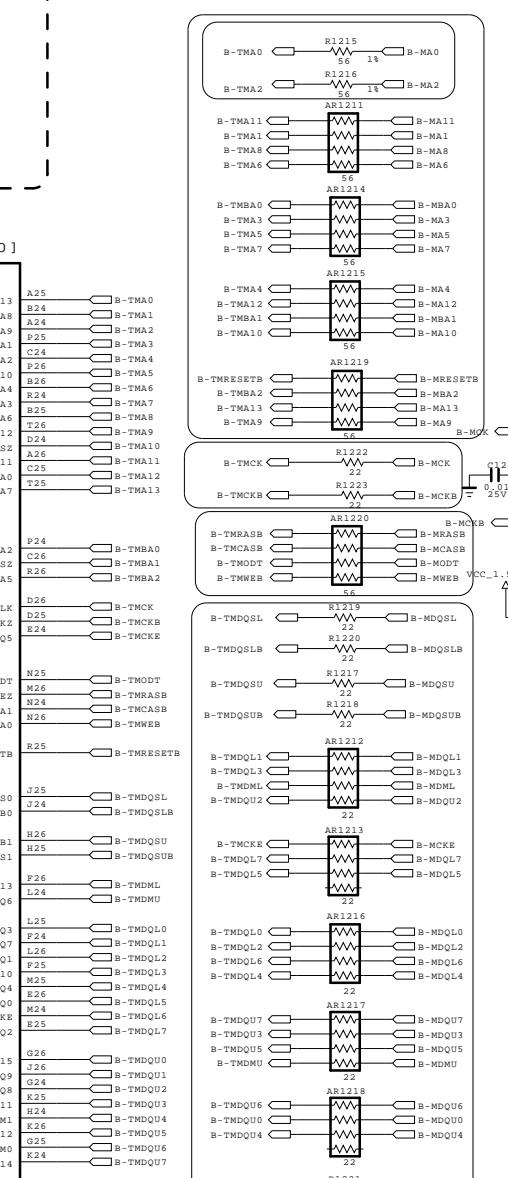
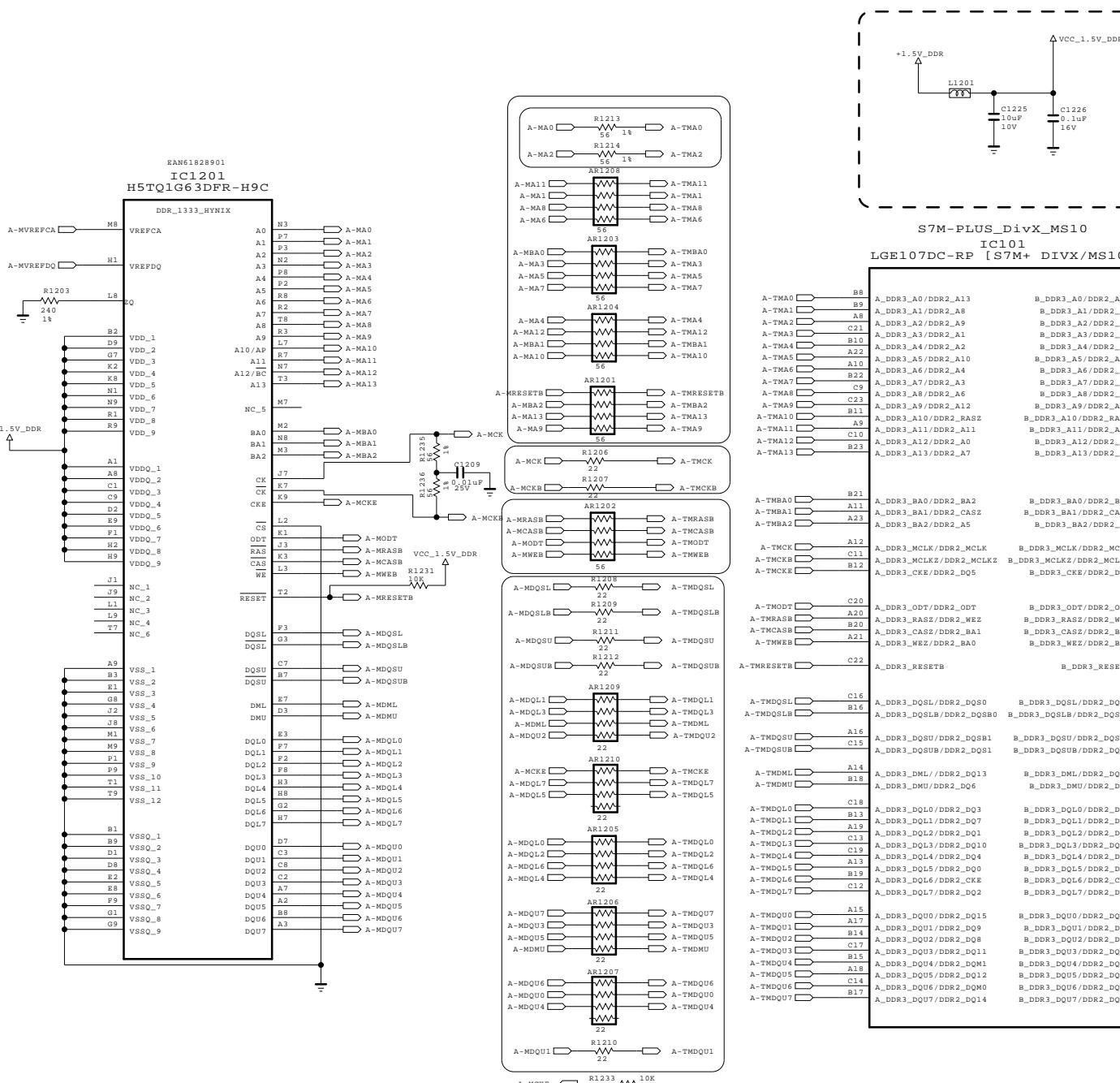
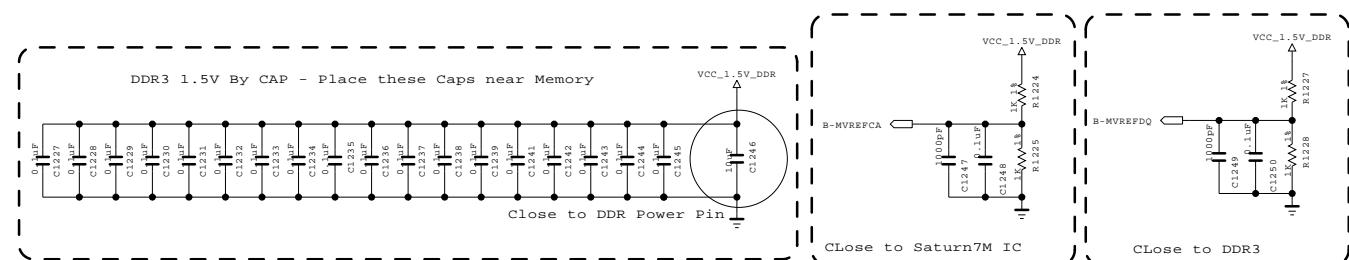
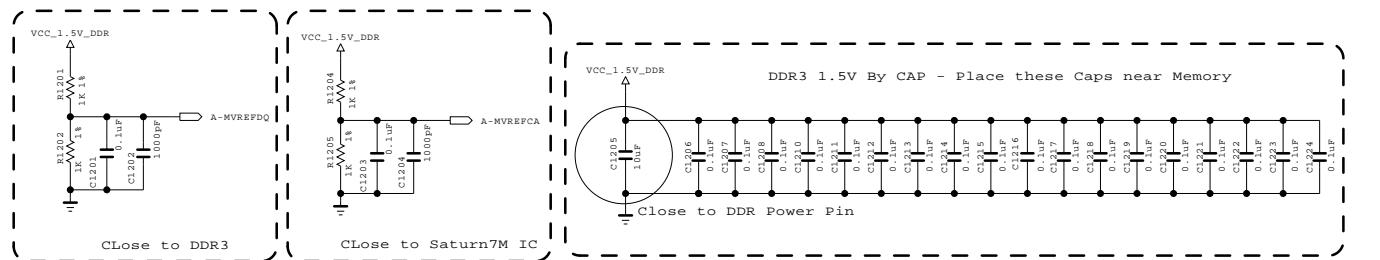


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**SECRET**  
LG Electronics

LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	LVDS_LARGE	SHEET	11

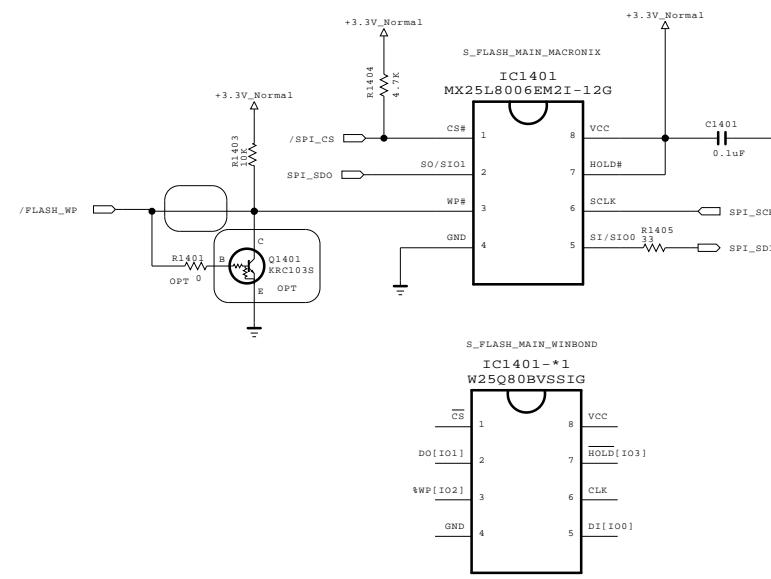


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SECRET



MODEL	GP2R	DATE	20101023
BLOCK	DDR_256	SHEET	12 /



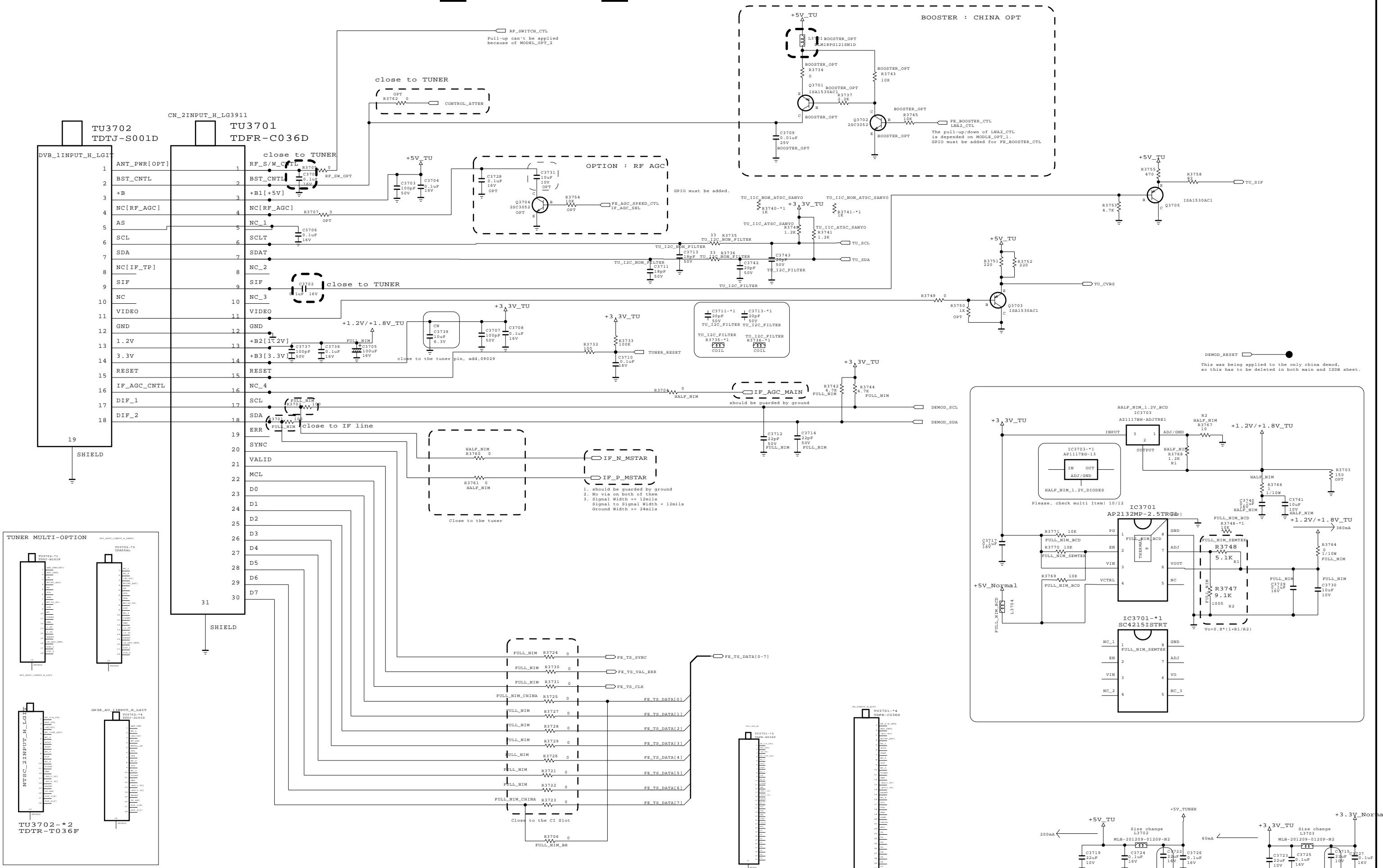
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LG Electronics

LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	SFLASH 1MB	SHEET	13

# GP2R\_LARGE\_TUNER

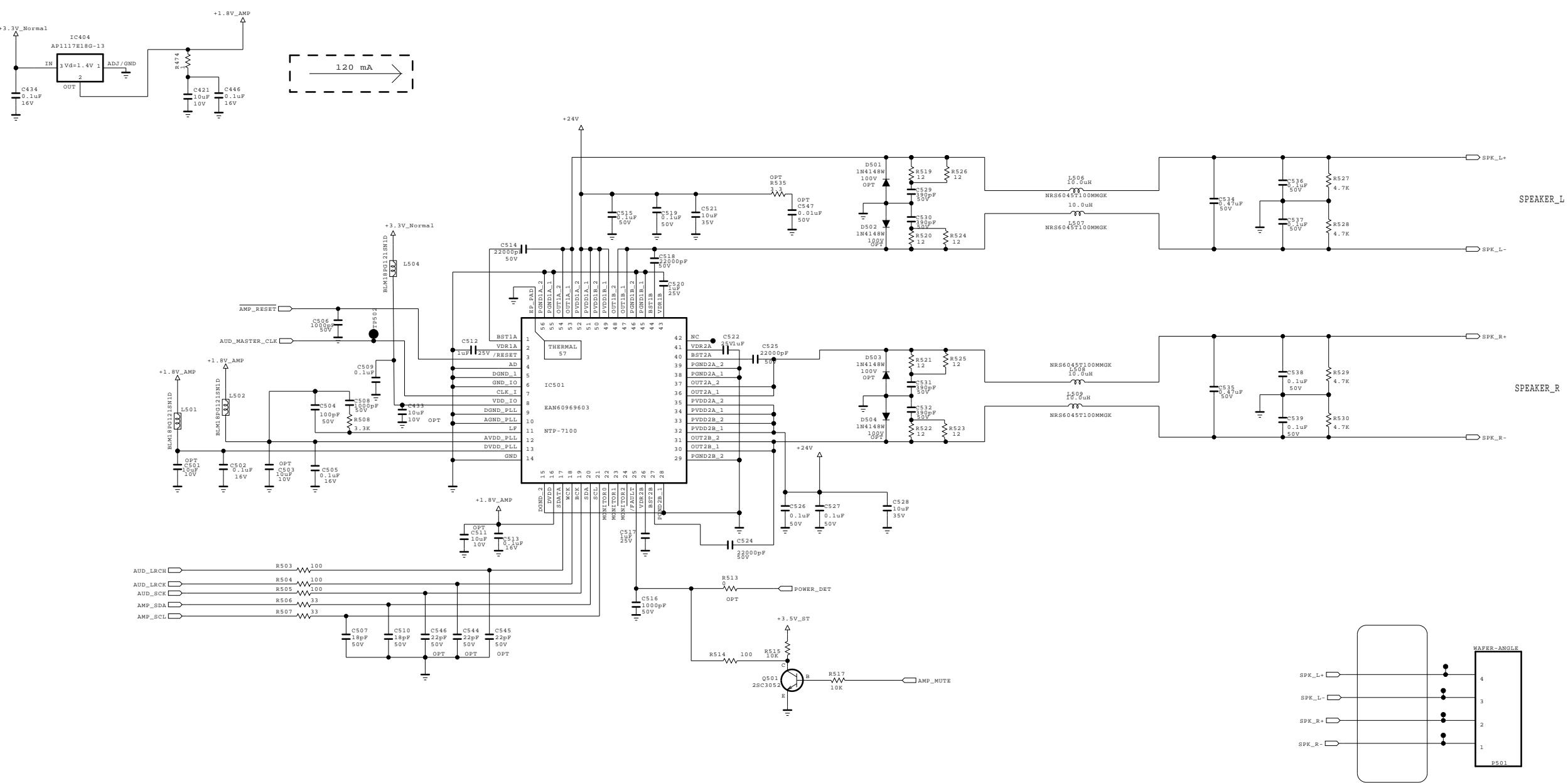


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SECRET



MODEL	GP2R	DATE	20101023
BLOCK	TUNER L	SHEET	14 /

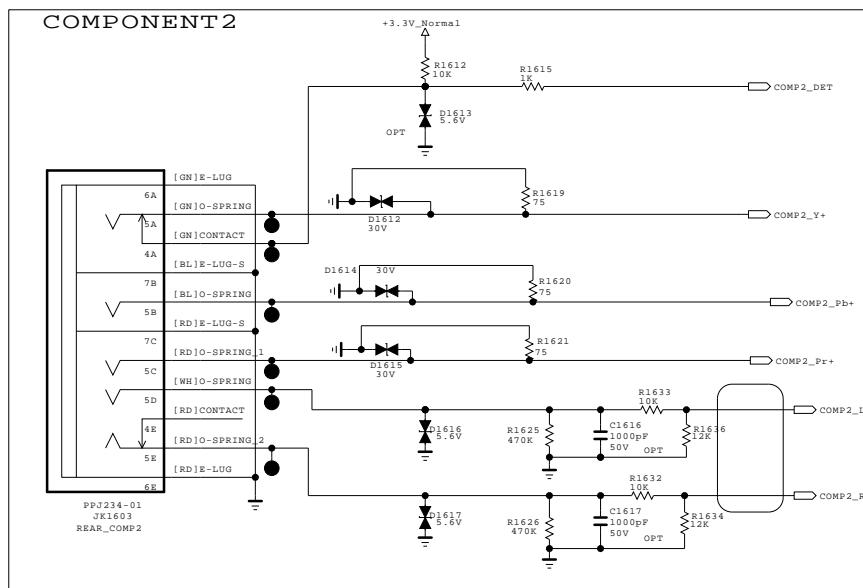
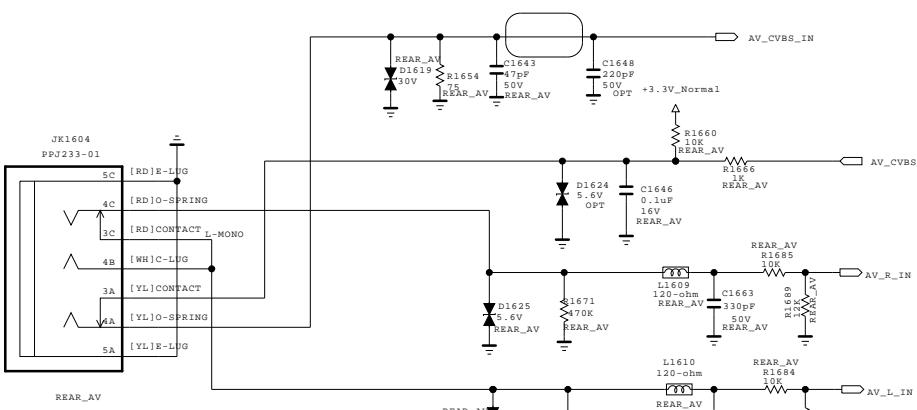


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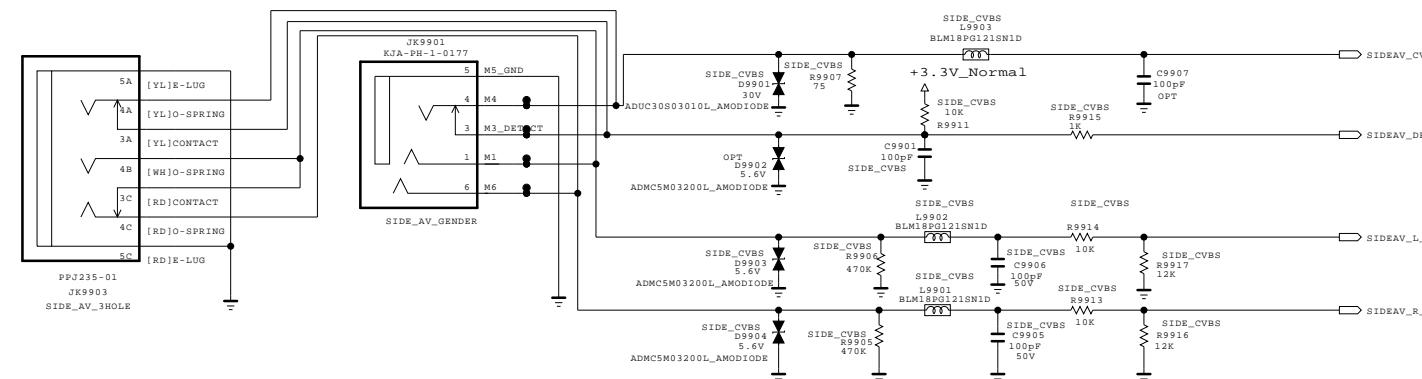
SECRET  
LG Electronics

LG ELECTRONICS

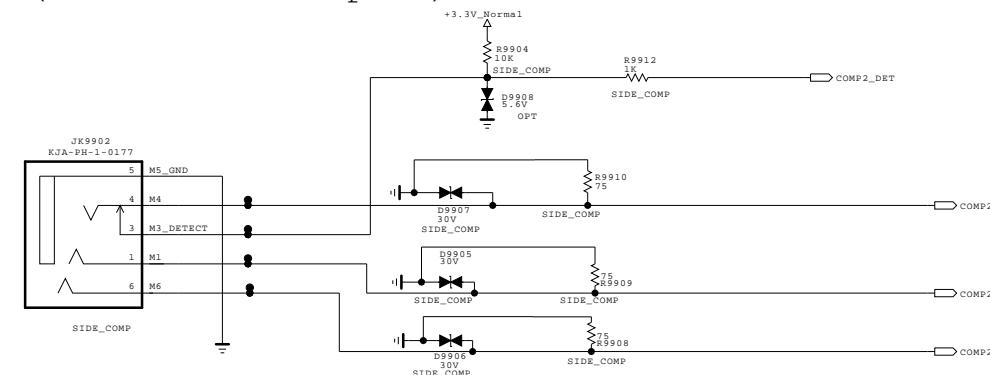
MODEL	GP2R	DATE	20101023
BLOCK	AMP_NTP	SHEET	16



SIDE CVBS PHONE JACK  
(New Item Development)



SIDE COMPONENT PHONE JACK  
(New Item Development)



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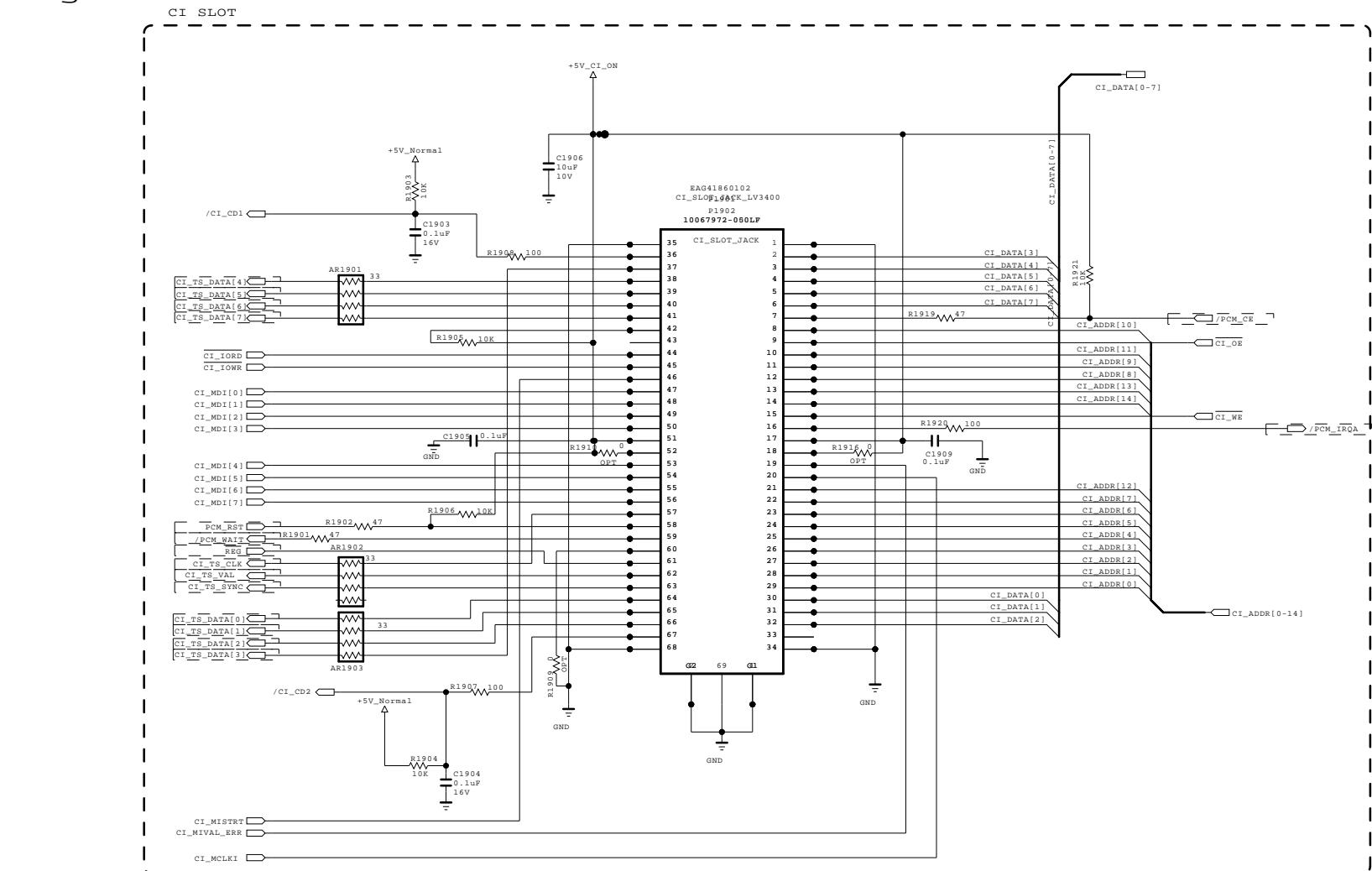
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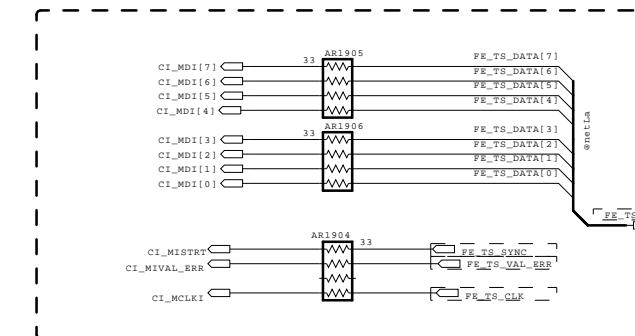
MODEL	GP2R	DATE	20101023
BLOCK	SIDE_JACK	SHEET	18 /

\* Option name of this page : CI\_SLOT  
(because of Hong Kong)

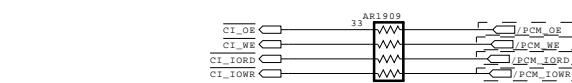
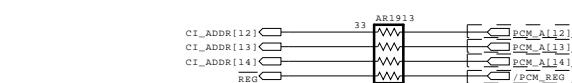
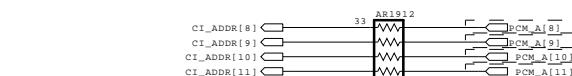
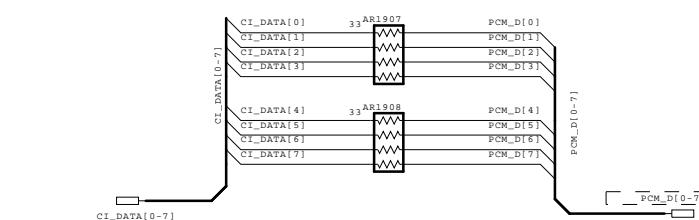
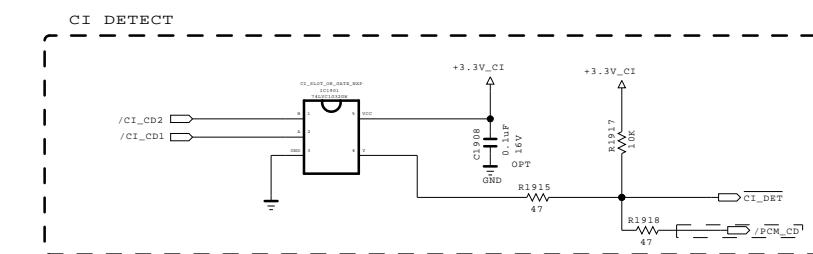
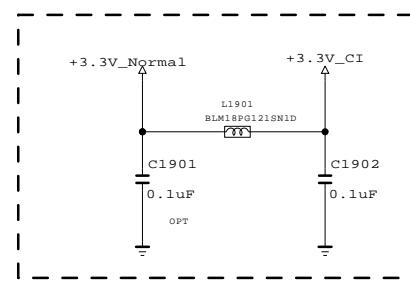
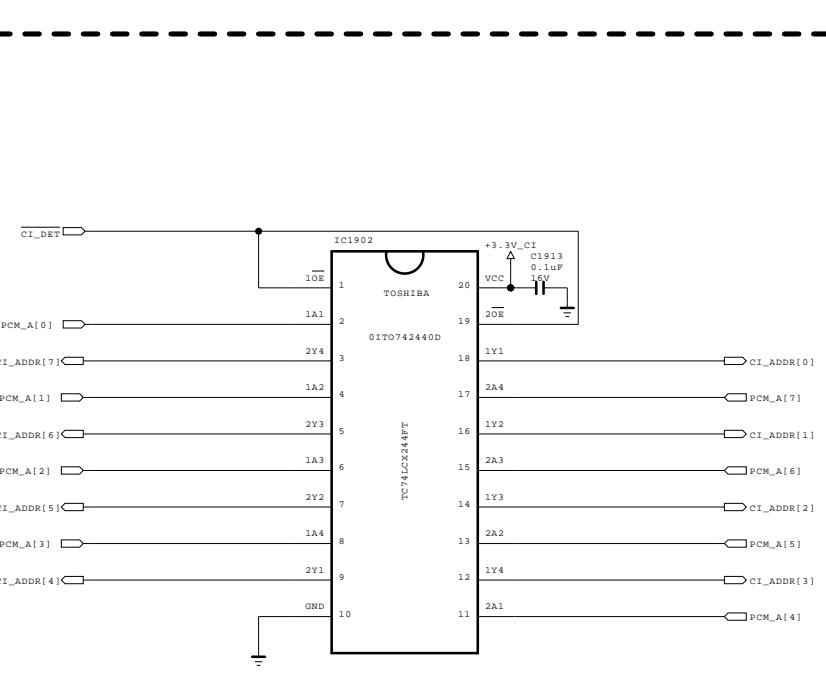
## CI Region



## CI TS INPUT



## CI HOST I/F



THE SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION, FIRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE SYMBOL MARK OF THE SCHEMATIC.

SECRET  
LG Electronics

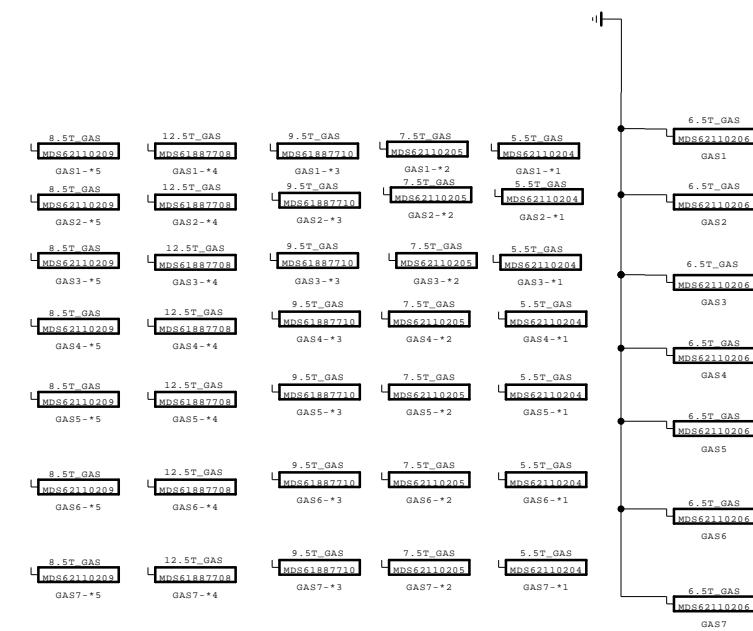
LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	PCMCII	SHEET	20

THE  SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES  
SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION,  
FIRE AND ELECTRICAL SHOCK HAZARDS. WHEN SERVICING IF IS  
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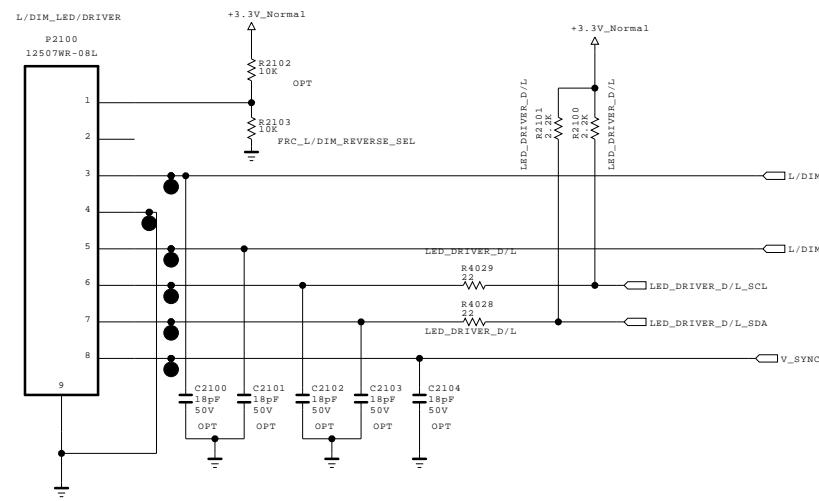
**SECRET**  
LG Electronics

## SMD GASKET



MODEL	GP2R	DATE	20101023
BLOCK	SMD_GAS	SHEET	20

LG ELECTRONICS



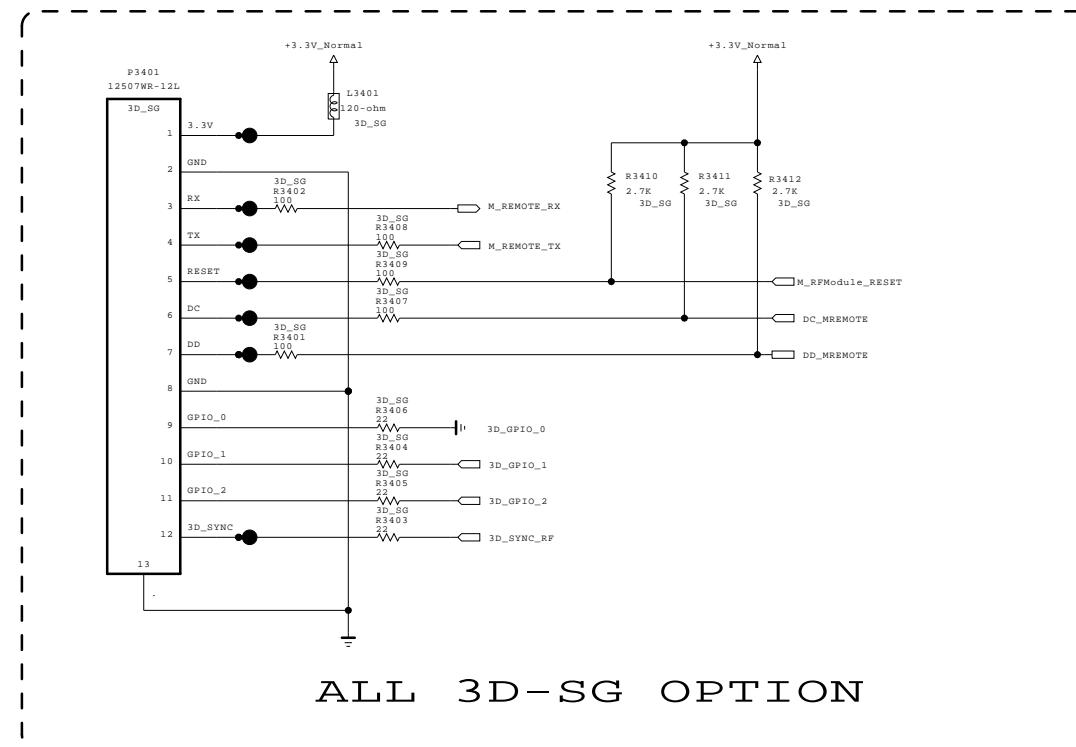
THE  SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION, FIRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IT IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE  SYMBOL MARK OF THE SCHEMATIC.

SECRET  
LG Electronics

 LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	L/DIM_LED	SHEET	21

## TI solution RF-3D OPTION



FREQ.	GPOIO_0	GPOIO_1	GPOIO_2
3D Off	0	0	0
60Hz	0	0	1
59.94Hz	0	1	0
50Hz	0	1	1
RESERVED	1	0	0
RESERVED	1	0	1
RESERVED	1	1	0
RESERVED	1	1	1

THE SYMBOL MARK OF THIS SCHEMATIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION, FIRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IT IS ESSENTIAL THAT ONLY MANUFACTURES SPECIFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE SYMBOL MARK OF THE SCHEMATIC.

SECRET  
LG Electronics

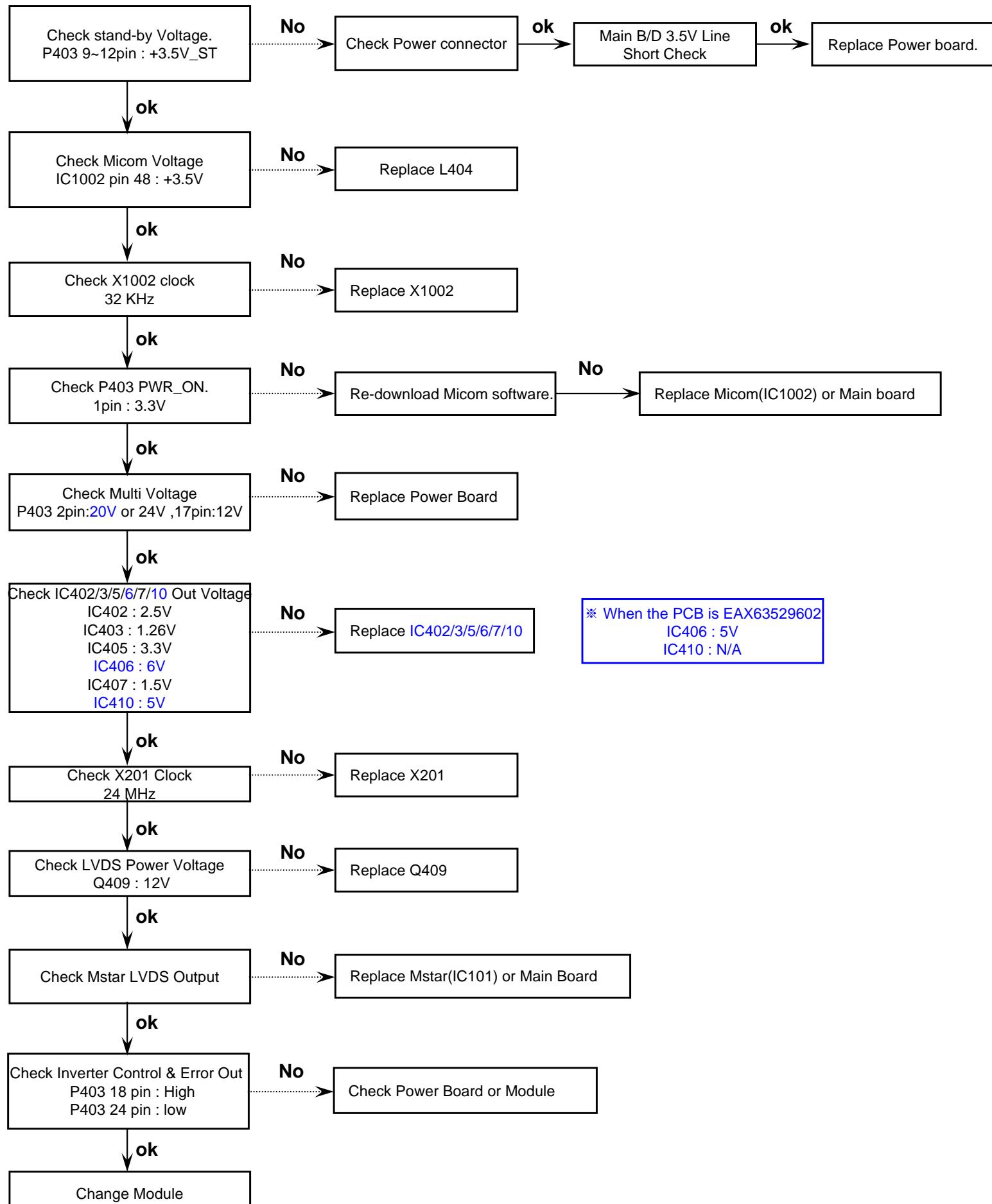
LG ELECTRONICS

MODEL	DATE
BLOCK	SHEET



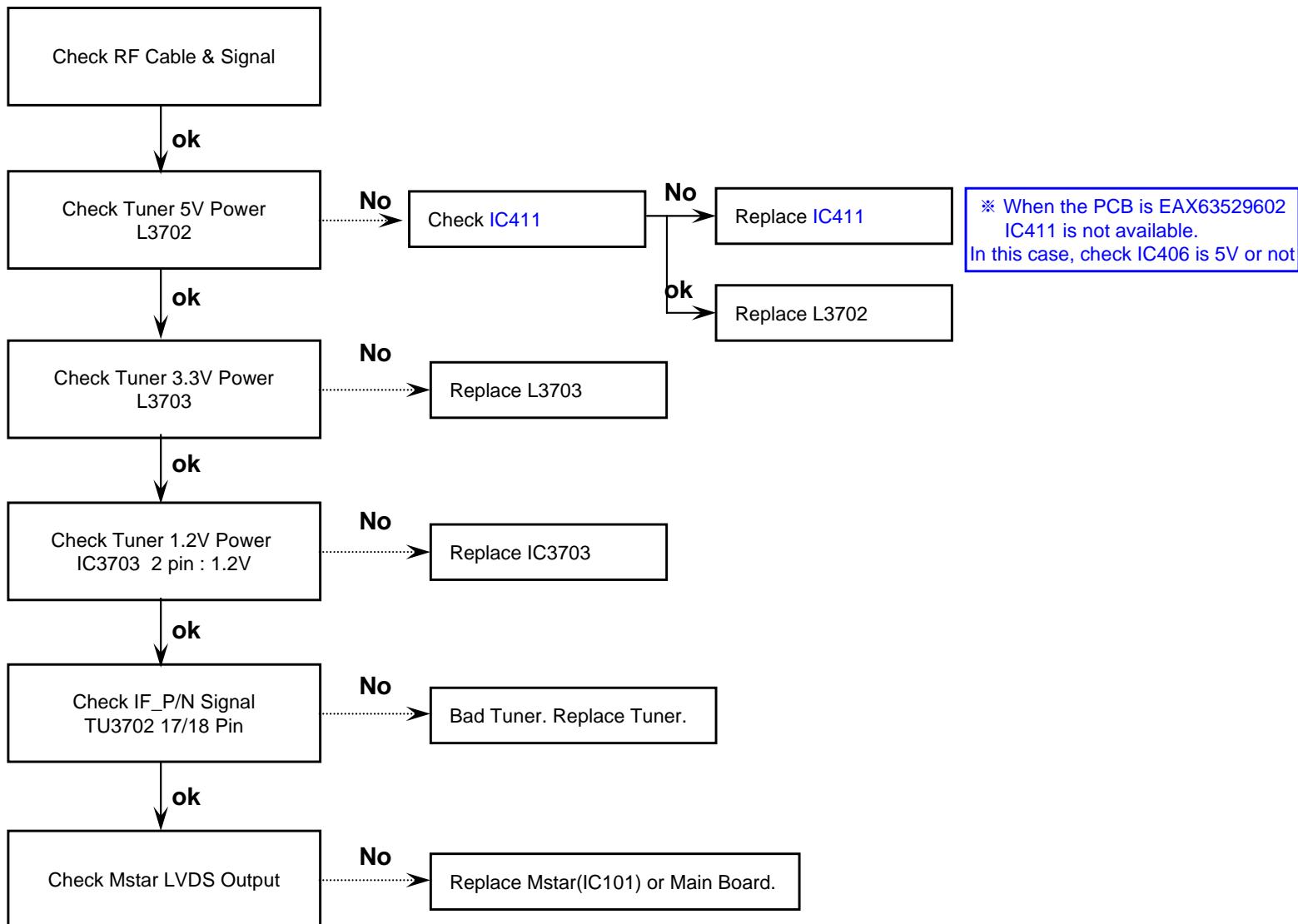
# Trouble shooting guide

## 1. Power-up boot check



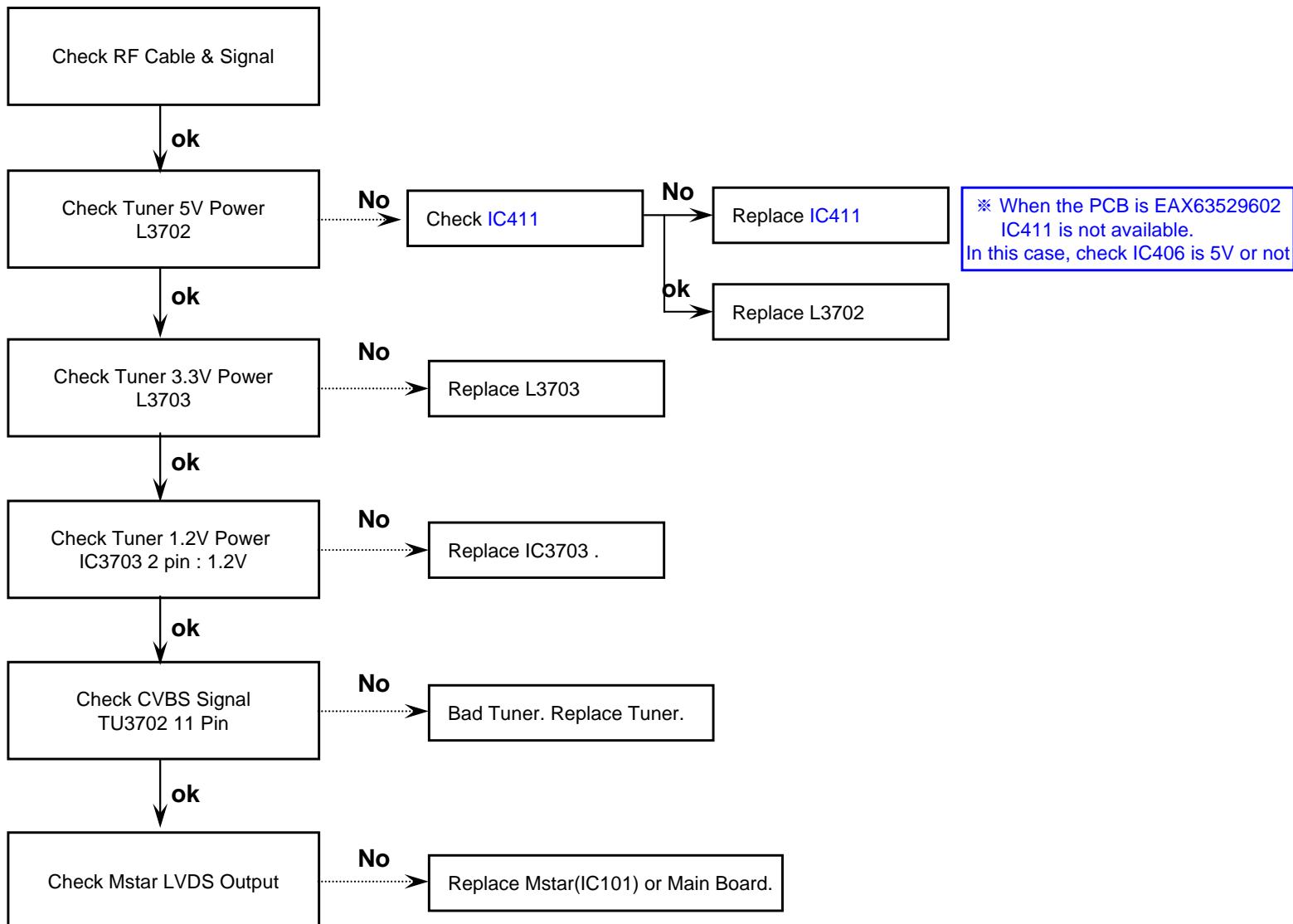
# Trouble shooting guide

## 2. Digital TV Video



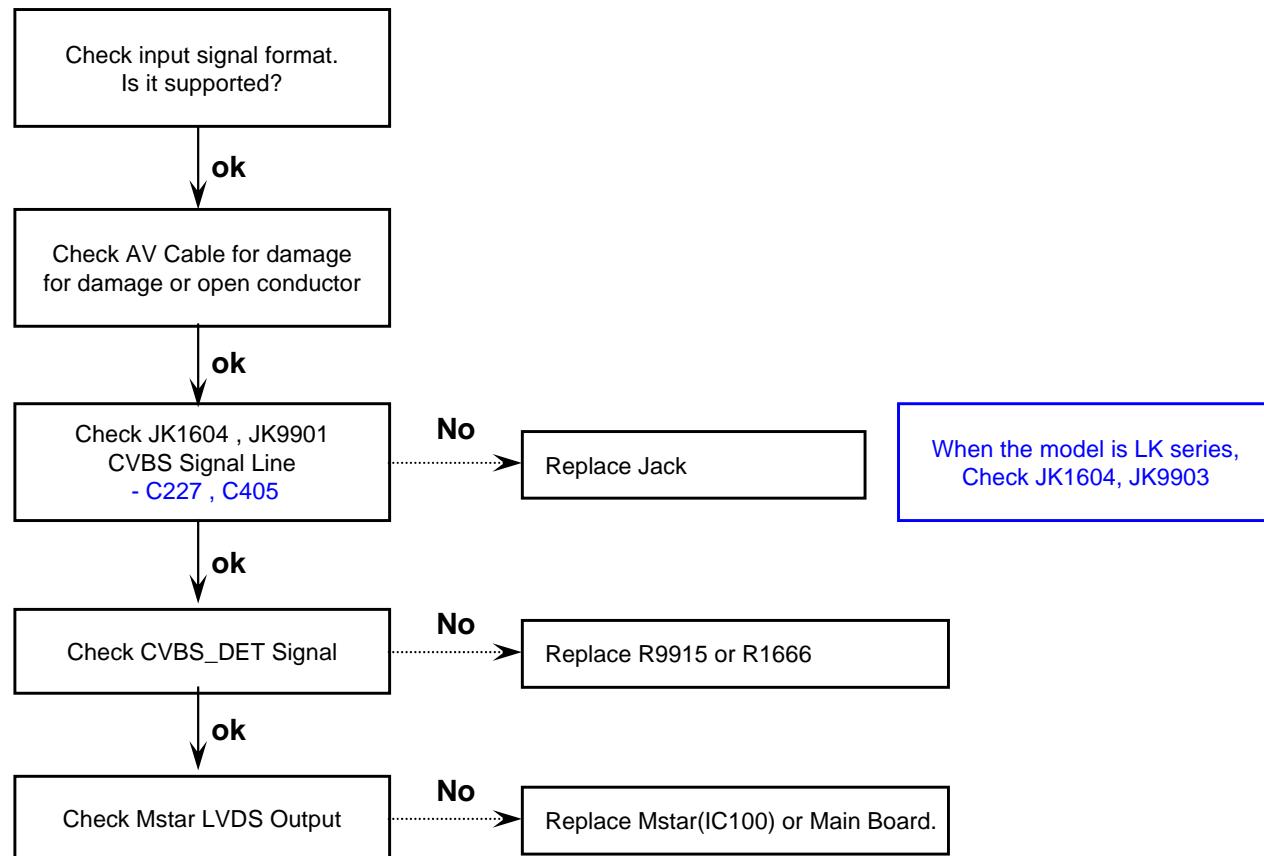
# Trouble shooting guide

## 3. Analog TV Video

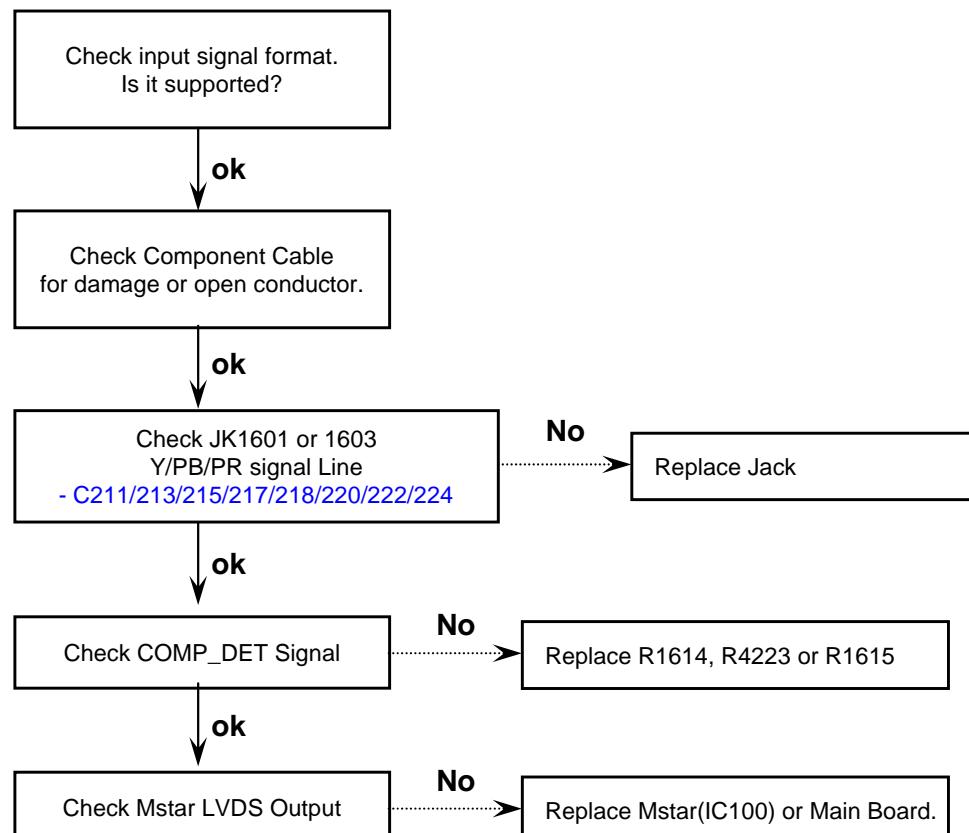


# Trouble shooting guide

## 4. AV Video

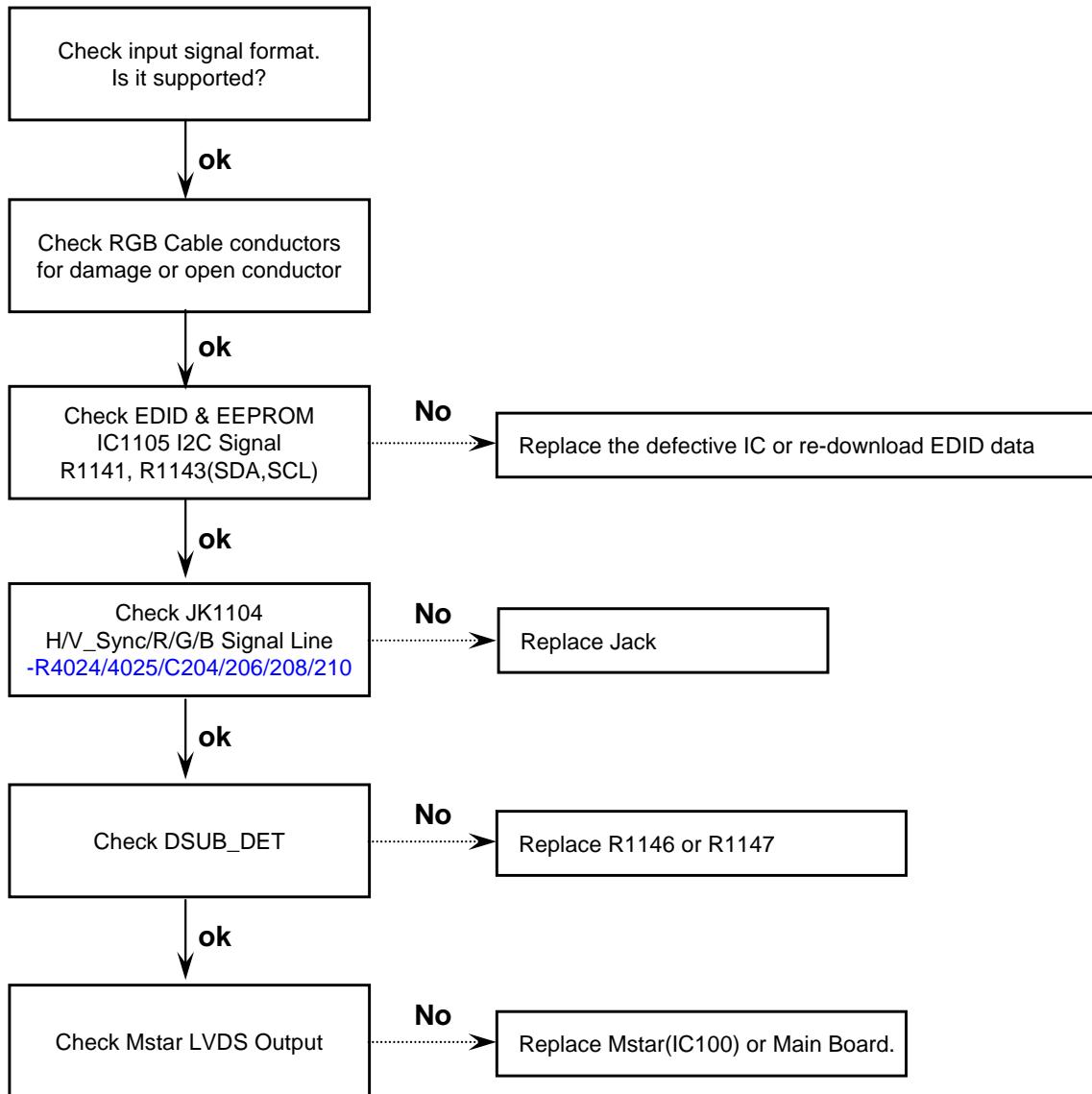


## 5. Component Video



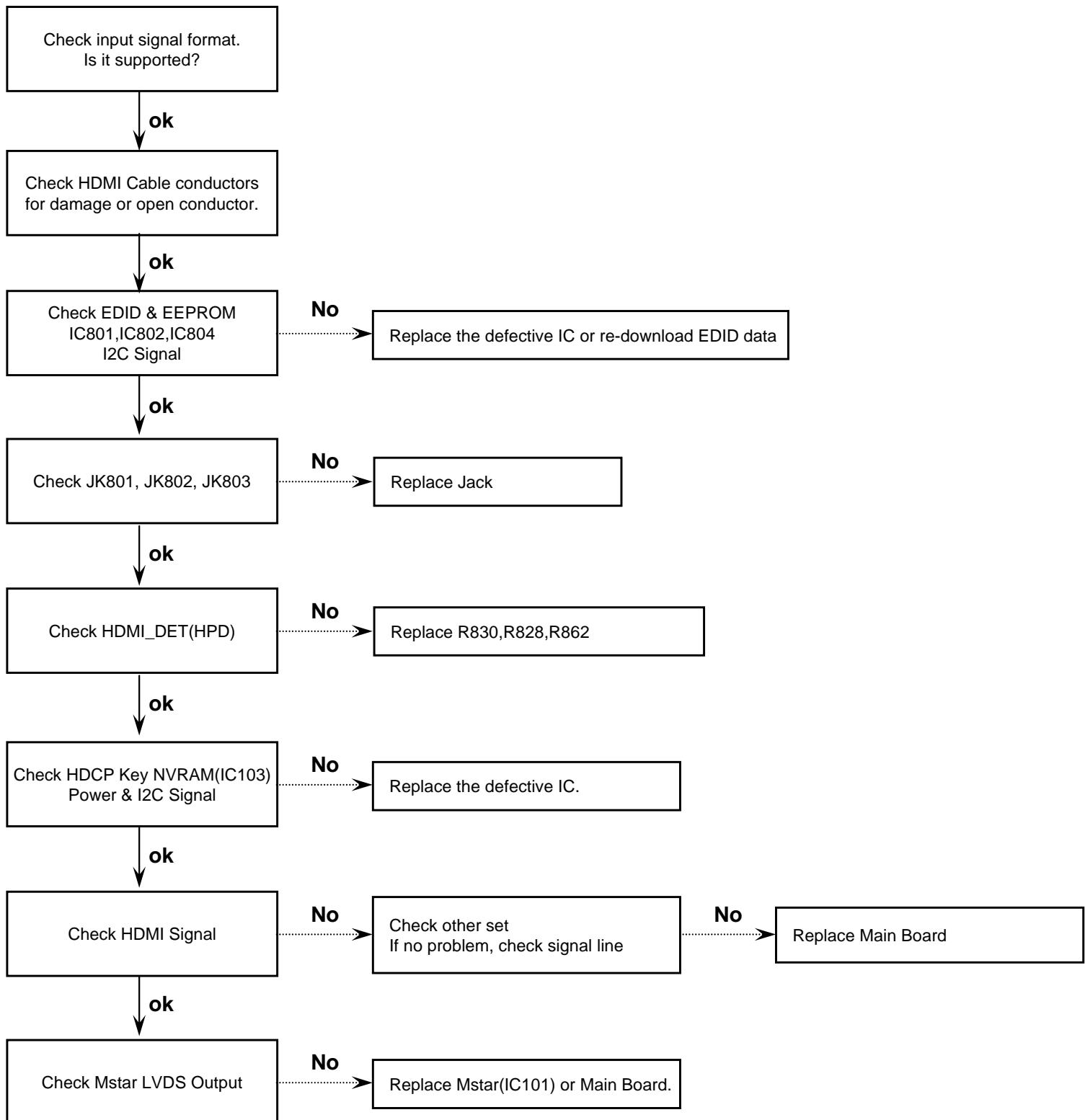
# Trouble shooting guide

## 6. RGB Video



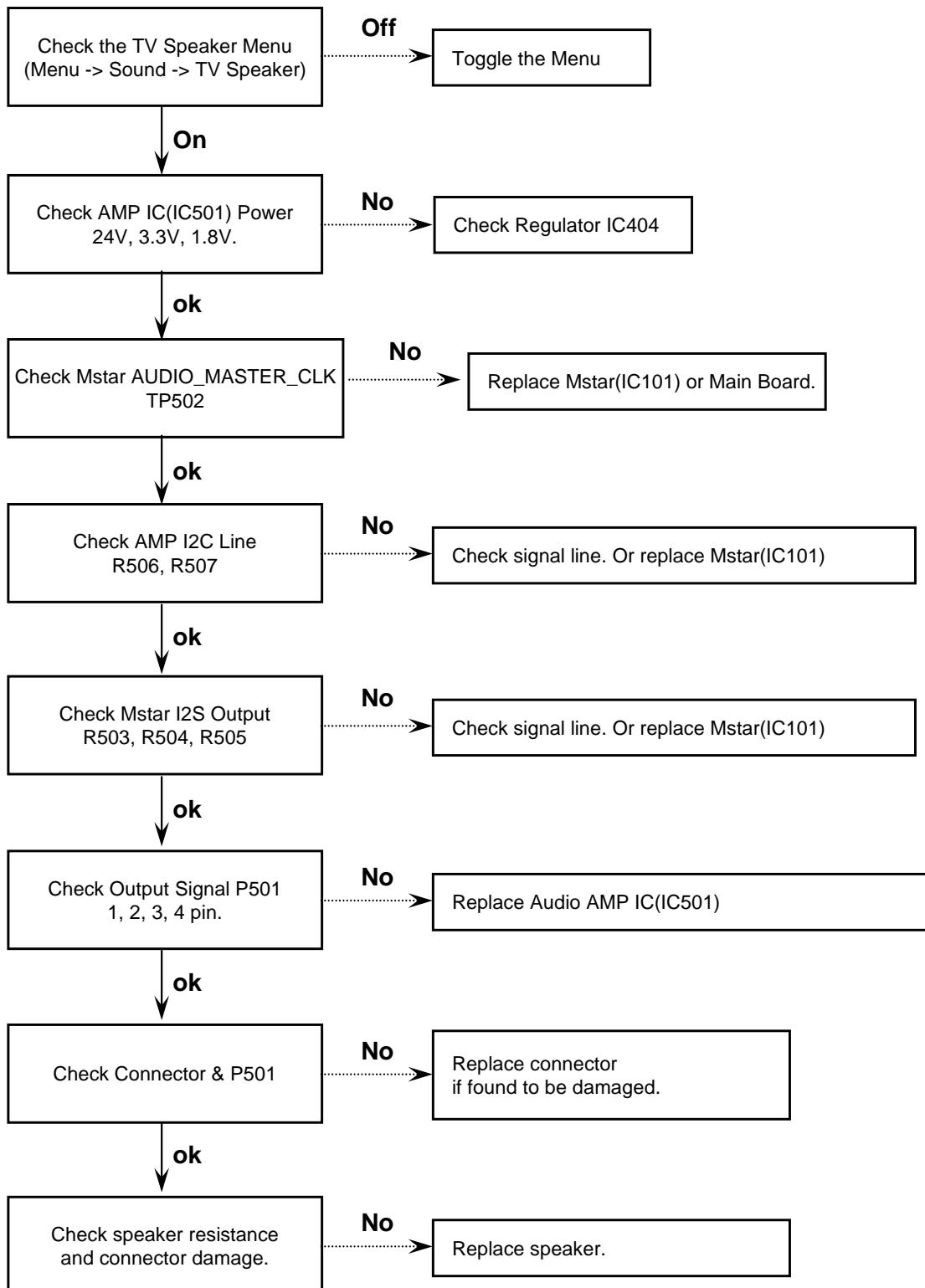
# Trouble shooting guide

## 7. HDMI Video



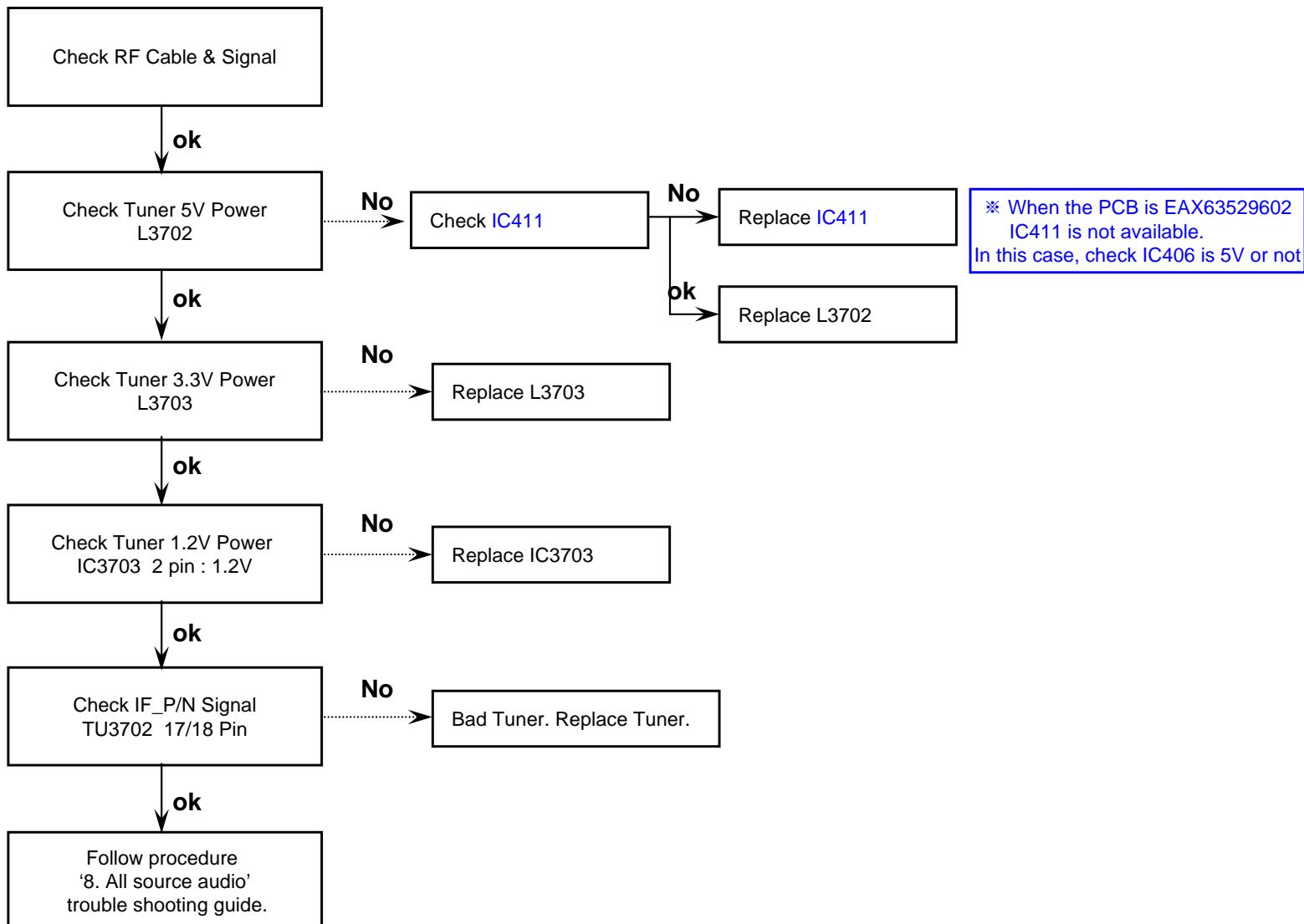
# Trouble shooting guide

## 8. All Source Audio



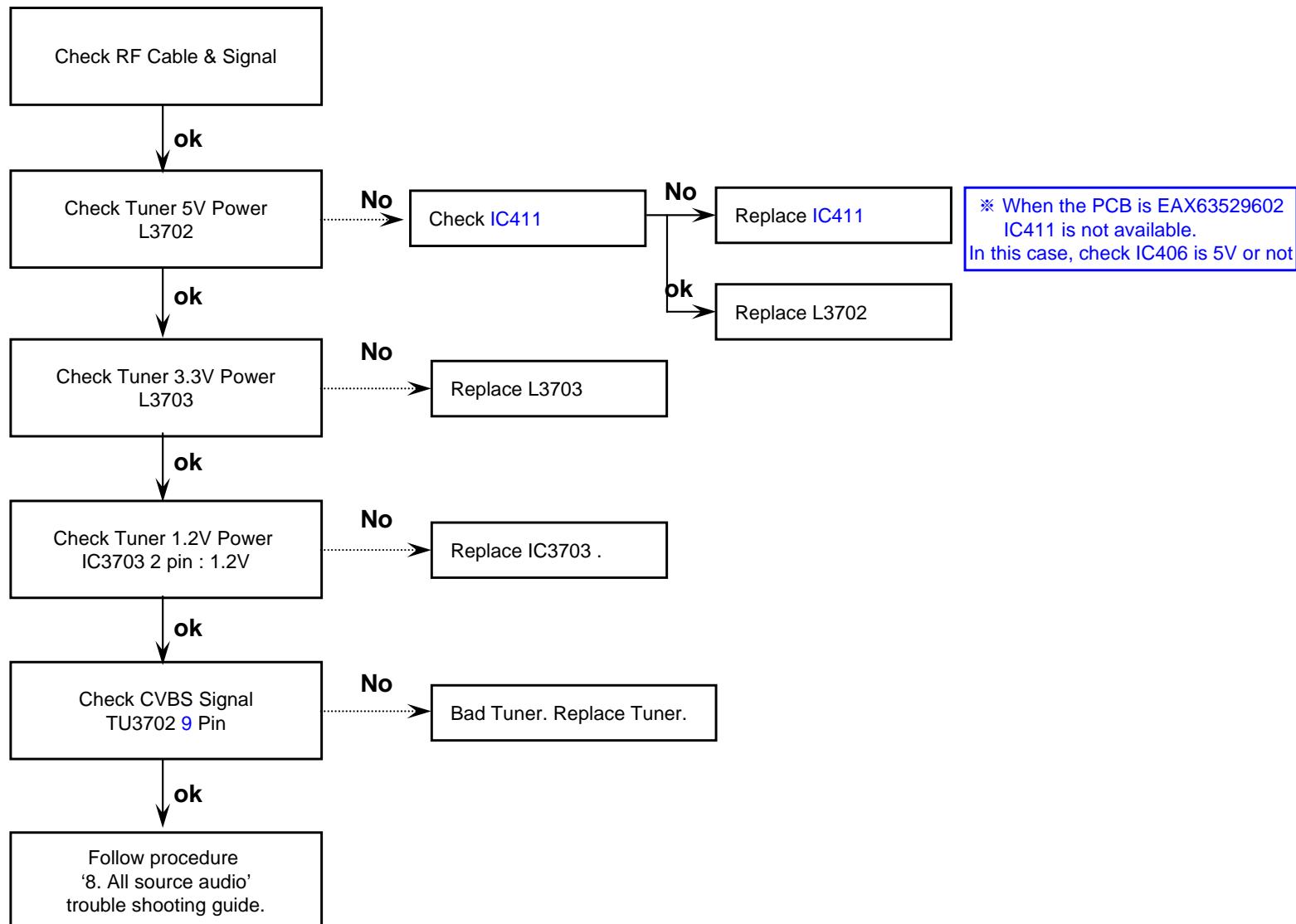
# Trouble shooting guide

## 9. Digital TV Audio



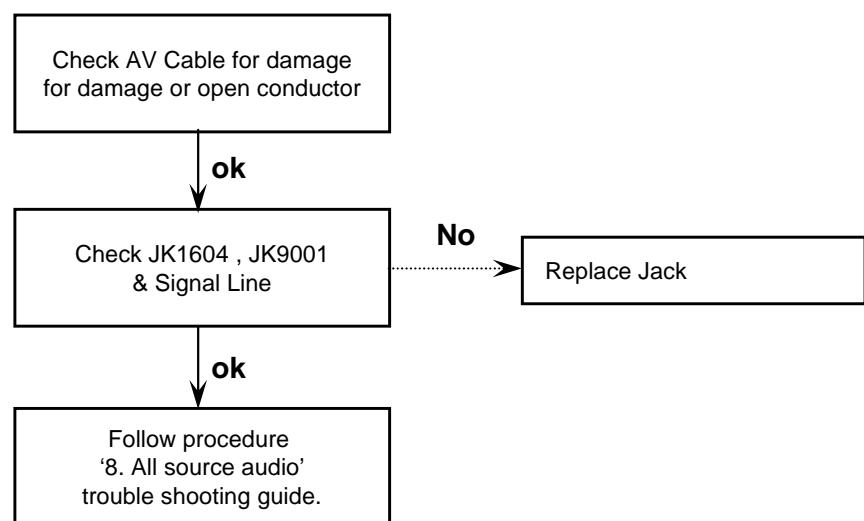
# Trouble shooting guide

## 10. Analog TV Audio

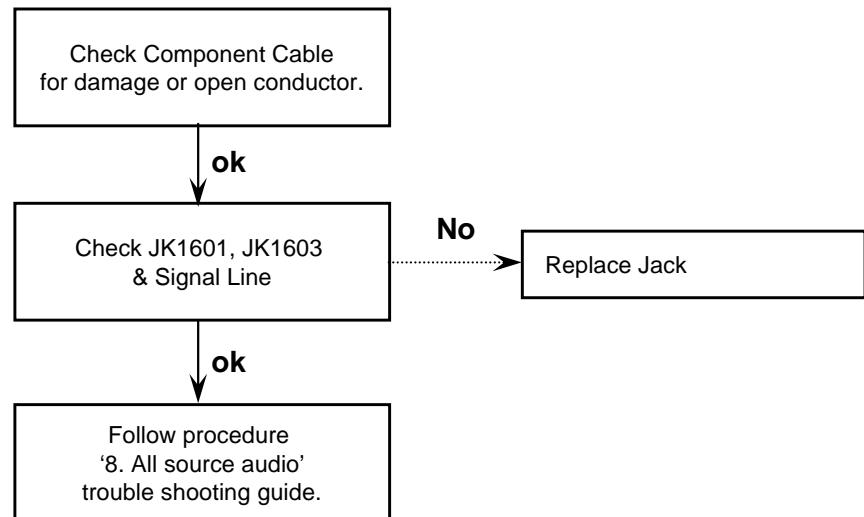


# Trouble shooting guide

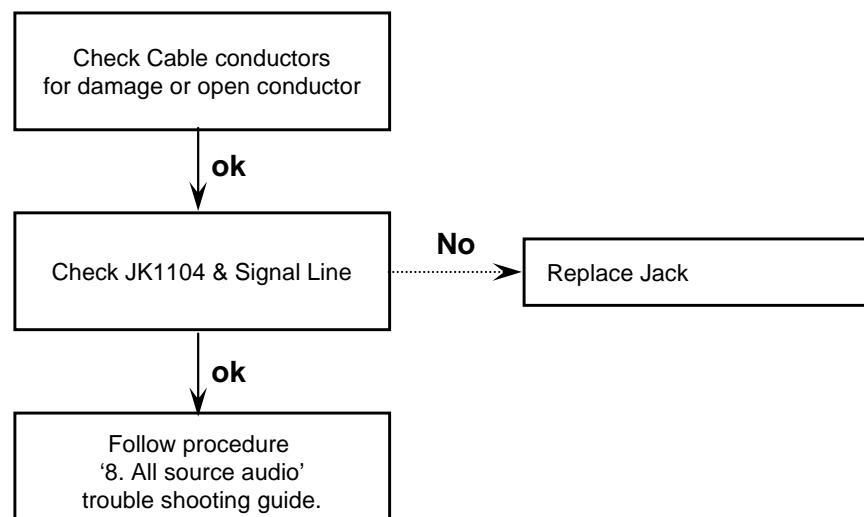
## 11. AV Audio



## 12. Component Audio



## 13. RGB Audio



# Trouble shooting guide

## 14. USB : movie, music, picture

